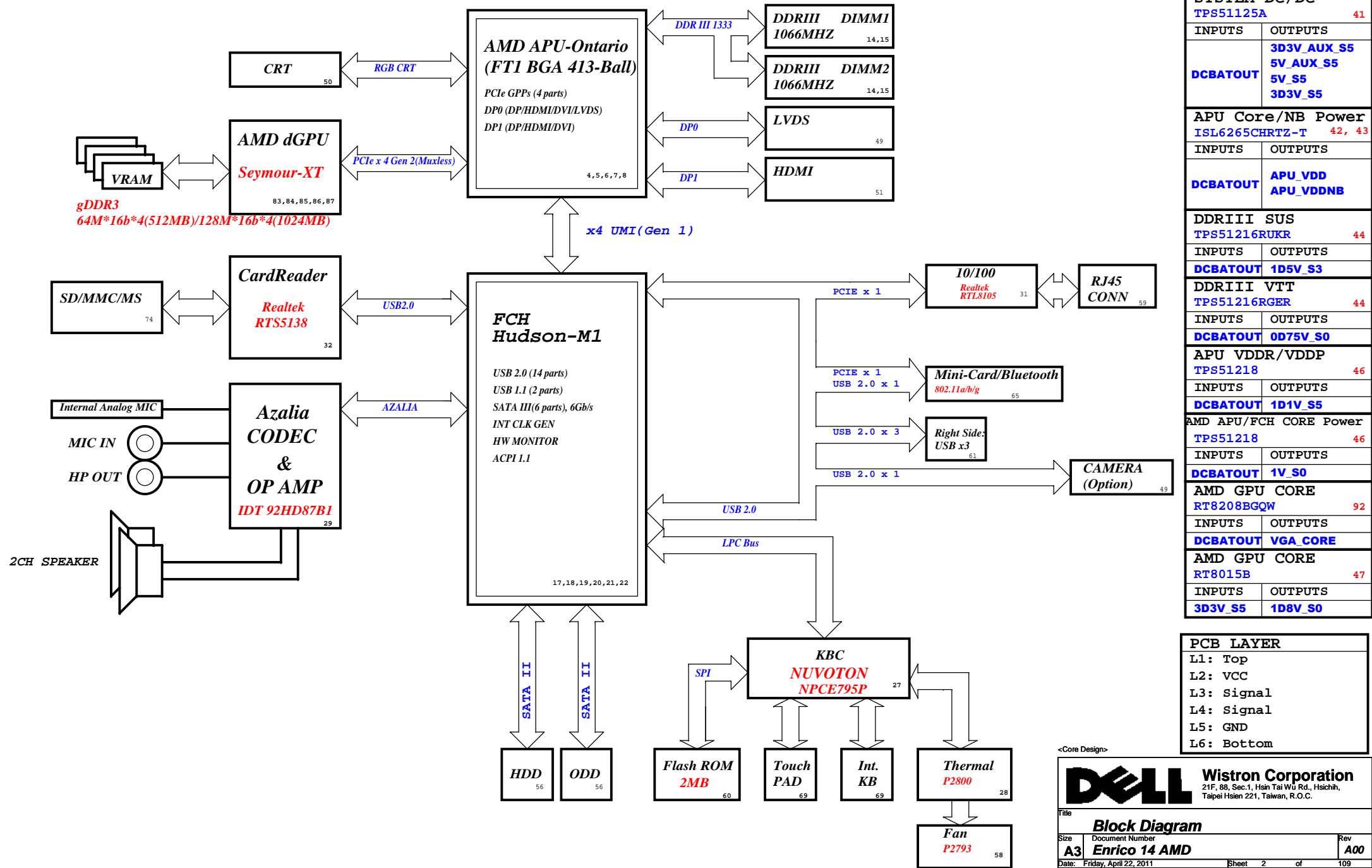


Enrico 14
Muxless Discrete/UMA Schematics Document
AMD Ontario CPU FT1
AMD GPU Seymour XT
FCH HUDSON M1
PCB :10265
2010-04-21
REV : A00

DY :None Installed
UMA:UMA and Muxless platform installed
DIS_PX:DIS and Muxless platform installed
PSL:10mW internal schematic
10mW: 10mW schematic installed
Surge: Surege schematic installed
GIGA: GIGA schematic installed
10/100: 10/100 schematic installed
ROB: ROBOSON GPU installed

AMD Brazos UMA/Discrete Block Diagram

Project code : 91.4IU01.001
 PCB P/N :
 Revision : 10265-1



REQUIRED SYSTEM STRAPS

PULL HIGH	AZ_SDOUT LOW POWER MODE	PCI_CLK1 Allow PCIE GEN2 DEFAULT	CLK_PCI_LPC USE DEBUG STRAPS	PCI_CLK4 non_Fusion CLOCK mode	LPC_CLK0 ENABLE EC	LPC_CLK1 CLKGEN ENABLED (Use Internal) DEFAULT	LPC_CLK2 Enable boot timer function
PULL LOW	PERFORMANCE MODE DEFAULT	Force PCIE GEN1	IGNORE DEBUG STRAPS DEFAULT	Fusion CLOCK mode DEFAULT	DISABLE EC DEFAULT	CLKGEN DISABLED (Use External)	Disable boot fail timer function DEFAULT

TYPE ENABLED	EC_PWM2	EC_PWM3
Reserved	2.2-kohm 5% pull-down	2.2-kohm 5% pull-down
LPC ROM	Not connected.	2.2-kohm 5% pull-down
SPI ROM	2.2-kohm 5% pull-down	Not connected.
Reserved	Not connected.	Not connected.

Note: EC_PWM2, EC_PWM3 default have internal 10kohm PU.


USB Table

Pair	USB Device
0	USB 2.0 EXT.Port1
1	Mini Card1 (WLAN)
2	USB 2.0 EXT.Port1
3	NC
4	NC
5	NC
6	USB 2.0 EXT.Port1
7	CCD Camera
8	NEWCARD
9	Card Reader
10	NC
11	NC
12	NC
13	NC

PCIe Routing

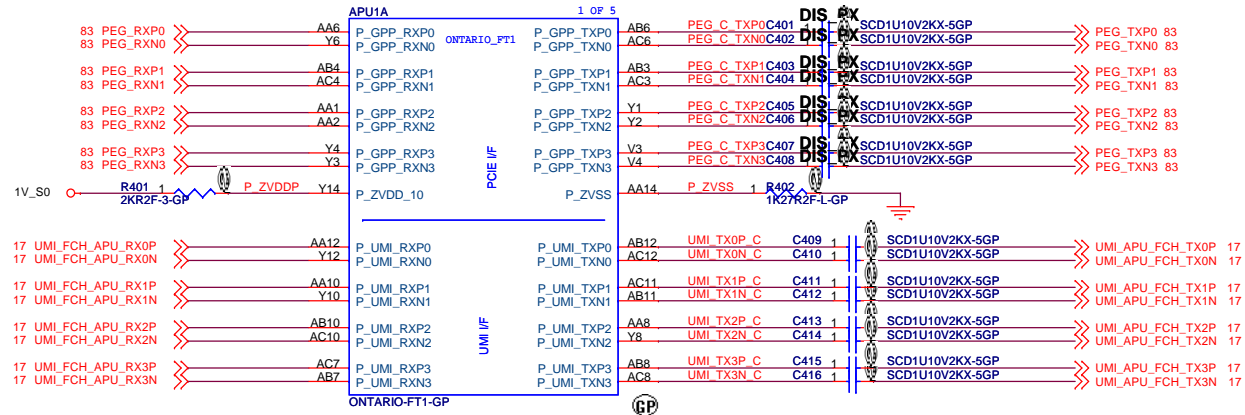
	APU
LANE0	LAN
LANE1	WWAN
LANE2	WLAN
LANE3	CardReader

<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title		<i>Table of Content</i>	
Size A3	Document Number <i>Enrico 14 AMD</i>	Rev <i>A00</i>	
Date: Friday, April 22, 2011	Sheet 3	of	109

SSID = CPU

www.chinafix.com.cn

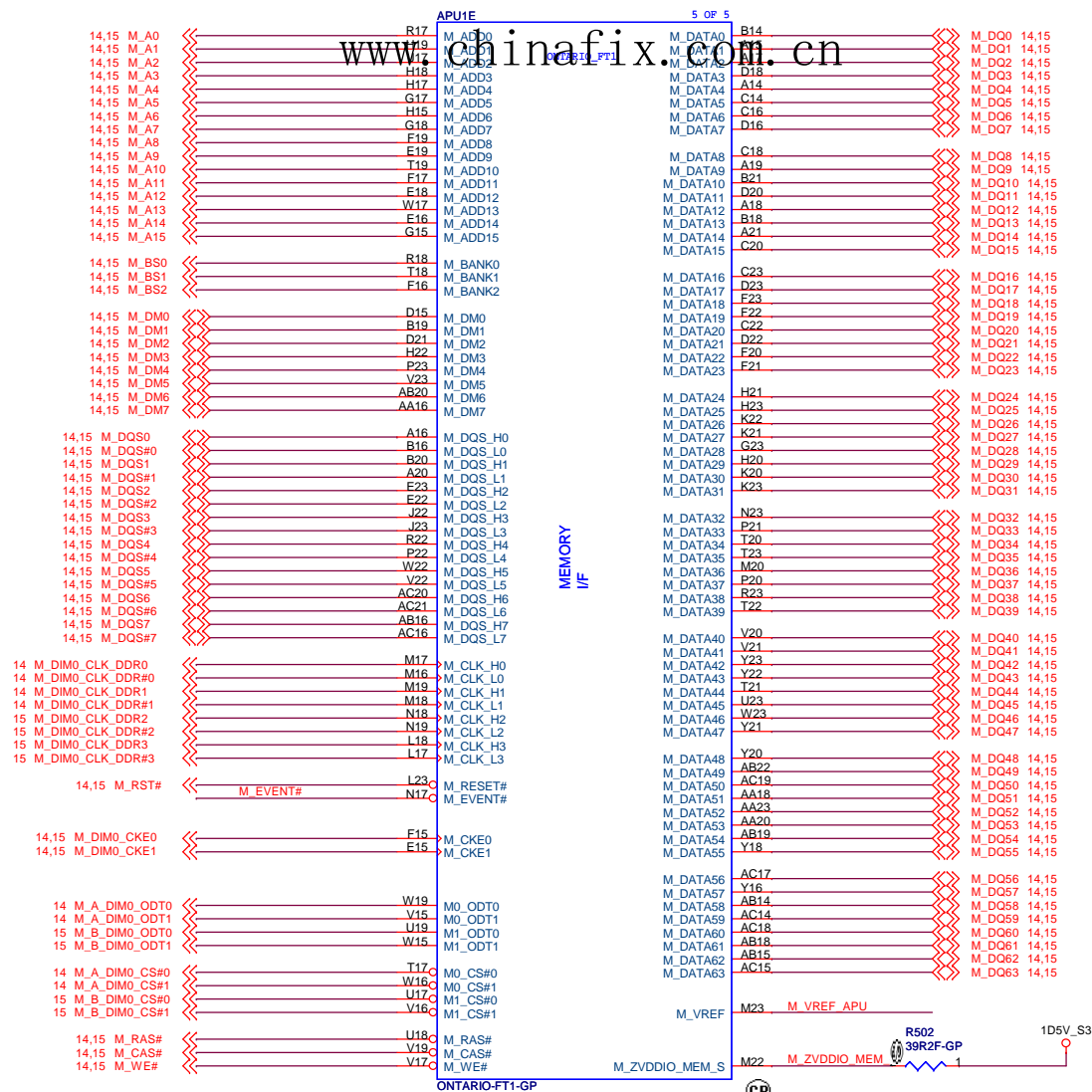


<Core Design>

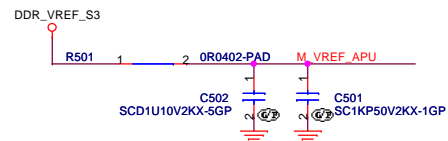
DELL		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
APU PCIE(1/5)			
Size	Document Number		Rev
A3	Enrico 14 AMD		A00
Date: Friday, April 22, 2011		Sheet 4 of	109

SSID = CPU

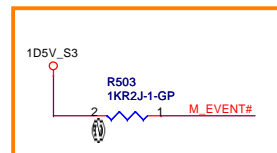
www.chinafix.com.cn



APU_VREF



LAYOUT: place them close to APU



AMD Confirm: PU Needed even if not used

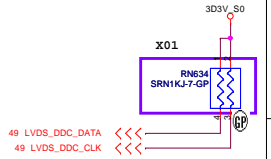
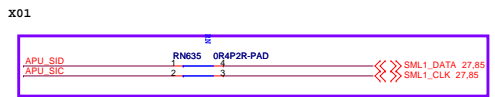
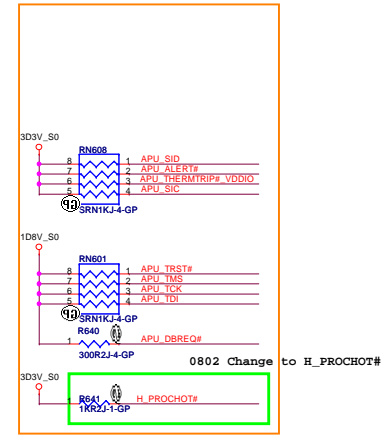
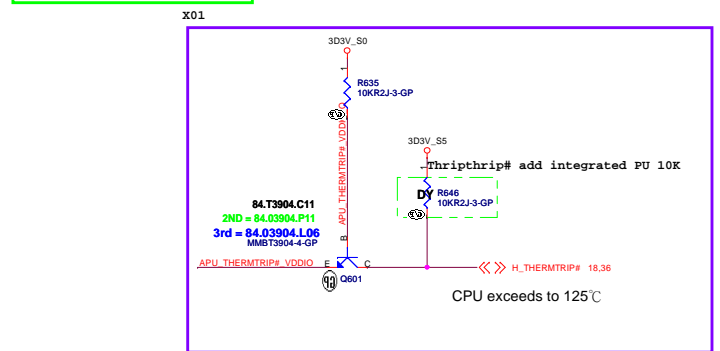
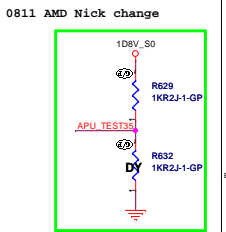
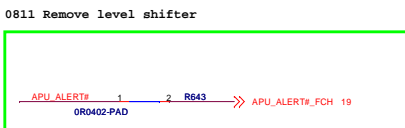
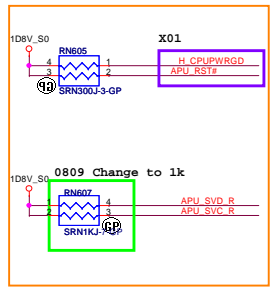
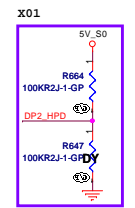
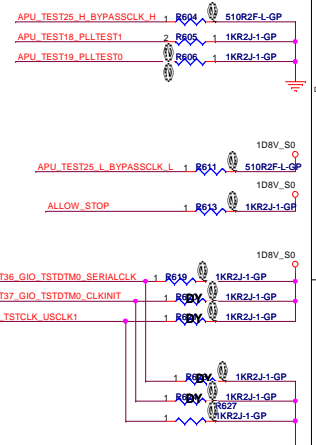
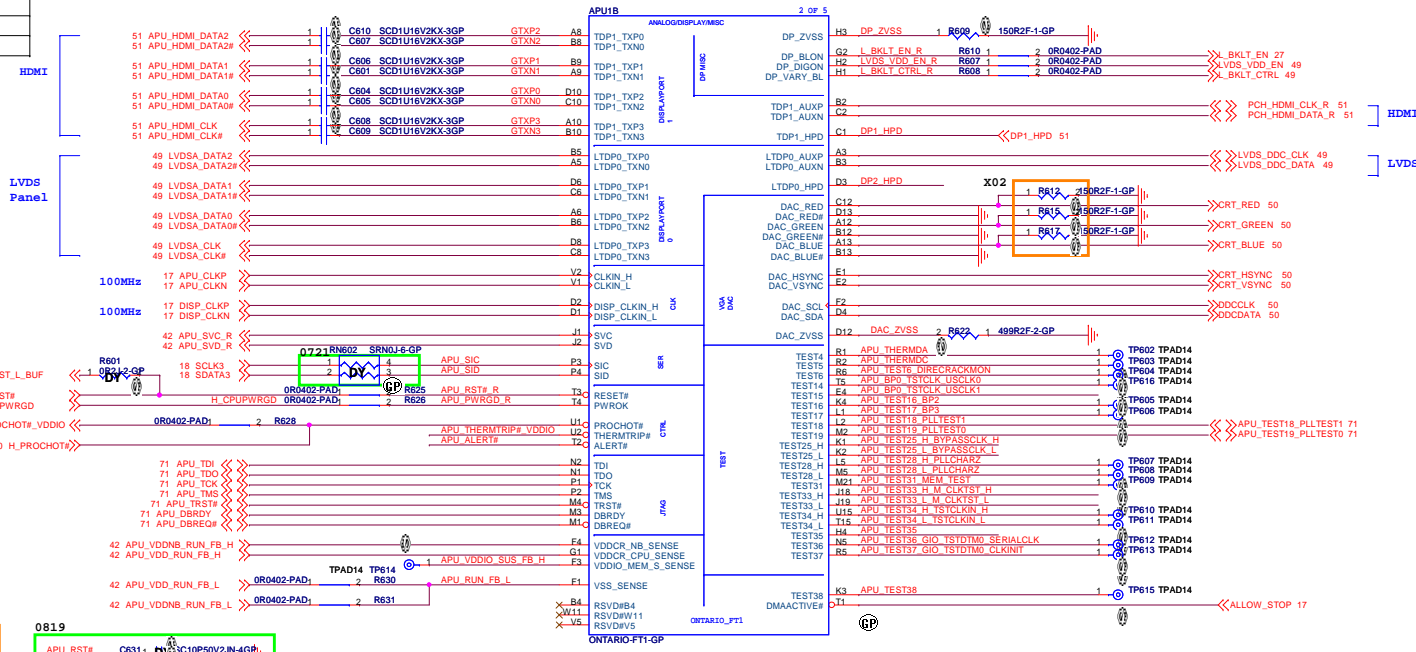
SSID = CPU

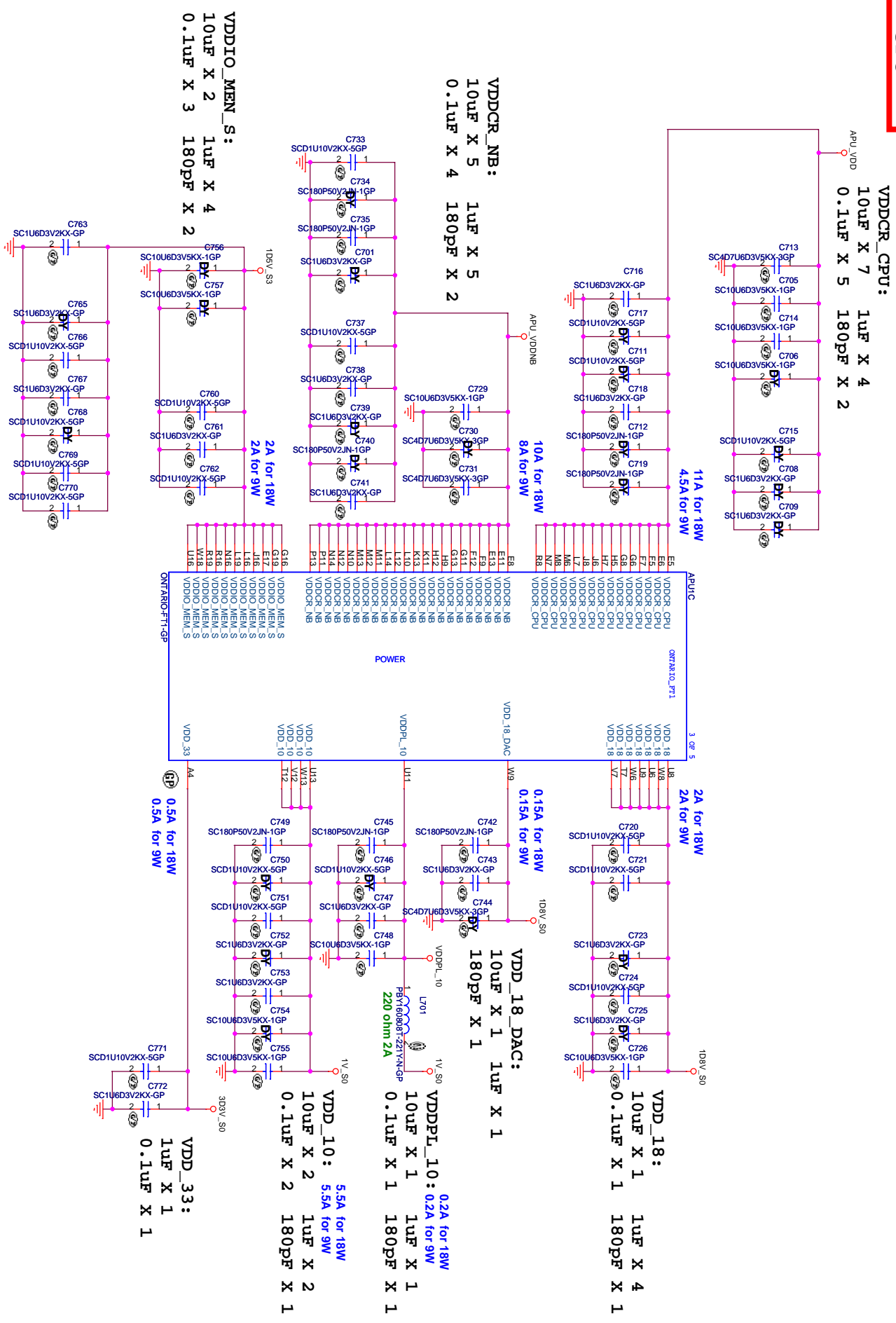
SVC	SVD	Boot Voltage (VCC/GND)	Boot Voltage (open)
0	0	1.1	1.1
0	1	1.0	1.2
1	0	0.9	1.1
1	1	0.8	0.9

www.chinafix.com

```
Brazos:      Sabine:
DP0  --> HDMI  DP0  --> LVDS
DP1  --> CRT   DP1  --> CRT
DP2  --> HDMI  DP2  --> HDMI
```

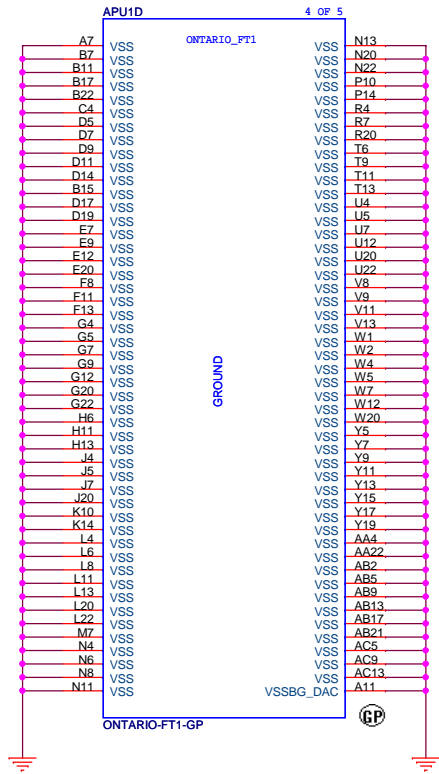
APU_TEST33 H M CLKST H SCD1U10V2KX-5GP C602 R602 51R2F-2-GP





SSID = CPU

www.chinafix.com.cn




<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title APU_VSS(5/5)			
Size A3	Document Number Enrico 14 AMD		Rev A00
Date: Friday, April 22, 2011		Sheet 8 of 109	

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

TRAVIS

Size

A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 9 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 10 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

Rev

A00


Date: Friday, April 22, 2011

Sheet 11 of 109

(Blanking)

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

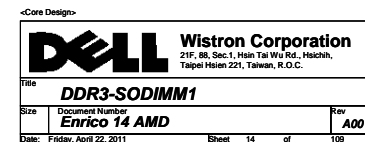
Rev

A00

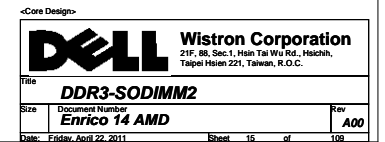
Date: Friday, April 22, 2011

Sheet 13 of 109

www.chinafix.com.cn



www.chinafix.com.cn



<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

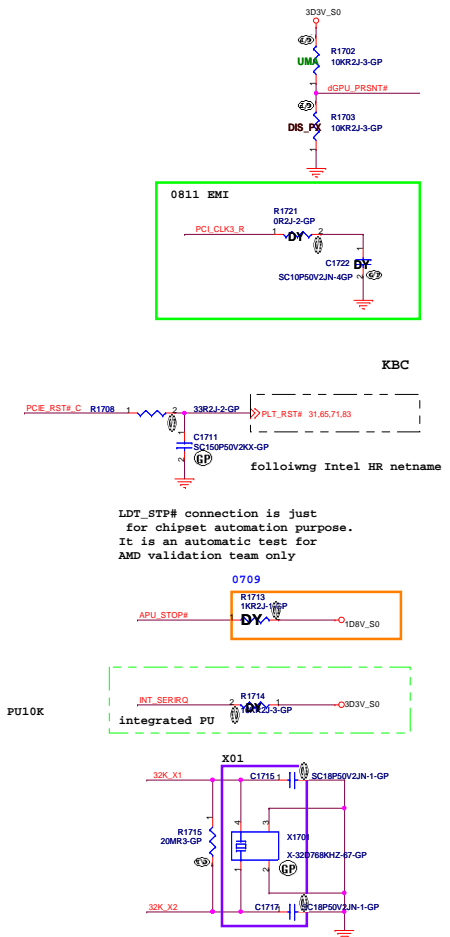
Size
A3

Document Number
Enrico 14 AMD

Date: Friday, April 22, 2011

Rev
A00

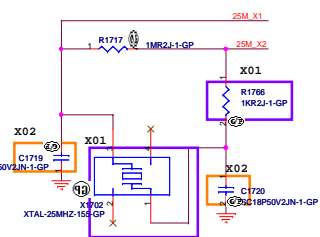
Sheet 16 of 109



```
if LAN support Wake on S5,
do not use clock from FCH,
have use X'tal
```

Use 48Mhz CLK For 5138

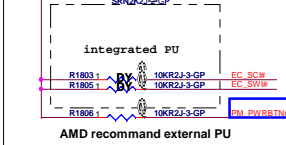
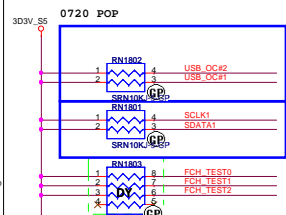
connection to devices that will use this clock as a PLL input. The 14-MHz output is intended for use as an auxiliary clock only. The 24-MHz, 25-MHz, 48-MHz, and 50-MHz clock outputs can be used as PLL inputs. Clock output is not available in S3/S5 state; device that need clock in S3/S5 state shouldn't be connected to this clock output. Leave unconnected if not used.



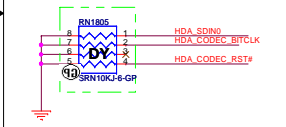
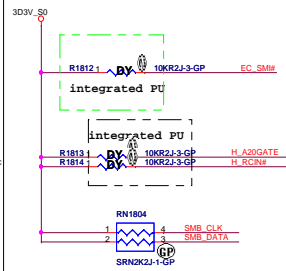
SSID = FCH

Integrated PU is not supported when the pin is configured for USB over current function.

0720: Change From 2.2K and POP

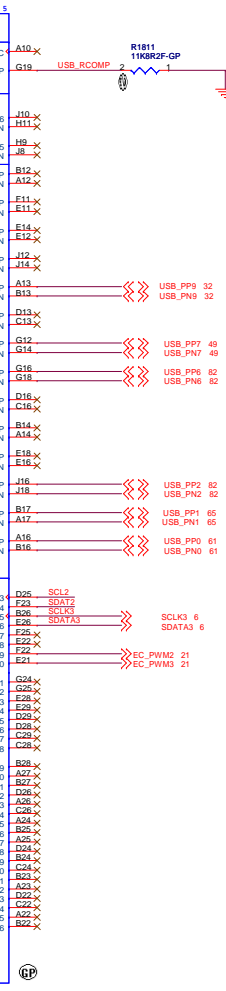
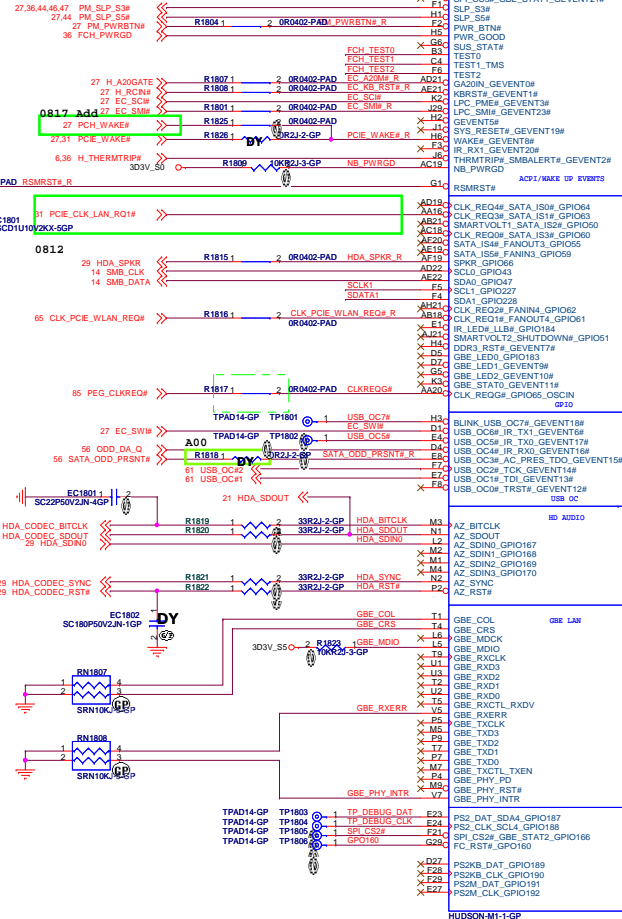


AMD recommend external PU

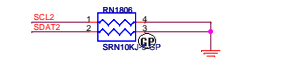


Rename 0712

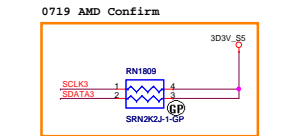
Confirm with SW, RSMRST# from KBC is push-pull. It can be driven high by SW.

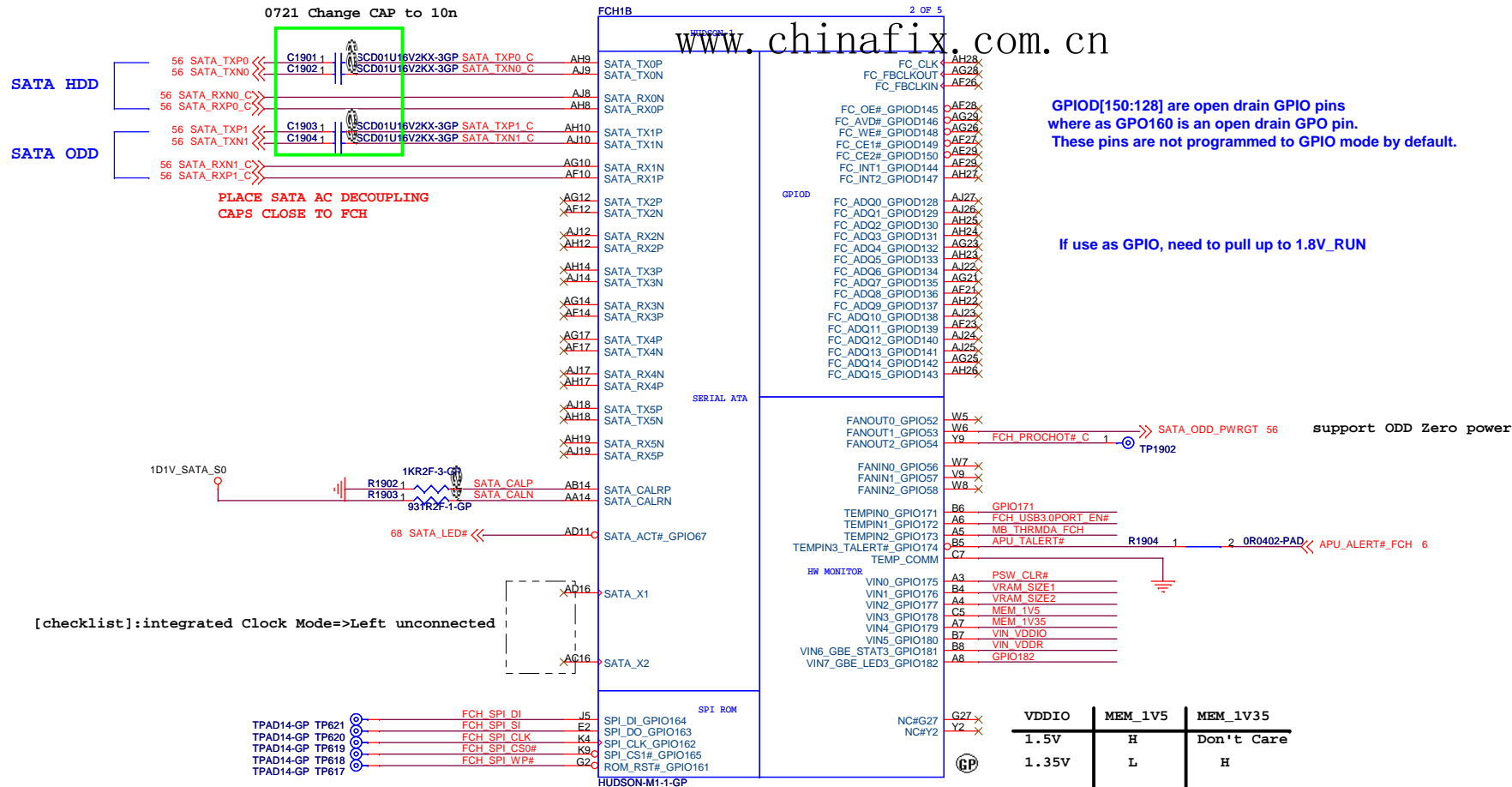


Pair	USB Device
0	USB 2.0 EXT.Port1
1	Mini Card1 (WLAN)
2	USB 2.0 EXT.Port1
3	NC
4	NC
5	NC
6	USB 2.0 EXT.Port1
7	CCD Camera
8	NEWCARD
9	Card Reader
10	NC
11	NC
12	NC
13	NC



if not used SMBUS or GPIO, PD 10K

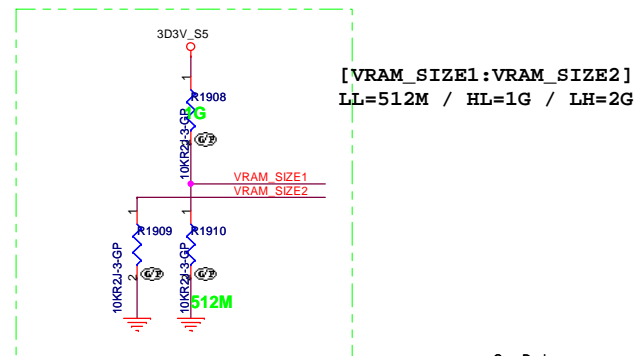
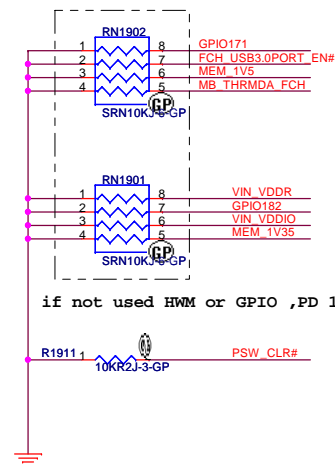




XTAL

1'nd 82.30020.851

2'nd 82.30020.791



<Core Design>

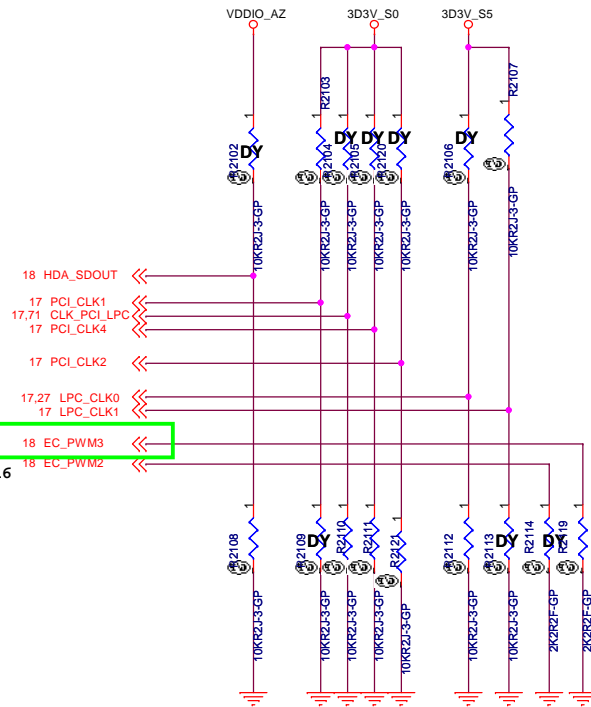
www.chinafix.com.cn



SSID = FCH

www.chinafix.com.cn

REQUIRED STRAPS



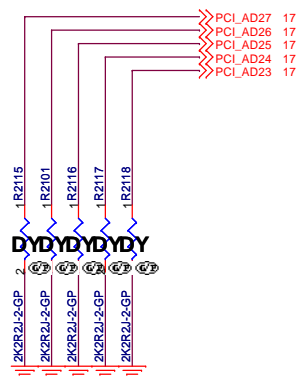
REQUIRED SYSTEM STRAPS

	AZ_SDOUT	PCI_CLK1	CLK_PCI_LPC	PCI_CLK4	LPC_CLK0	LPC_CLK1	LPC_CLK2
PULL HIGH	LOW POWER MODE	Allow PCIE GEN2 DEFAULT	USE DEBUG STRAPS	non_Fusion CLOCK mode	ENABLE EC	CLKGEN ENABLED (Use Internal) DEFAULT	Enable boot timer function
PULL LOW	PERFORMANCE MODE DEFAULT	Force PCIE GEN1	IGNORE DEBUG STRAPS DEFAULT	Fusion CLOCK mode DEFAULT	DISABLE EC DEFAULT	CLKGEN DISABLED (Use External)	Disable boot fail timer function DEFAULT

TYPE ENABLED	EC_PWM2	EC_PWM3
Reserved	2.2-kohm 5% pull-down	2.2-kohm 5% pull-down
LPC ROM	Not connected.	2.2-kohm 5% pull-down
SPI ROM	2.2-kohm 5% pull-down	Not connected.
Reserved	Not connected.	Not connected.

Note: EC_PWM2, EC_PWM3 default have internal 10kohm PU.

DEBUG STRAPS



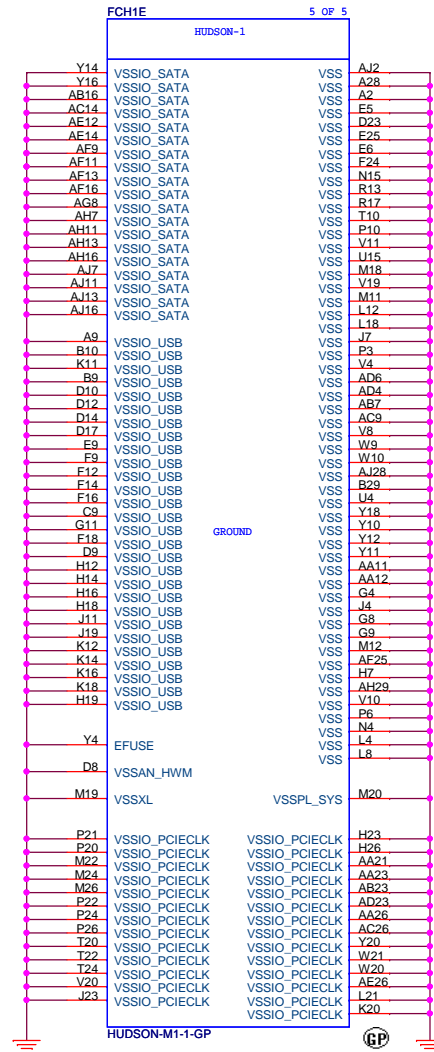
	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL (DEFAULT)	Disable ILA AUTORUN (DEFAULT)	USE FC PLL (DEFAULT)	USE DEFAULT PCIE STRAPS (DEFAULT)	Disable PCI MEM BOOT (DEFAULT)
PULL LOW	BYPASS PCI PLL	Enable ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	Enable PCI MEM BOOT

Note: FCH has 15K internal PU FOR PCI_AD[27:23]

<Core Design>

SSID = FCH

www.chinafix.com.cn



<Core Design>


		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title Reserved			
Size A3	Document Number Enrico 14 AMD		Rev A00
Date: Friday, April 22, 2011		Sheet 22 of	109

A

Date: Friday, April 22, 2011	Sheet 23 of 109
------------------------------	-----------------

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Size
A3

Document Number
Reserved

Rev
A00


Date: Friday, April 22, 2011

Sheet 24 of 109

(Blanking)

(Blanking)

<Core Design>



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

Rev

A00

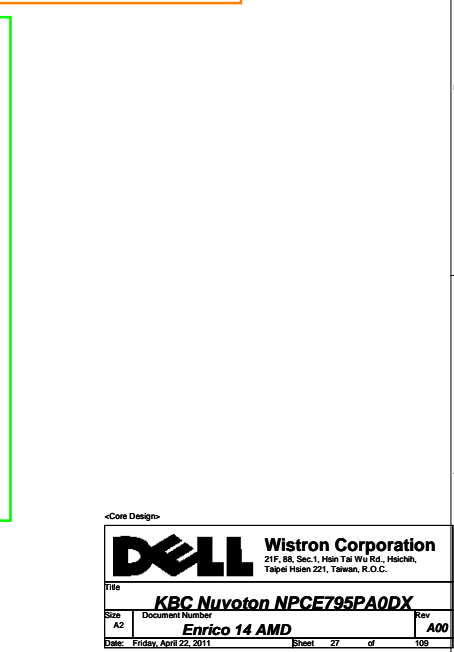
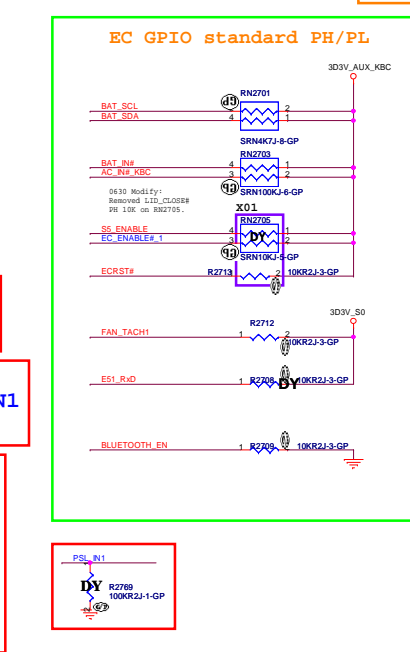
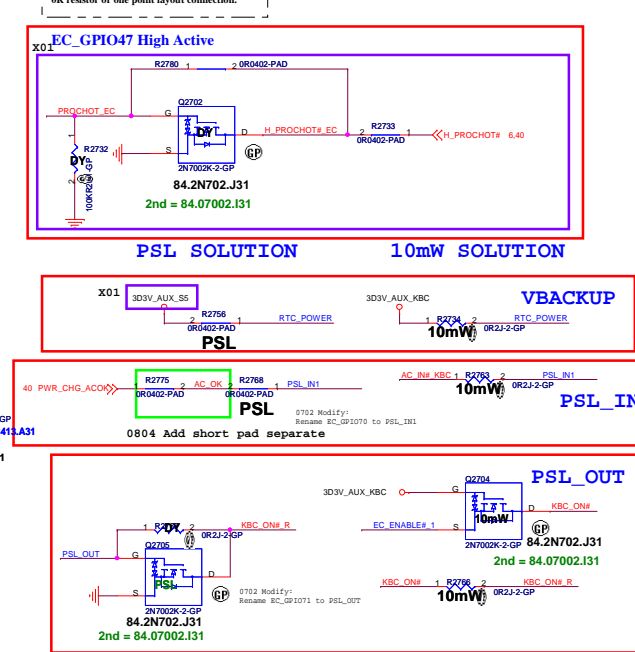
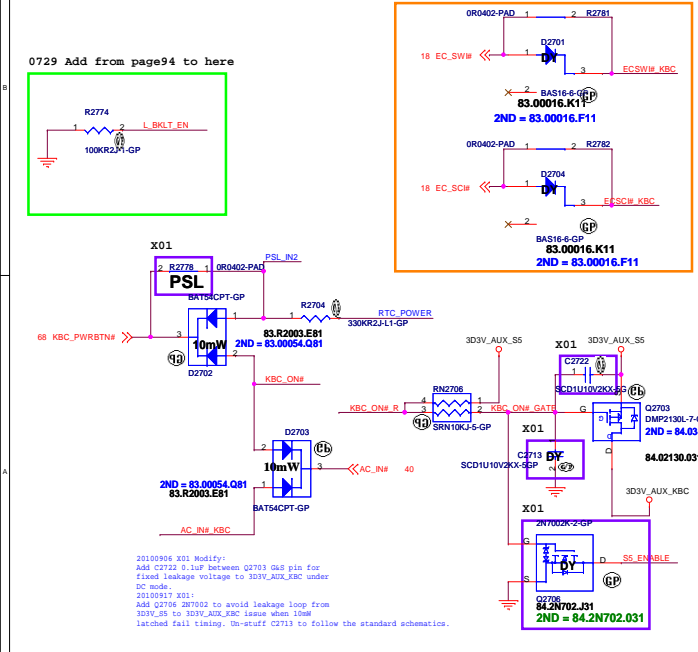
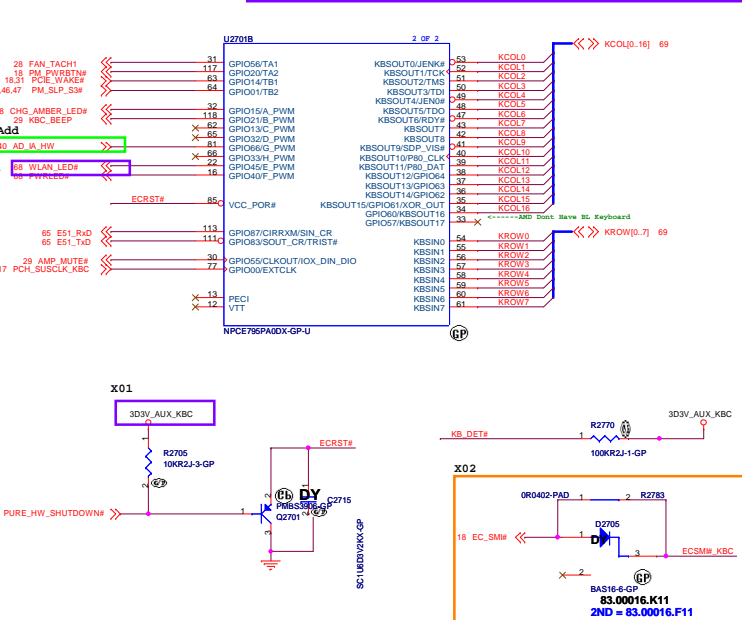
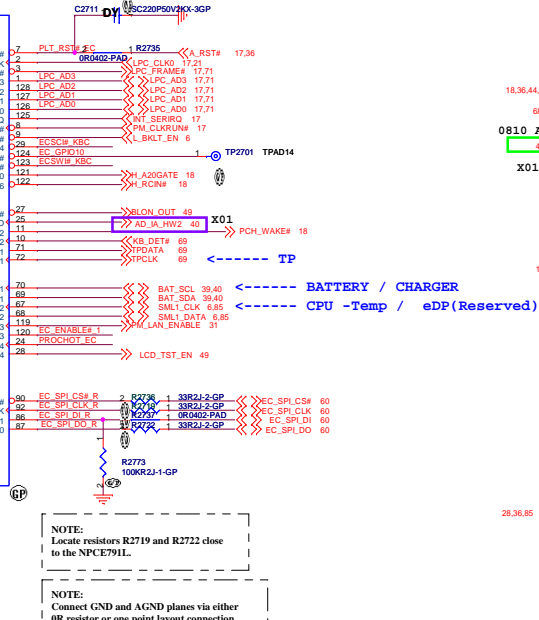
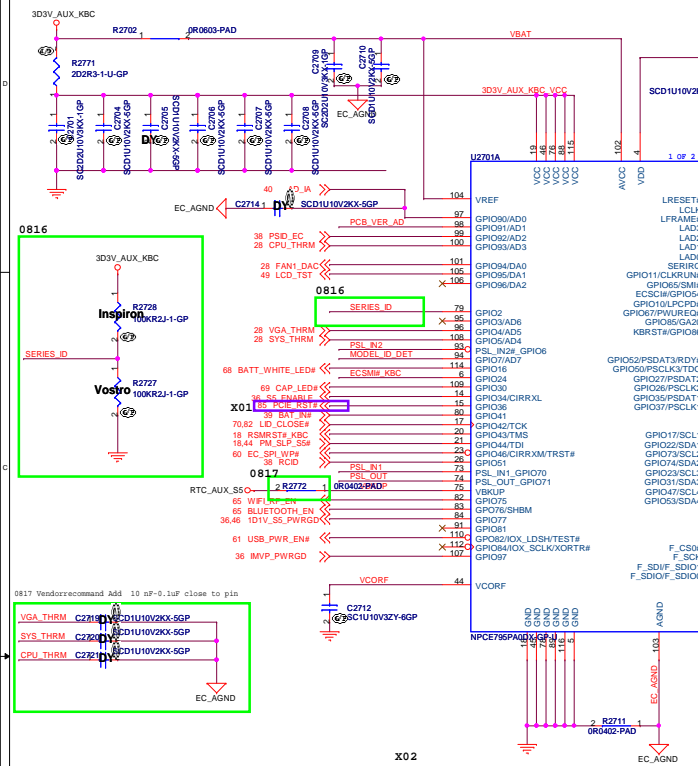
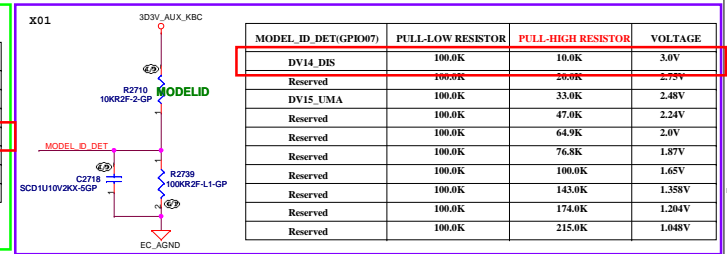
Date: Friday, April 22, 2011

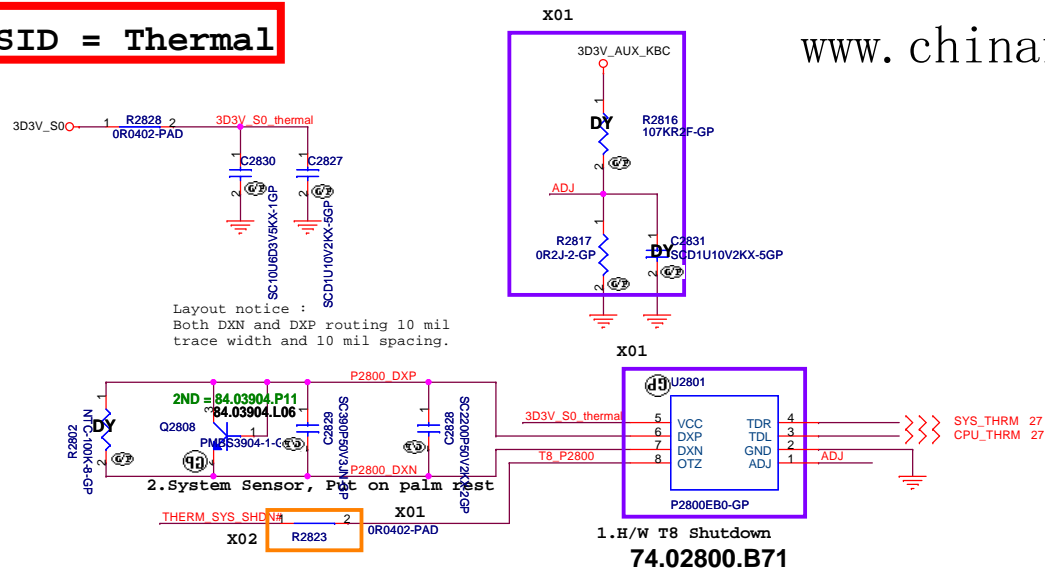
Sheet 26 of 109

SSID = KBC

www.chinafix.com.cn

PC VERSION (MPC11N8)	PC LOW RESISTOR	PC HIGH RESISTOR	VOLTAGE
SA	100.0K	10.0K	3.0V
SB	20.0K	20.0K	2.75V
SC	100.0K	33.0K	2.48V
A00	100.0K	47.0K	2.24V
Reserved	100.0K	64.7K	2.0V
Reserved	100.0K	76.8	1.87V
Reserved	100.0K	100.0K	1.65V

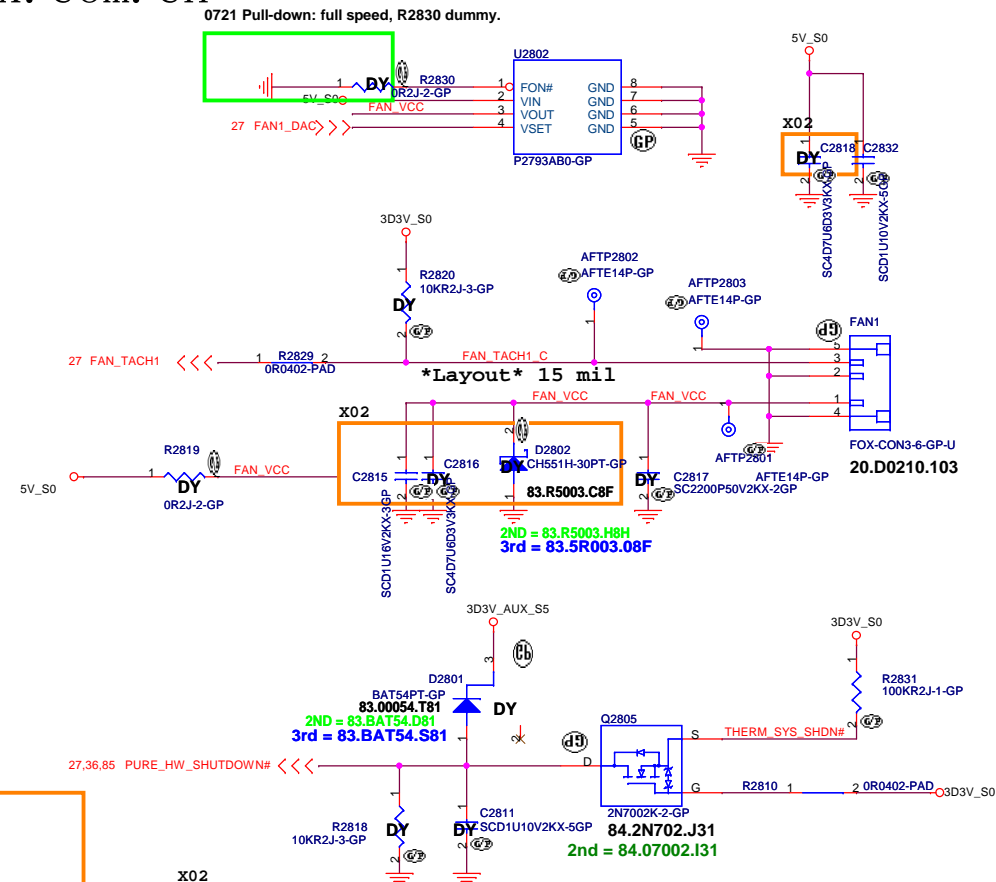




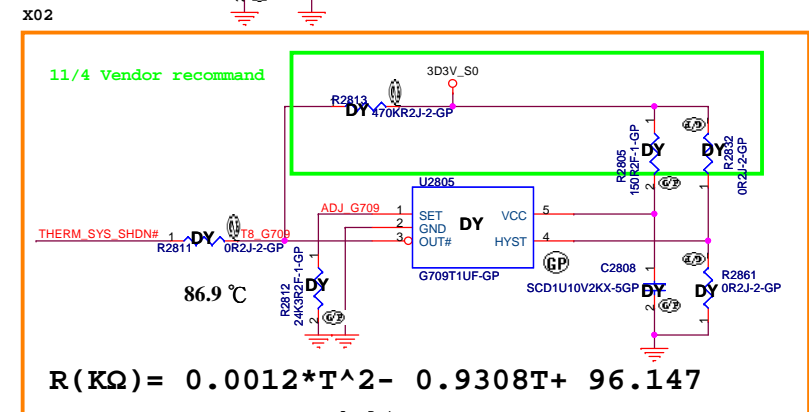
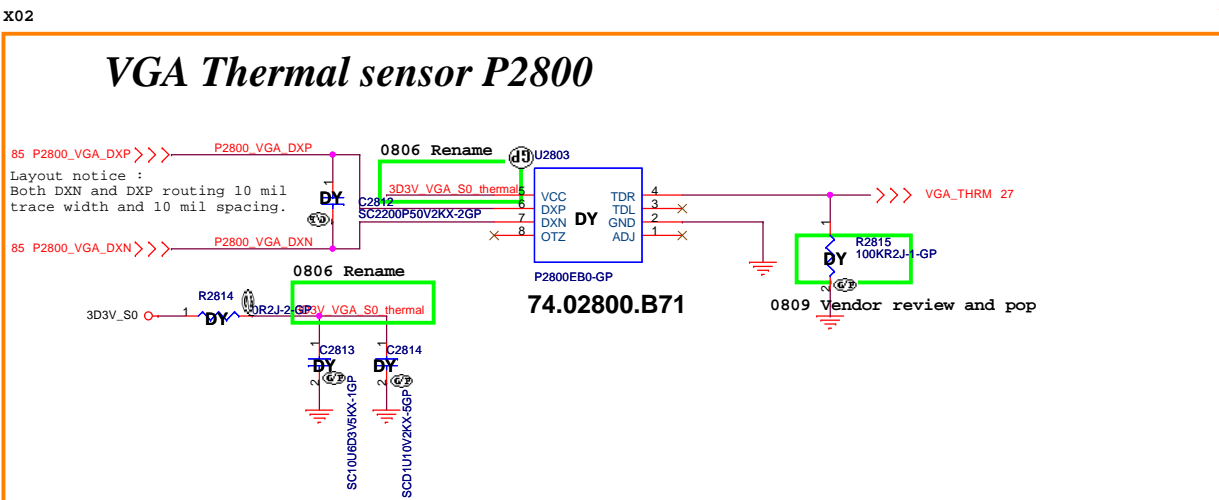
ADJ floating : OTZ shutdown temperature=85℃

ADJ pull-down : OTZ shutdown temperature=90℃

ADJ pull-up : OTZ shutdown temperature=95°C



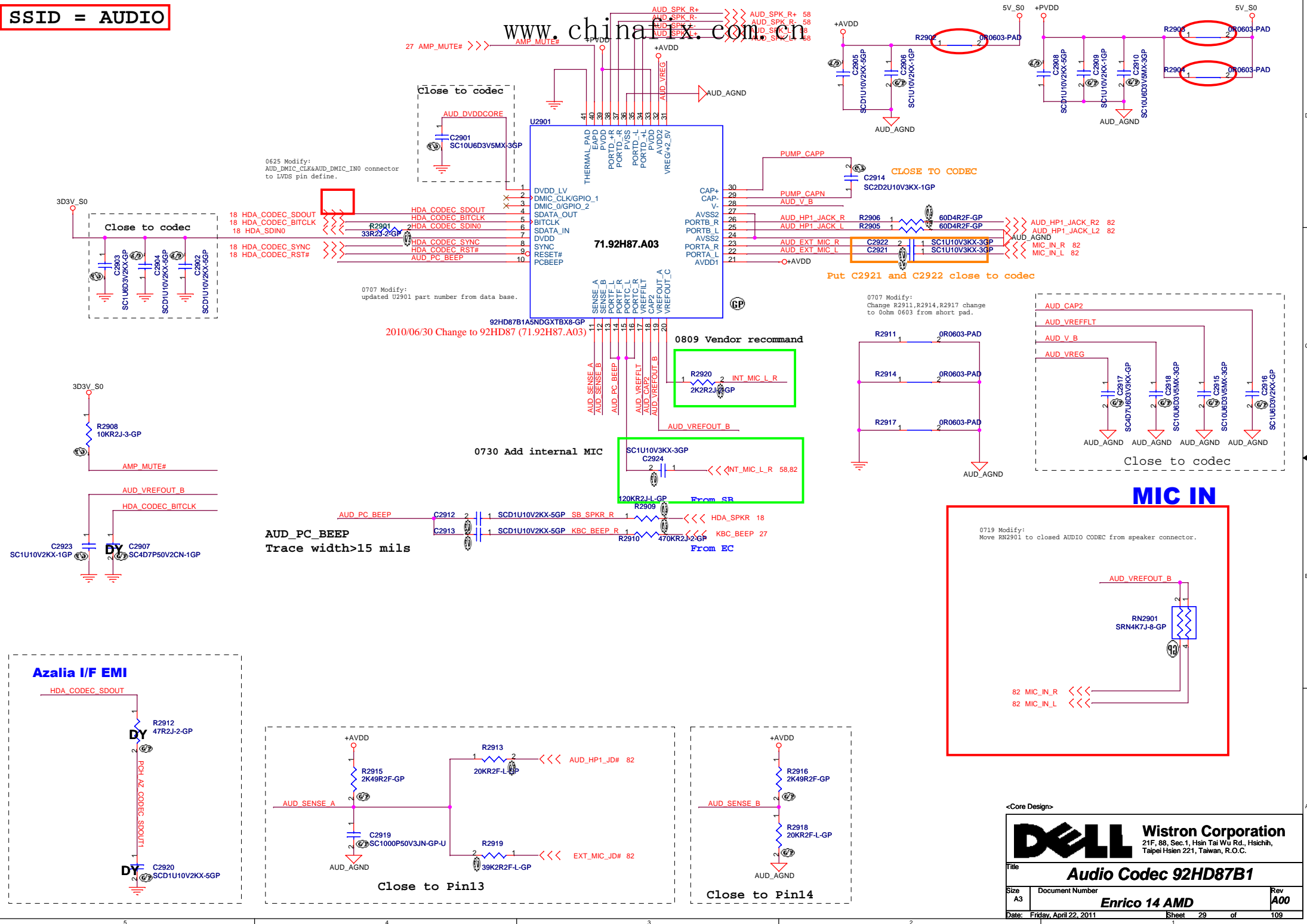
VGA Thermal sensor P2800



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

SSID = AUDIO

www.chinafix.com.cn



<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

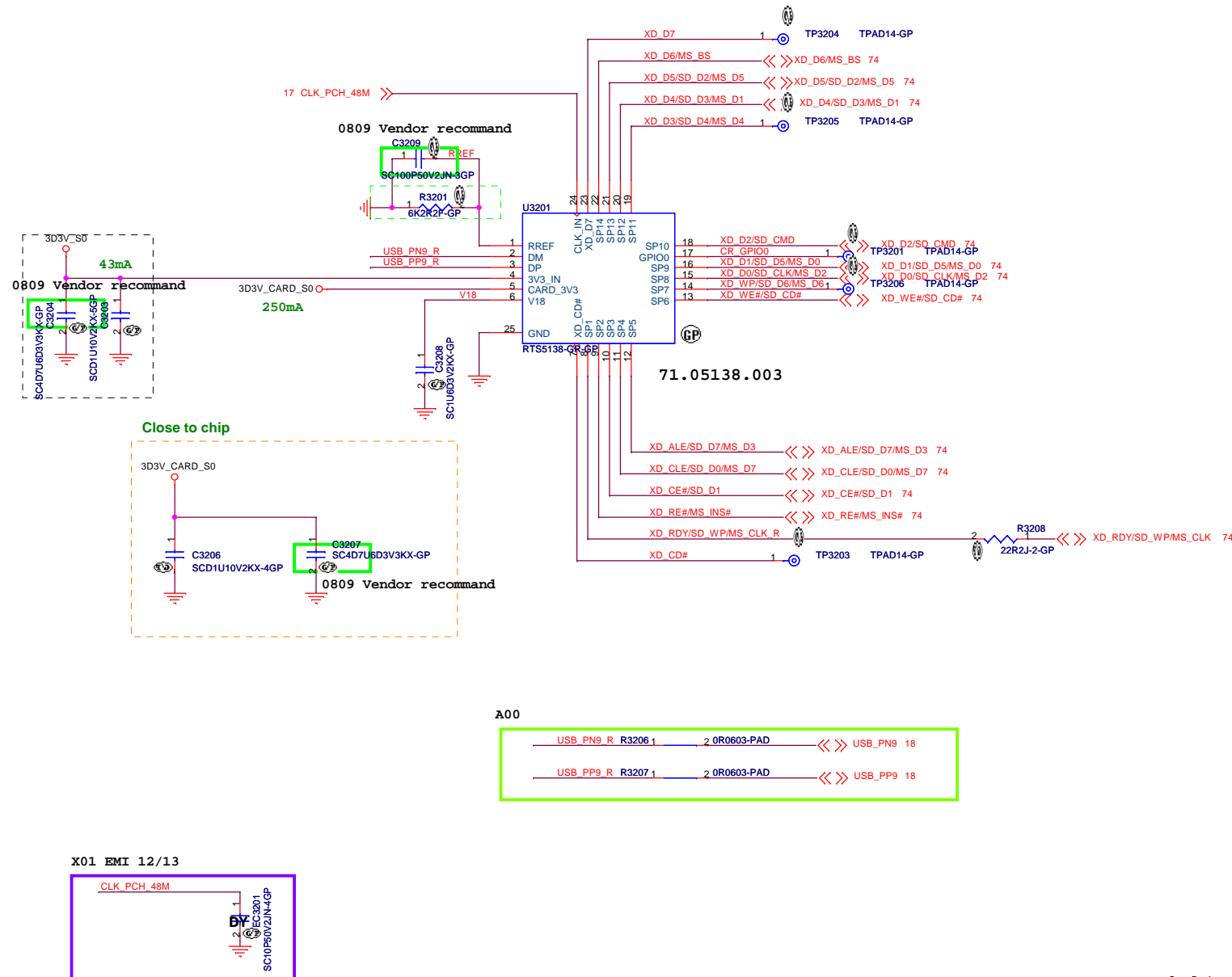
Title			AMP		
Size	Document Number				Rev
A3	Enrico 14 AMD				A00
Date: Friday, April 22, 2011		Sheet	30	of	109

www.chinafix.com.cn
LAN CHIP



SSID = SDIO

www.chinafix.com.cn



A00

X01 EMI 12/13


<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		Reserved	
Size	Document Number	Rev	
A3		A00	
Date: Friday, April 22, 2011		Sheet	109

(Blanking)

<Core Design>			
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Reserved			
Size A3	Document Number		Rev A00
Date: Friday, April 22, 2011		Sheet 33 of	109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size
A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 34 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Size

A3

Document Number

Enrico 14 AMD

Date: Friday, April 22, 2011

Sheet 35 of 109

Rev

A00

Reserved

D

D

C

C


B

B

A

A

<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
		Title <i>Power Plane Enable</i>	
Size A3	Document Number <i>Enrico 14 AMD</i>		Rev <i>A00</i>
Date: Friday, April 22, 2011		Sheet 37 of	109

0721 Remove PSID schematic



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

No.	Title	Date	Page
1	Title	Date	Page
2	Title	Date	Page
3	Title	Date	Page
4	Title	Date	Page
5	Title	Date	Page
6	Title	Date	Page
7	Title	Date	Page
8	Title	Date	Page
9	Title	Date	Page
10	Title	Date	Page
11	Title	Date	Page
12	Title	Date	Page
13	Title	Date	Page
14	Title	Date	Page
15	Title	Date	Page
16	Title	Date	Page
17	Title	Date	Page
18	Title	Date	Page
19	Title	Date	Page
20	Title	Date	Page
21	Title	Date	Page
22	Title	Date	Page
23	Title	Date	Page
24	Title	Date	Page
25	Title	Date	Page
26	Title	Date	Page
27	Title	Date	Page
28	Title	Date	Page
29	Title	Date	Page
30	Title	Date	Page
31	Title	Date	Page
32	Title	Date	Page
33	Title	Date	Page
34	Title	Date	Page
35	Title	Date	Page
36	Title		

DCIN JACK

Size	Document Number
Custom	Enrico 14 AMD

Rev
A00

Date: Friday, April 22, 2011	Sheet 38 of 109
------------------------------	-----------------

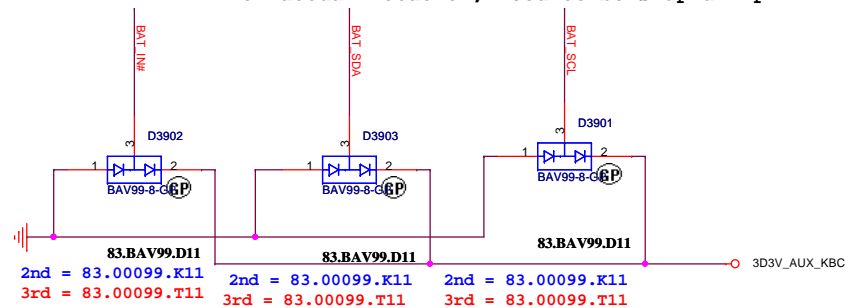
Batt Connector

The schematic diagram illustrates the connections for the Batt Connector (X01). It shows the following components and connections:

- BT+:** Connected to the BT+ pin of the connector. A capacitor C3902 (SCD1U50V3KX-GP) is connected to ground.
- BAT_ALERT:** Connected to the BAT_ALERT pin of the connector. A capacitor AFTP3901 is connected to ground.
- PBAT Presense:** Connected to the PBAT Presense pin of the connector. A capacitor PD3902 (SMF1BAT1G-GP) is connected to ground.
- SMBus:** Connected to the PBAT SMBDAT1 and PBAT SMBCLK1 pins of the connector. Resistors R3903 and R3902 (100R2J-2-GP) are connected to ground.
- I2C:** Connected to the BAT_SDA and BAT_SCL pins of the connector. Resistors R3903 and R3902 (100R2J-2-GP) are connected to ground.
- EC3902:** Connected to the EC3902 pin of the connector. A capacitor SC10P50V2JN-4GP is connected to ground.
- EC3901:** Connected to the EC3901 pin of the connector. A capacitor SC10P50V2JN-4GP is connected to ground.

The diagram also shows the connection of the connector to the system, with the connector pins labeled 1 through 11. The connector is labeled X01 and the system is labeled X01.

For actual location, need to be swap all pin



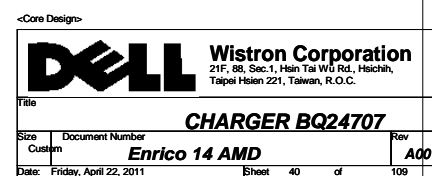
DELL

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

BATT CONN

Enrico 14 AMD

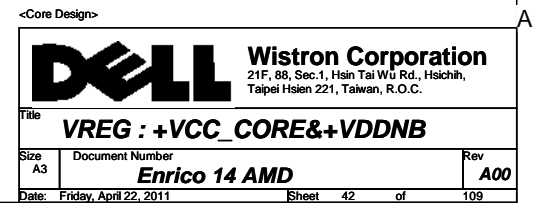
109



www.chinafix.com.cn

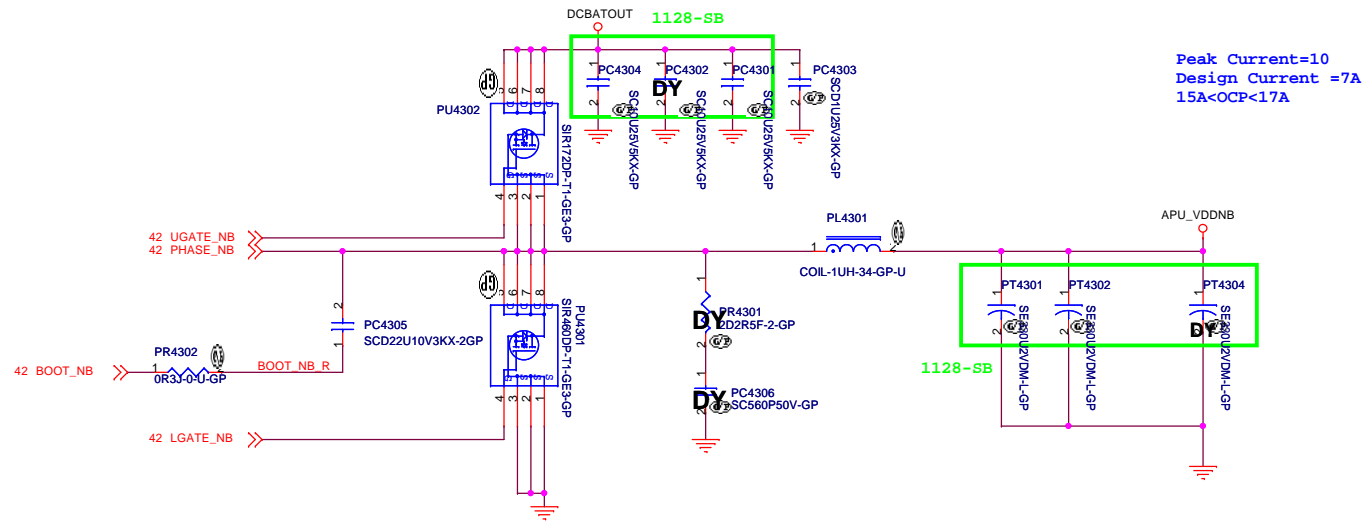


www.chinafix.com.cn



SSID = PWR.Plane.VDDNB.REG

www.chinafix.com.cn



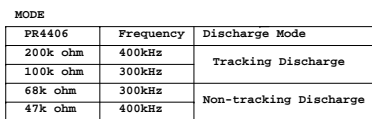
I/P cap: 10U 25V K0805 X5R/ 78.10622.51L
Inductor: 1uH PCMC063T-1R0MN Cyntec 9mohm/10mohm Isat =22Arms 68.1R01A.20B
O/P cap: 330U 2V EEFSX0D331ER 9mOhm 3Arms Panasonic/79.33719.L01
H/S: SIR712DP/ POWERPAK/10.3mOhm/12.4mOhm@4.5Vgs/ 84.00172.037
L/S: SiR460DP/ POWERPAK/ 4.9mOhm/ 6.1mohm@4.5Vgs/ 84.00460.037

<Core Design>



Title			
TPS51218 VDDNB			
Size	Document Number		Rev
A3	Enrico 14 AMD		A00
Date: Friday, April 22, 2011		Sheet 43 of	109

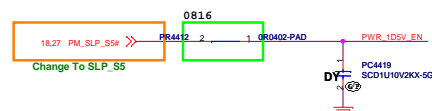
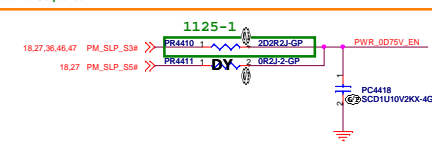
www.chinafix.com.cn



I/P cap: 10U 25V K0805 X5R/ 78.10622.51L
Inductor: 1.5uH PCMC104T-1R5MH Cyntec 3.8mohm/4.2mohm Isat =33Arms 68.1R510.20I
O/P cap: 220U 2V EEPFC00221R 15mohm 2.7Arms Panasonic/79.22719.20L
H/S: SR1712DP/ POWERPAK/10.3mohm/12.4mohm@4.5Vgs/ 84.00172.037
L/S: SR1460DP/ POWERPAK/ 4.9mohm/ 6.1mohm@4.5Vgs/ 84.00460.037

Intel Sequence, Remove

Add For Sequence



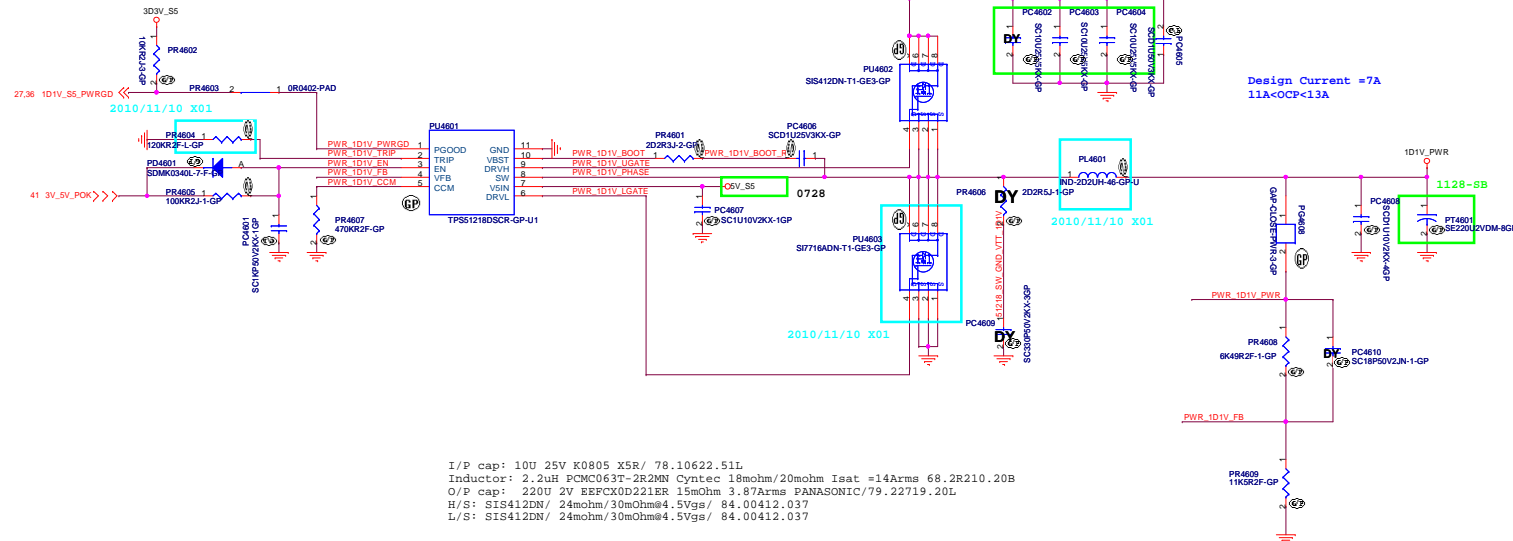
(Blanking)

<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
VDDR & VDDP			
Size A3	Document Number		Rev
	Enrico 14 AMD		A00
Date: Friday, April 22, 2011	Sheet	45	of 109

SSID = PWR.Plane.1V1REG

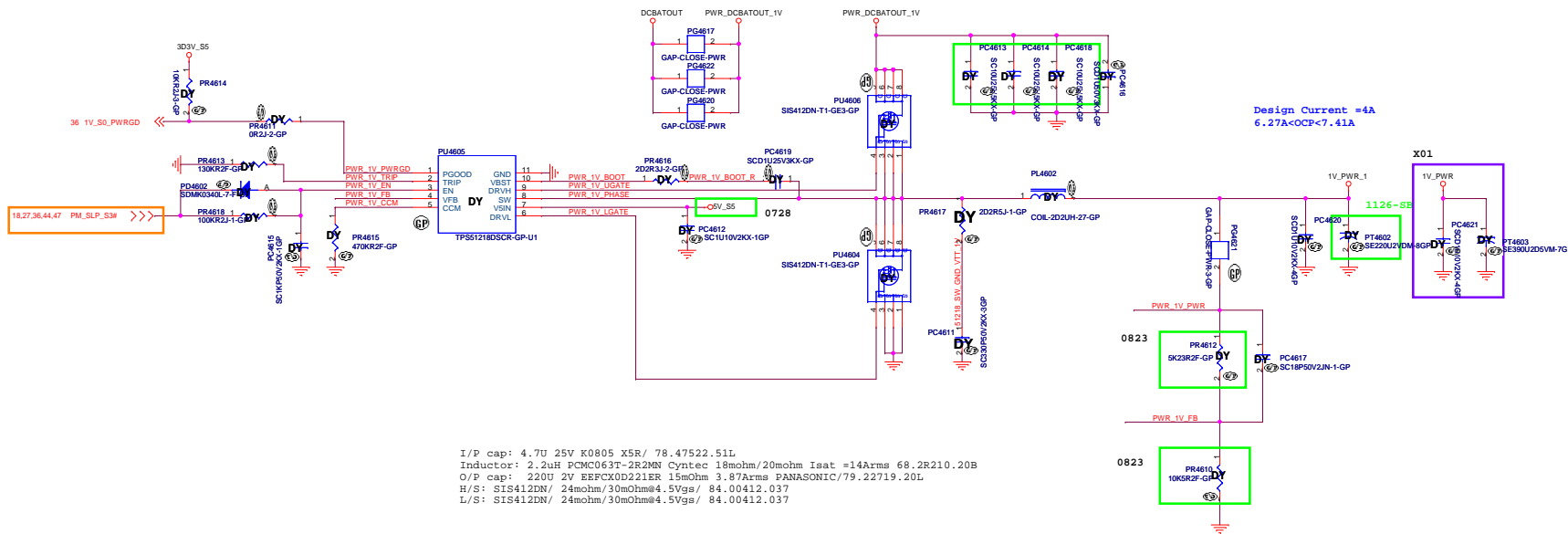
www.chinafix.com.cn



I/P cap: 10U 25V K0805 X5R/ 78.10622.51L
Inductor: 2.2uH PCMC063T-2R2MN Cyntec 18mohm/20mohm Isat =14Arms 68.2R210.20B
O/P cap: 220U 2V EEFCXD0221ER 15mOhm 3.87Arms PANASONIC/79.22719.20L
H/S: SIS412DN/ 24mohm/30mOhm@4.5Vgs/ 84.00412.037
L/S: SIS412DN/ 24mohm/30mOhm@4.5Vgs/ 84.00412.037

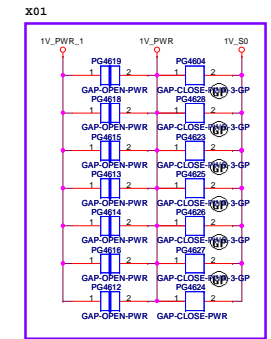
$$V_{out} = 0.704V * (R1 + R2) / R2$$

SSID = PWR.Plane.1VREG



I/P cap: 4.7U 25V K0805 X5R/ 78.47522.51L
Inductor: 2.2uH PCMC063T-2R2MN Cyntec 18mohm/20mohm Isat =14Arms 68.2R210.20B
O/P cap: 220U 2V EEFCXD0221ER 15mOhm 3.87Arms PANASONIC/79.22719.20L
H/S: SIS412DN/ 24mohm/30mOhm@4.5Vgs/ 84.00412.037
L/S: SIS412DN/ 24mohm/30mOhm@4.5Vgs/ 84.00412.037

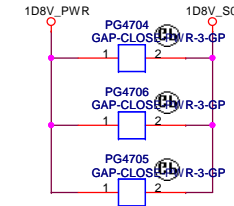
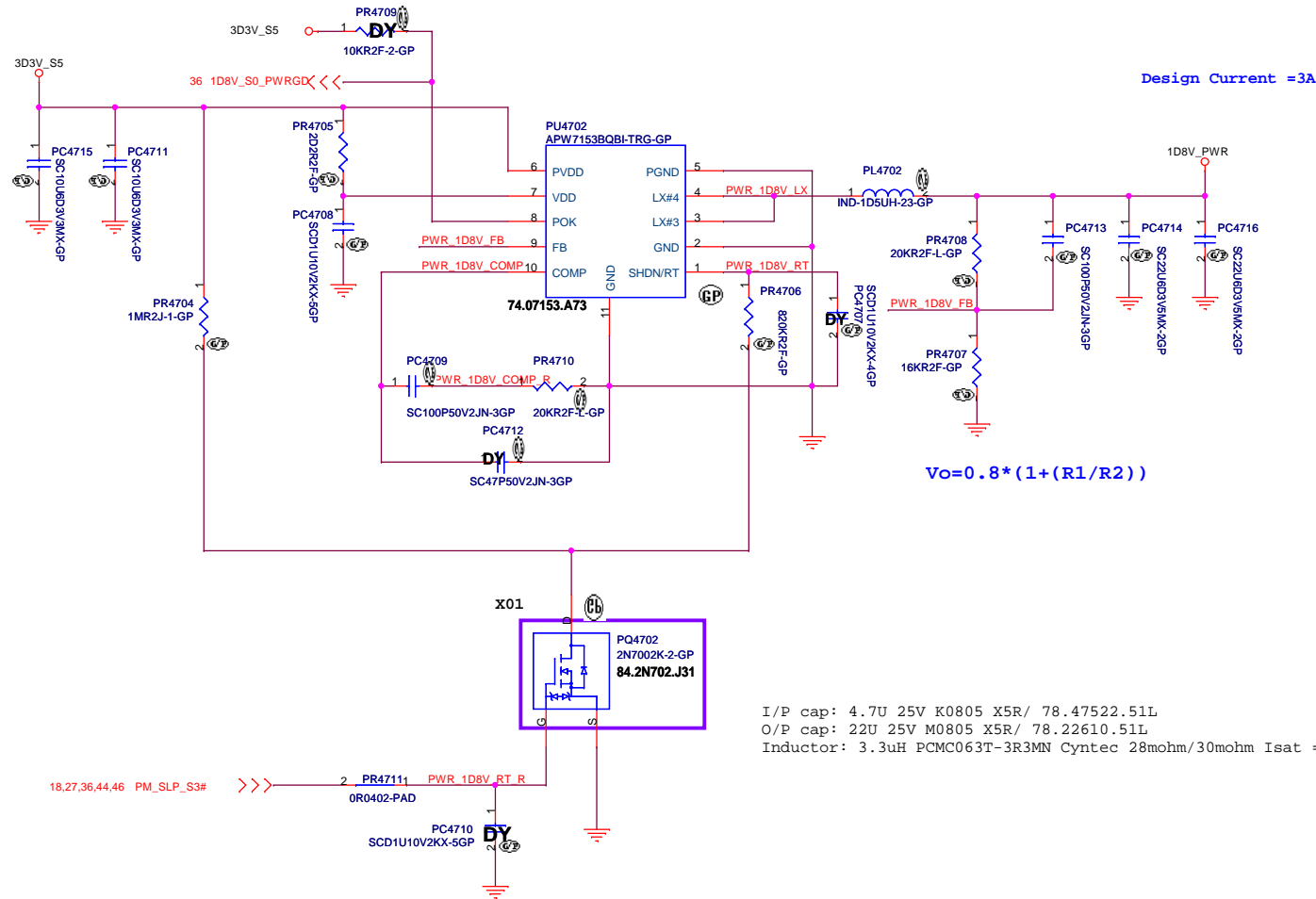
$$V_{out} = 0.704V * (R1 + R2) / R2$$



<Core Design>

SSID = PWR.Plane.1V8REG

www.chinafix.com.cn
APW7153B for 1D8V_S0



I/P cap: 4.7U 25V K0805 X5R/ 78.47522.51L
O/P cap: 22U 25V M0805 X5R/ 78.22610.51L
Inductor: 3.3uH PCMC063T-3R3MN Cyntec 28mohm/30mohm Isat =13.5Arms 68.3R310.20A

<Core Design>

DELL		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title			
RT8015B 1D8V S0			
Size	Document Number	Rev	
A3		A00	
Date: Friday, April 22, 2011		Sheet	47 of 109

(Blanking)

<Core Design>

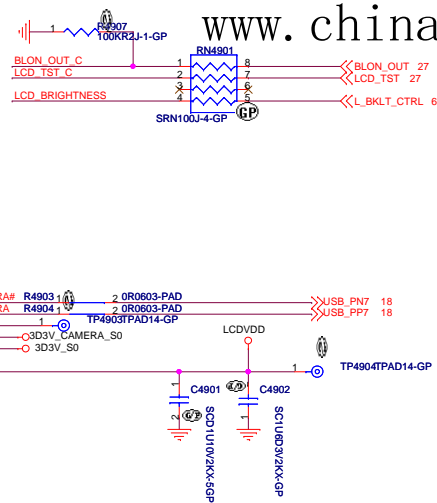


Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			Reserved		
Size	Document Number				Rev
A3	Enrico 14 AMD				A00
Date: Friday, April 22, 2011			Sheet	48	of 109

SSID = VIDEO

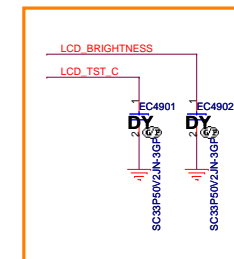
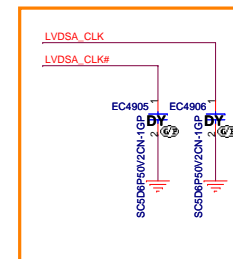
LVDS CONNECTOR



INVERTER POWER

Camera Power

Close to LVDS connector



For EMI request

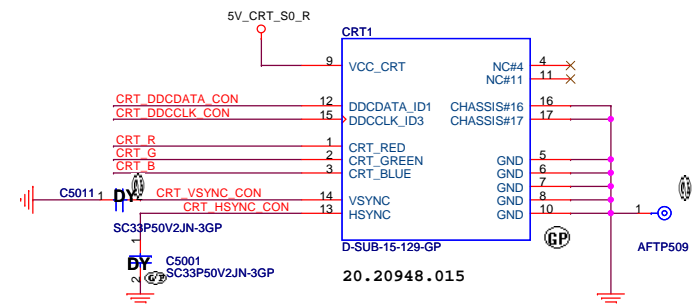
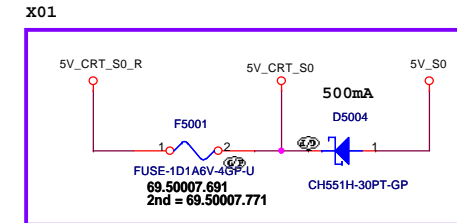
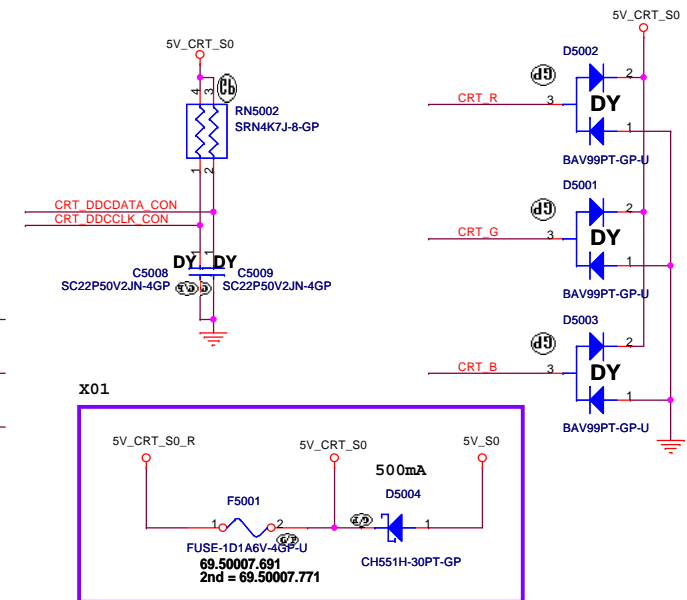
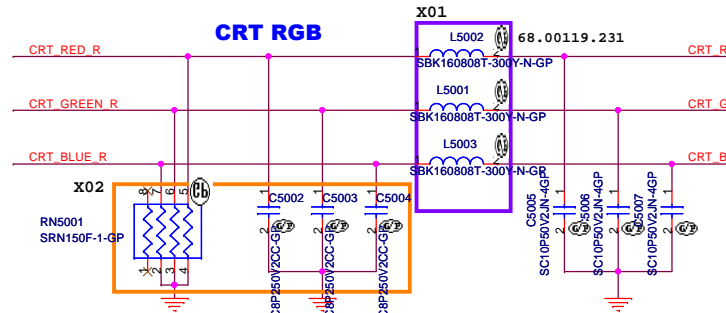
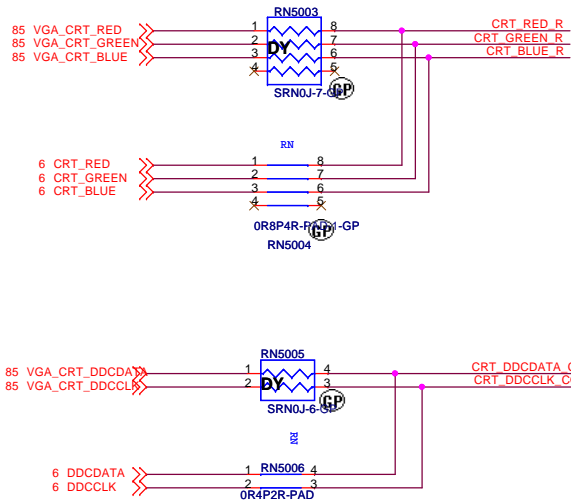
<Core Design>

DELL		Wistron Corporation	
		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
LCD/Inverter Connector			
Size	Document Number	Rev	
Custom			
Enrico 14 AMD		A00	
Date:	Friday, April 22, 2011	Sheet	49 of 109

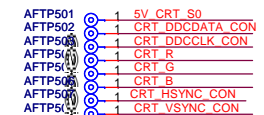
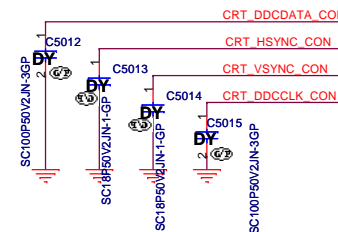
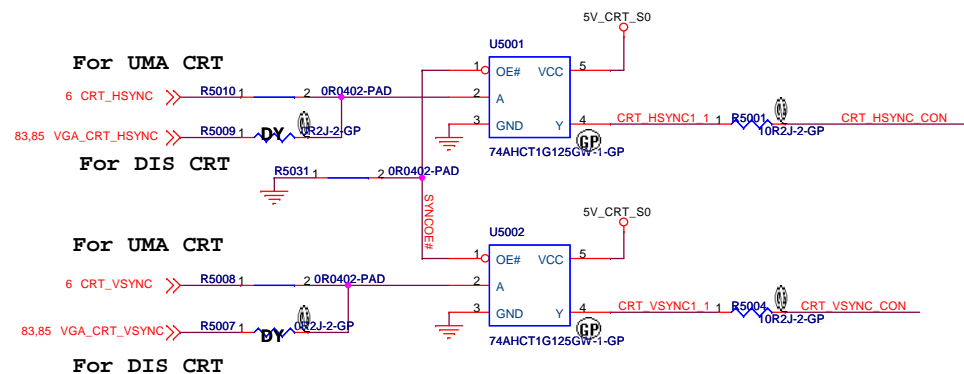
SSID = VIDEO

Layout Note:
www.chinafix.com.cn

*Pi-filter & 150 Ohm pull-down resistors should be as close as to CRT CONN.
* RGB signal will hit 75 Ohm first, then pi-filter, finally CRT CONN.



CRT Hsync & Vsync level shift



DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Haichih,
Taipei Hsien 221, Taiwan, R.O.C.

File: **DCIN**

Size: **A3** Document Number: **Enrico 14 AMD** Rev: **A00**

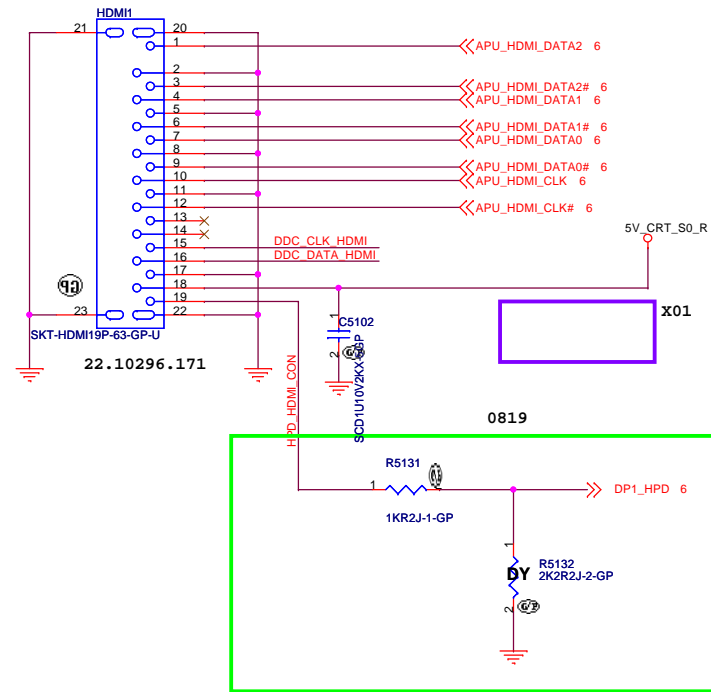
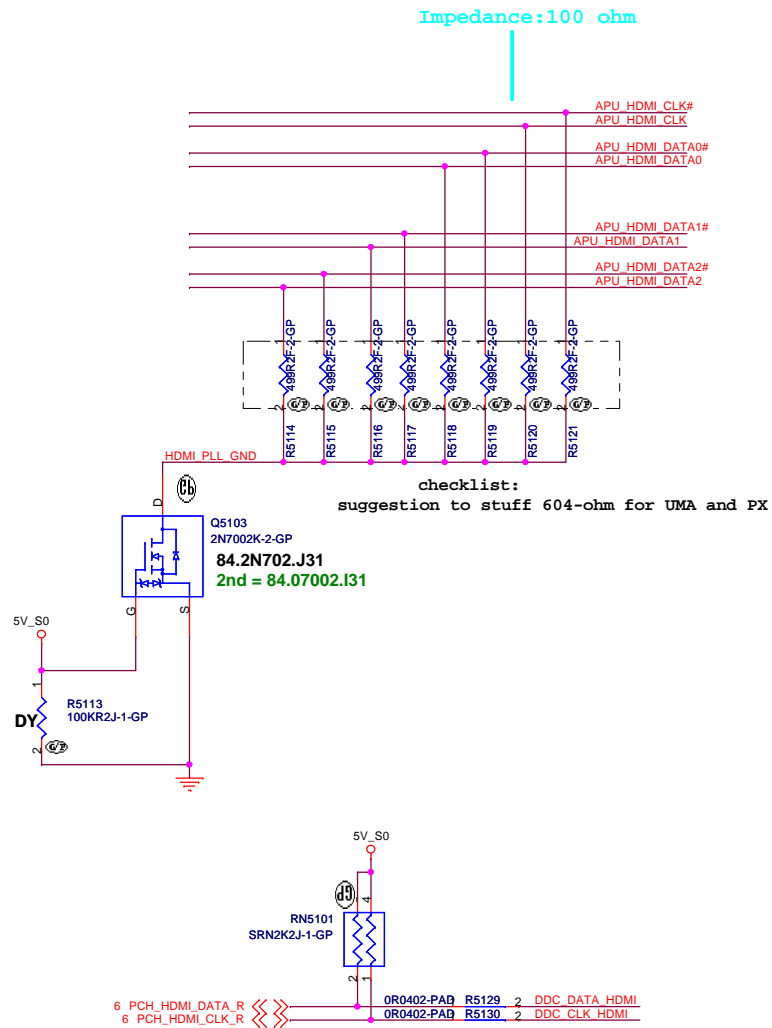
Date: Friday, April 22, 2011 Sheet 50 of 109

SSID = VIDEO

www.chinafix.com.cn

HDMI Level Shifter & CONNECTOR

HDMI CONN



<Core Design>

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			eDP		
Size	Document Number				Rev
A3	Enrico 14 AMD				A00
Date: Friday, April 22, 2011			Sheet	52	of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size
A3

Document Number

Enrico 14 AMD

Rev

A00

Date: Friday, April 22, 2011

Sheet 53 of 109

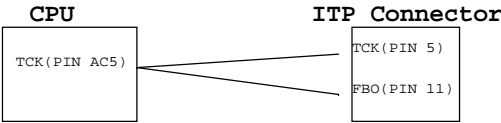
(Blanking)

SSID = User.Interface

www.chinafix.com.cn

ITP Connector

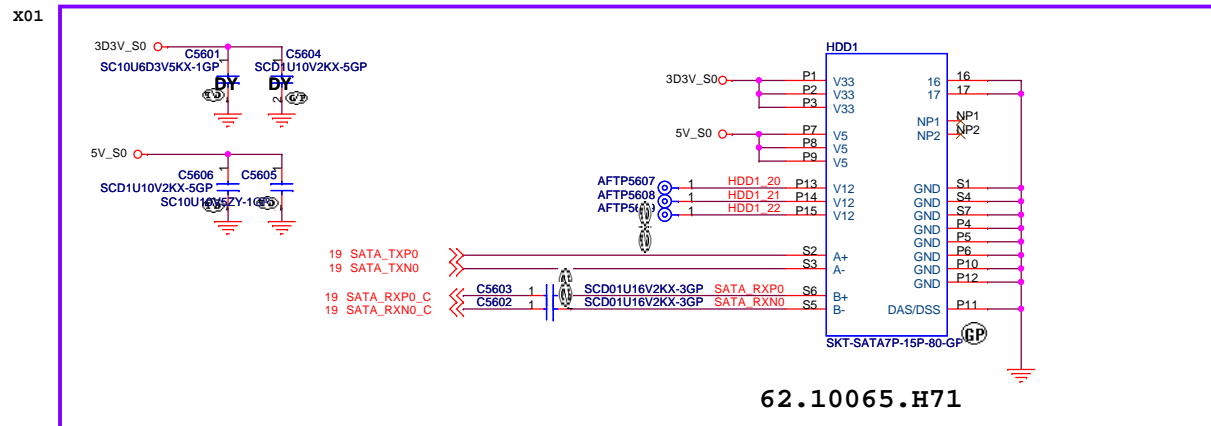
H_CPURST# use pull-up Resistor close
ITP connector 500 mil (max),
others place near CPU side.



SSID = SATA

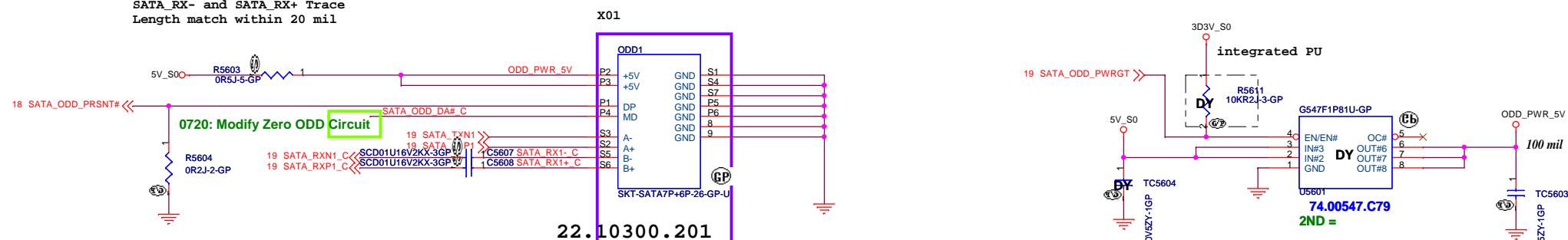
SATA HDD Connector

www.chinafix.com.cn

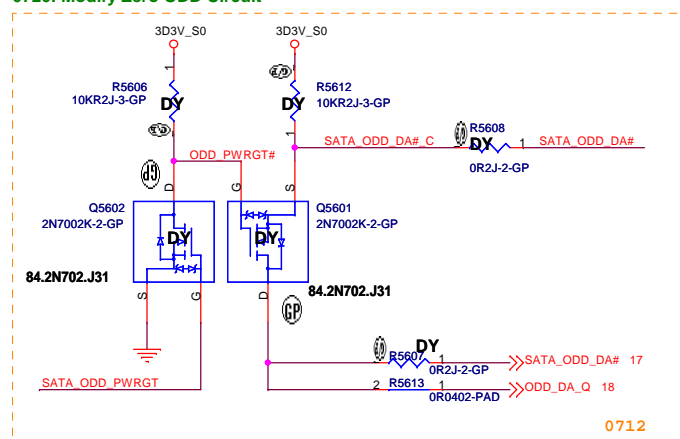


ODD Connector

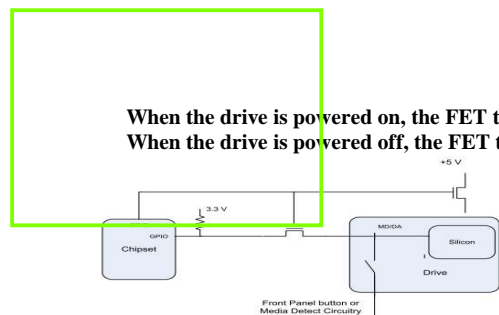
SATA_RX- and SATA_RX+ Trace
Length match within 20 mil



0720: Modify Zero ODD Circuit



0721 Remove ODD_DA PU



When the drive is powered on, the FET to the MD/DA pin drive is OFF.
When the drive is powered off, the FET to the MD/DA pin is ON

<Core Design>

DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **HDD/ODD**
Size: A3 Document Number: **Enrico 14 AMD** Rev: **A00**
Date: Friday, April 22, 2011 Sheet: 56 of 109

SSID = ESATA

www.chinafix.com.cn

(Blanking)

<Core Design>



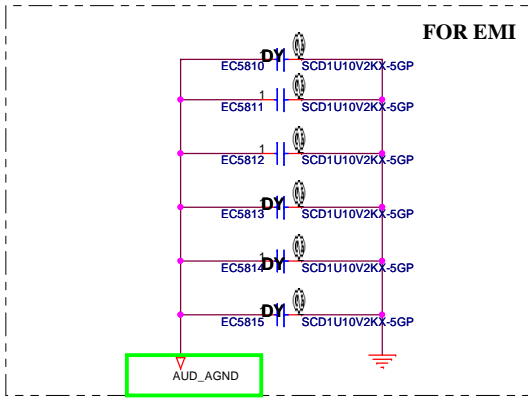
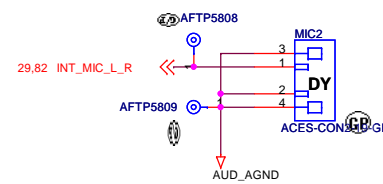
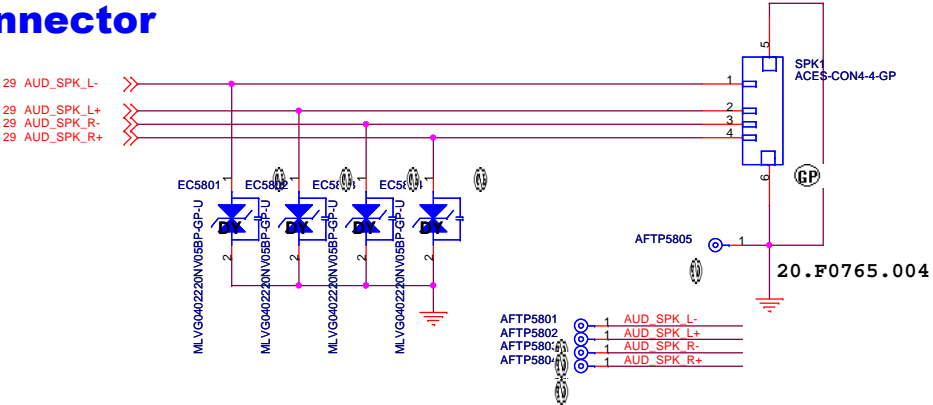
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		
ESATA/USB Charger		
Size	Document Number	Rev
A3	Enrico 14 AMD	A00
Date: Friday, April 22, 2011		
Sheet 57 of 109		

SSID = AUDIO

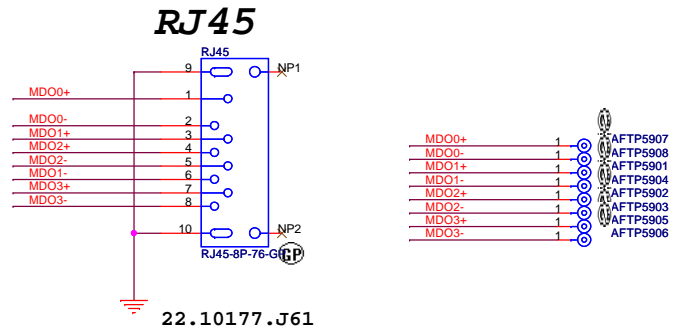
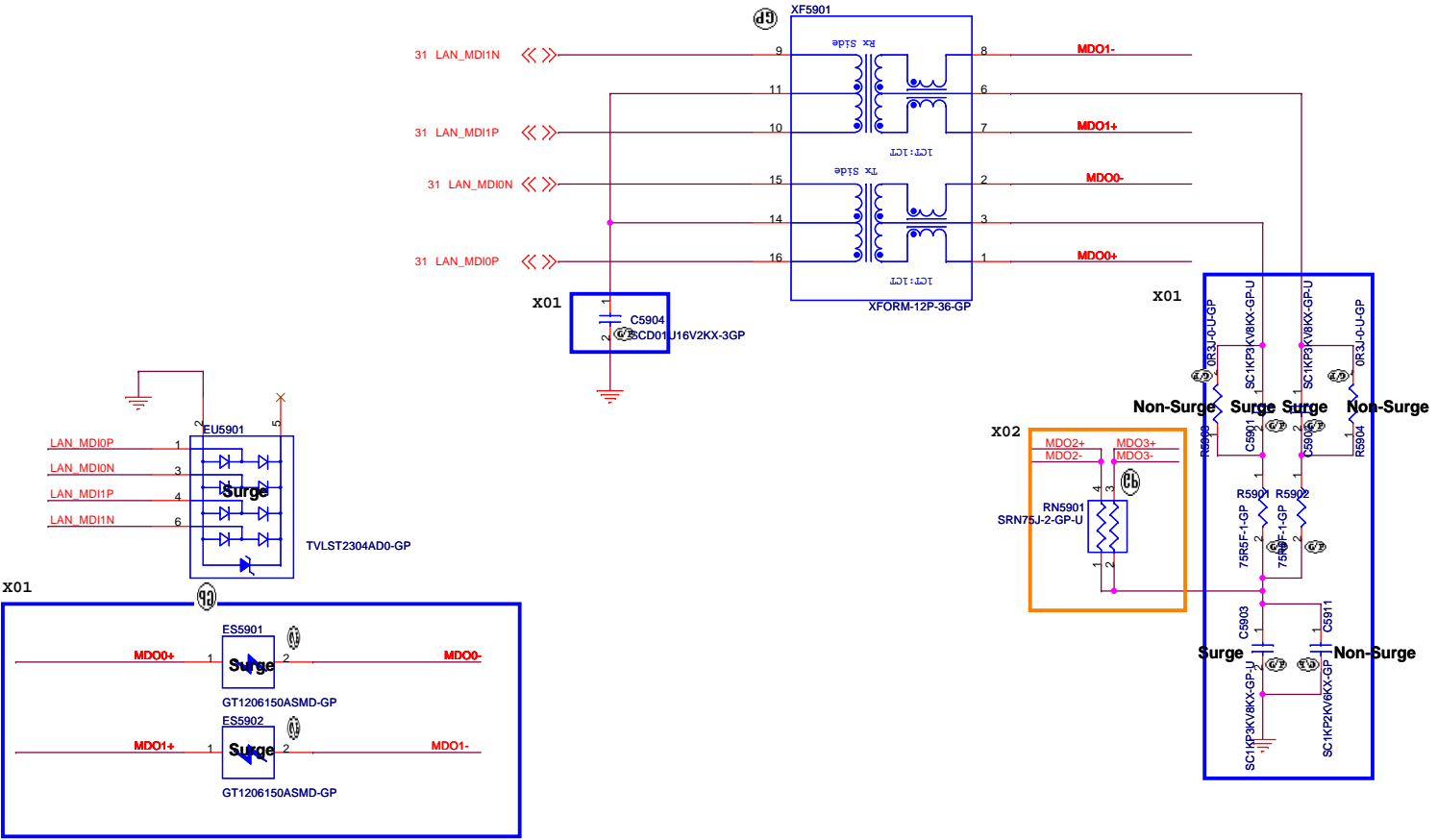
www.chinafix.com.cn

Speaker
Connector



0804 Change to AGND

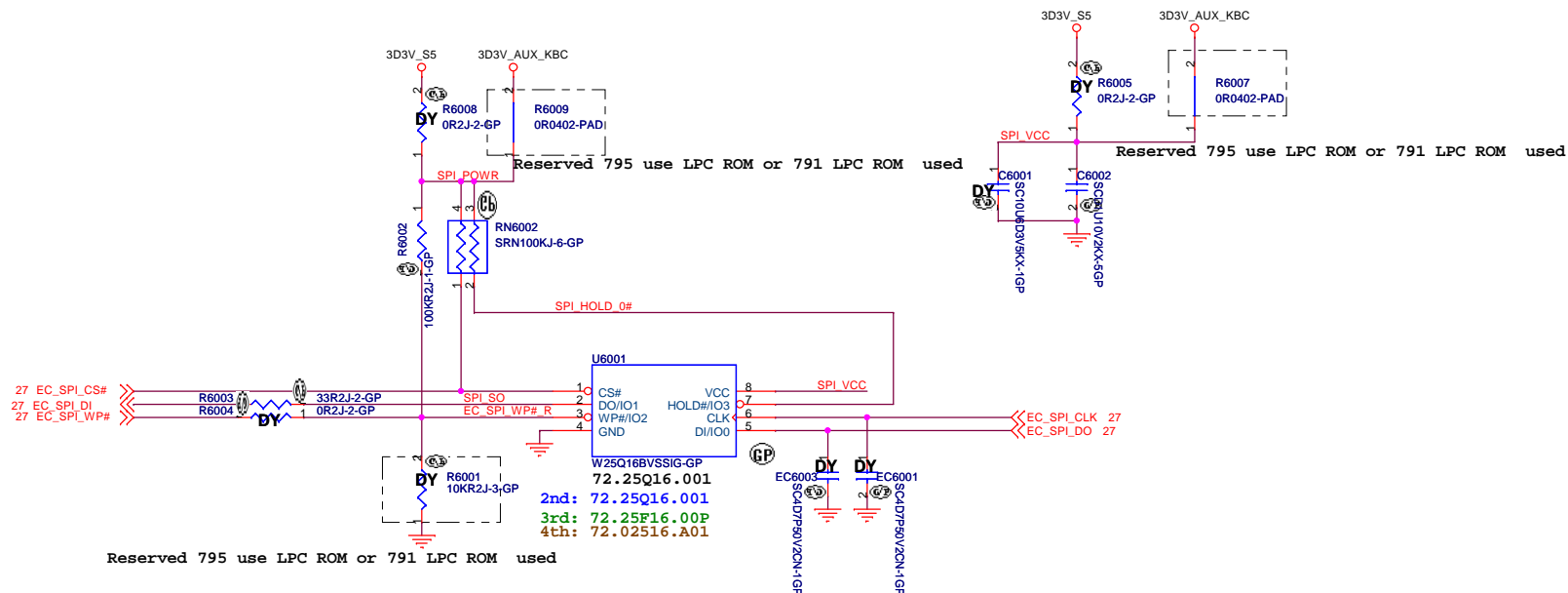
SSID = LOM



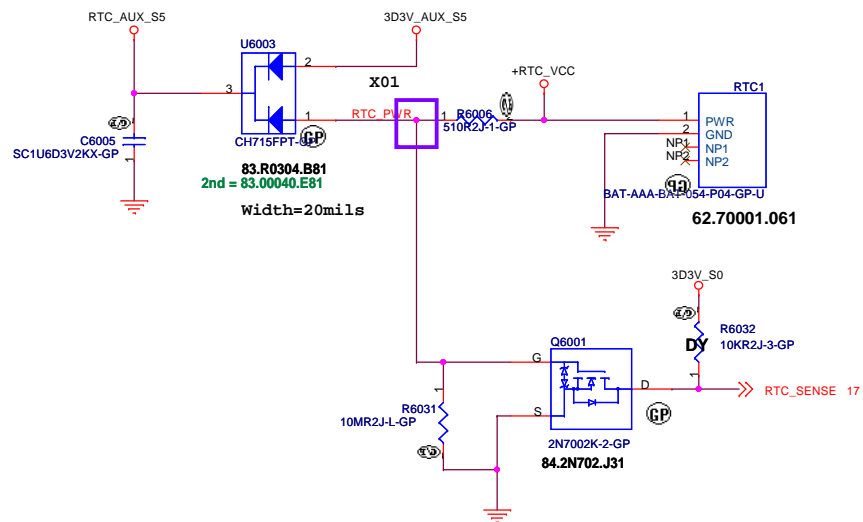
SSID = Flash.ROM

SPI FLASH ROM (2M byte) for KBC

www.chinafix.com.cn



SSID = RBATT



<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Flash/RTC

Size

Document Number

Enrico 14 AMD

Rev

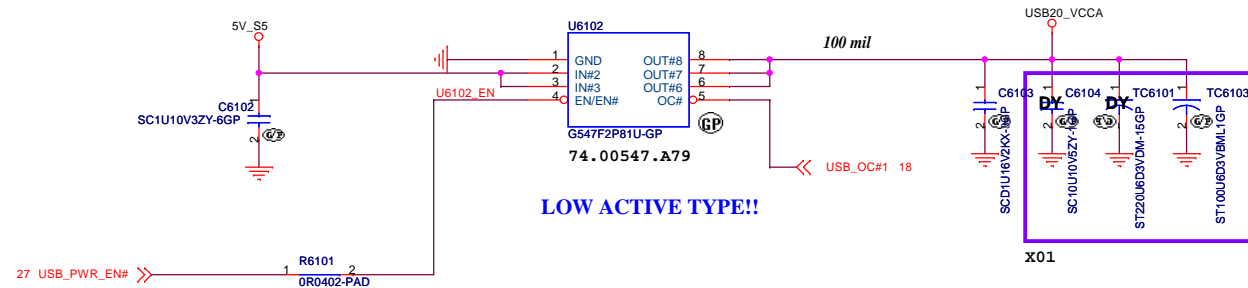
A00

Date: Friday, April 22, 2011

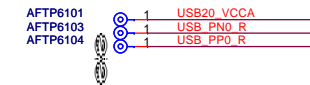
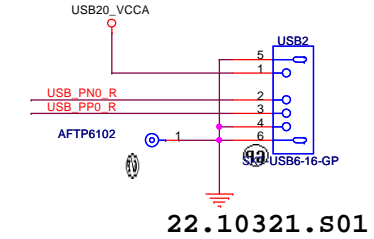
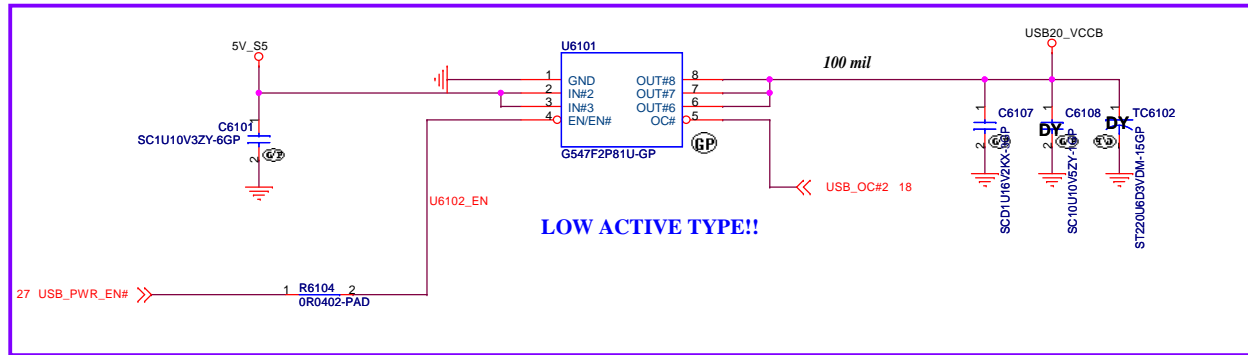
Sheet 60 of 109

SSID = USB

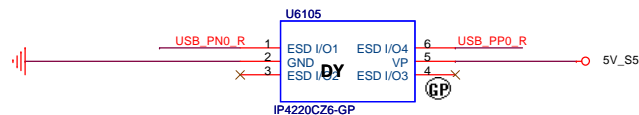
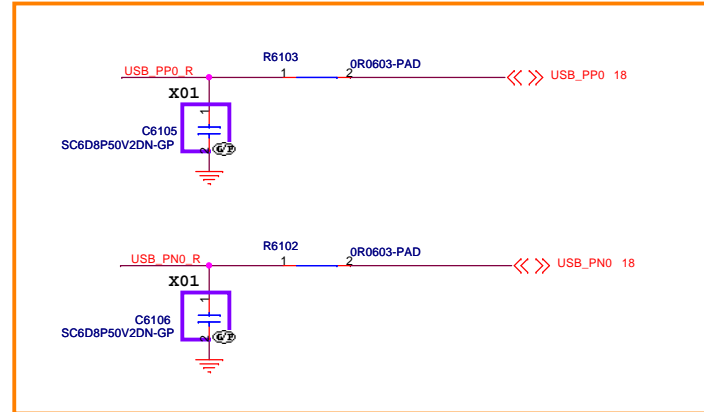
www.chinafix.com.cn



X01




X02



<Core Design>

(Blanking)

<Core Design>



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

USB 3.0

Size

A3

Document Number

Enrico 14 AMD

Rev

A00

Date: Friday, April 22, 2011


Sheet 62 of 109

SSID = User.Interface

www.chinafix.com.cn

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title


Bluetooth

Size	Document Number	Rev
A3	Enrico 14 AMD	A00

Date: Friday, April 22, 2011	Sheet 63 of 109
------------------------------	-----------------

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

F/P

Size
A3

Document Number
Enrico 14 AMD

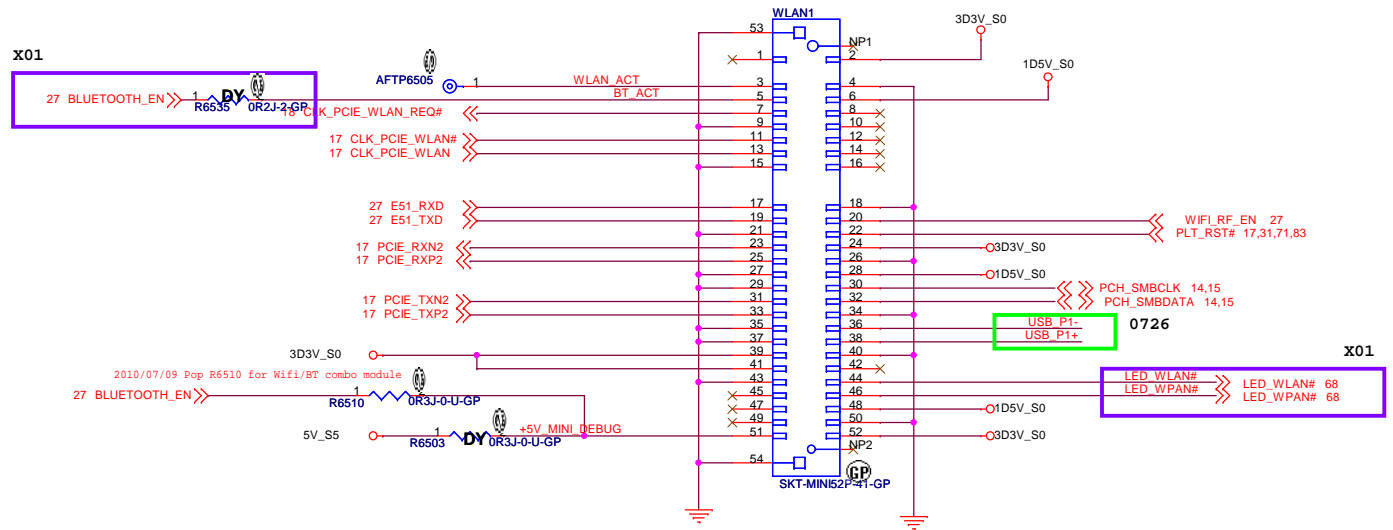
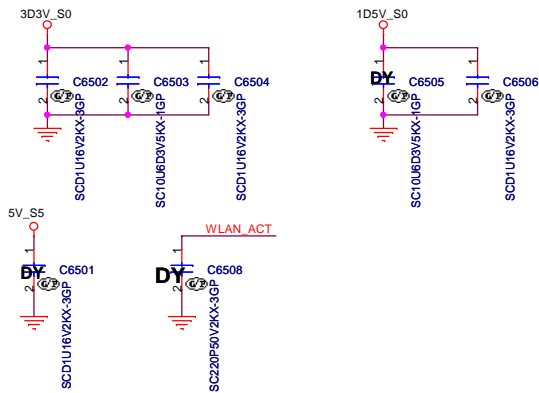
Rev
A00

Date: Friday, April 22, 2011

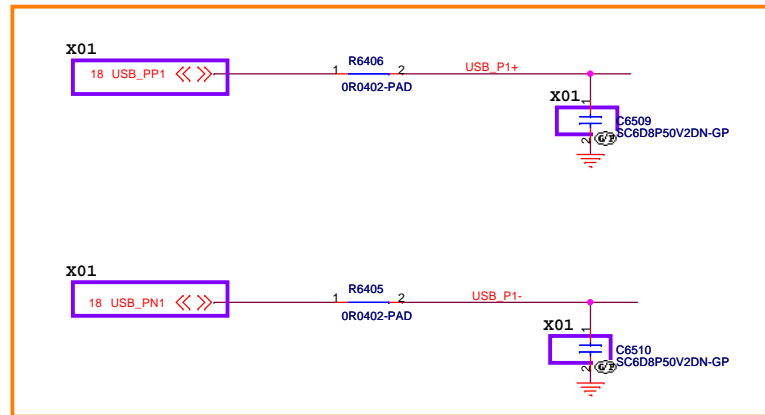
Sheet 64 of 109

SSID = Wireless

Mini Card Connector(802.11a/b/g/n)



X02



05/19 Add Common Mode Choke
2010/07/16 Change CMC L6401 to smaller 69.10118.001 (the same same as other CMCs on MB) and rename L6401 to TR6501.
Change R6406,R6405 to 0R 0402 size

<Core Design>




Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title		MINICARD(WLAN)/TP CONN	
Size	Document Number	Rev	A00
A3	Enrico 14 AMD		
Date:	Friday, April 22, 2011	Sheet	65 of 109

(Blanking)

<Core Design>



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

WWAN

Size

A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 66 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

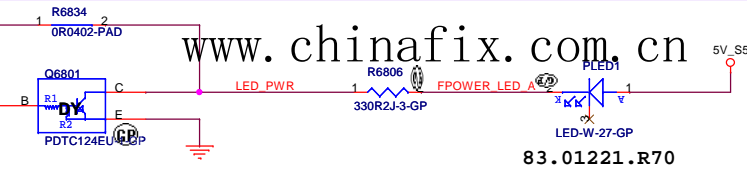
Title

Reserved

Size	Document Number	Rev
A3	Enrico 14 AMD	A00
Date: Friday, April 22, 2011		Sheet 67 of 109

X01

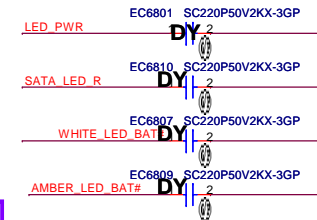
FRONT POWER LED

27 PWRLED#
19 SATA_LED#

SATA HDD LED(White)

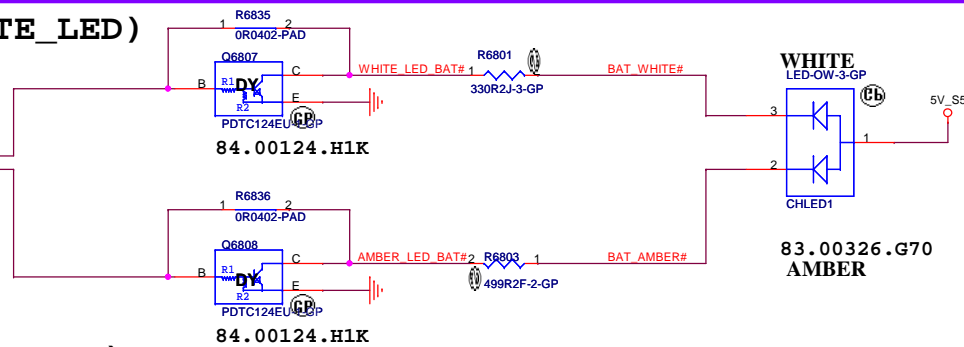
84.00143.M11

SSID = User.Interface



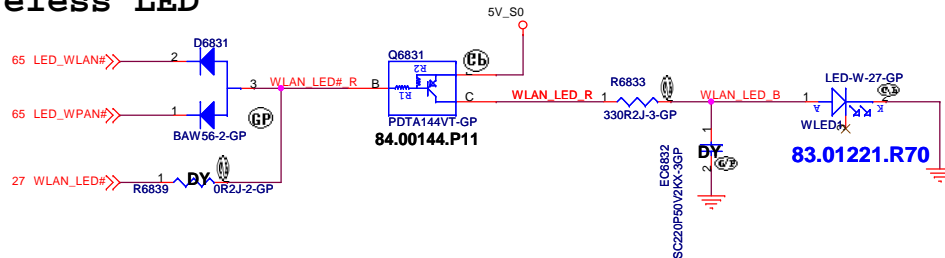
X01

Battery LED2(WHITE_LED)

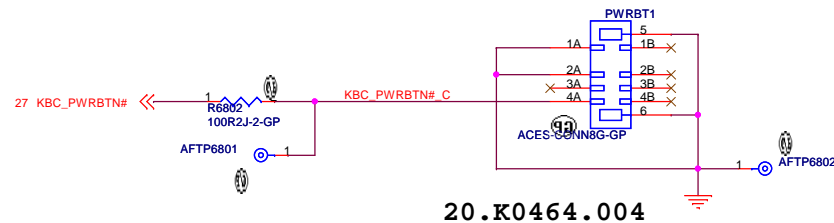
27 BATT_WHITE_LED#
27 CHG_AMBER_LED#

Battery LED1(AMBER_LED)

Wireless LED



Power button

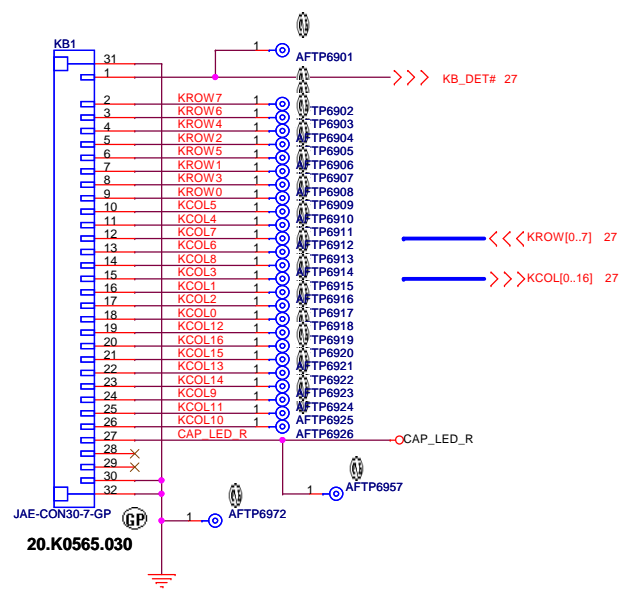


<Core Design>

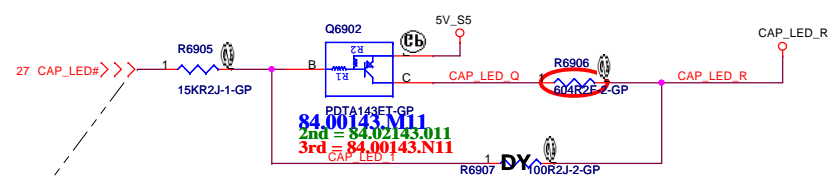
X01

SSID = KBC

www.chinafix.com.cn

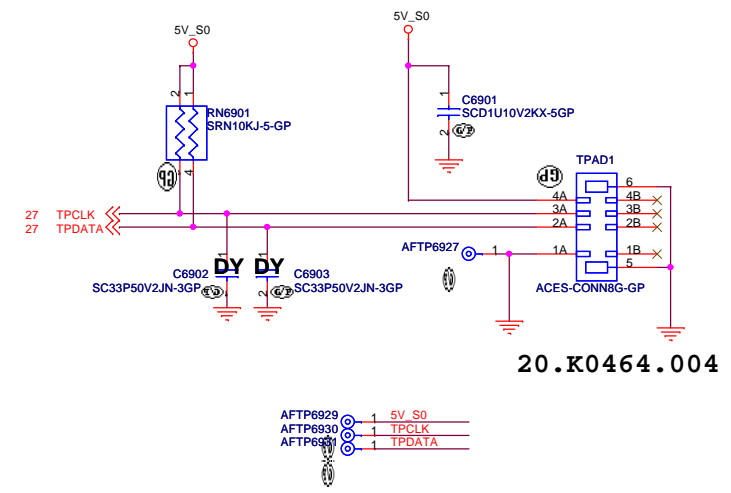


20101116 X02 Modify:
Change R6906 to 1K from 390ohm for
fine tune LED illumination.
20101118 X02:
Dell recommend: change all white LEDs resistor to 620 ohm.
20101202 X02:
Dell recommend: change all white LEDs resistor to 604 ohm.



CAP_LED:(X01 Low active)
Connect to KB driving internal LED directly.(MAX 25mA)

TouchPad Connector

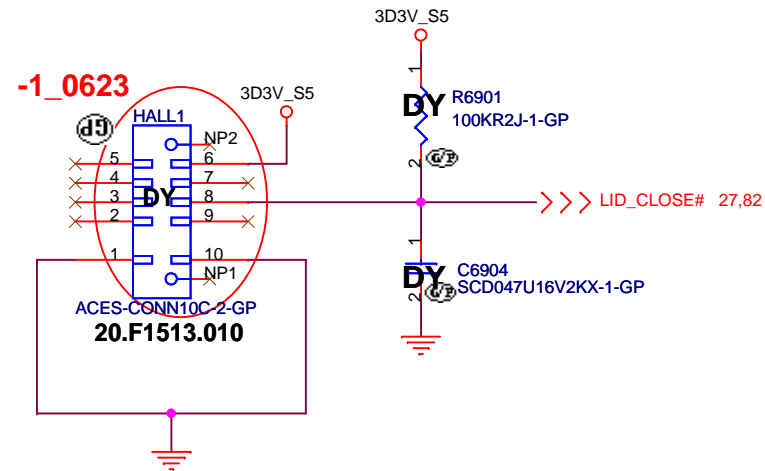


20.K0464.004

<Core Design>

DELL		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichin, Taipei Hsien 221, Taiwan, R.O.C.	
Title Key Board/Touch Pad			
Size A3	Document Number Enrico 14 AMD	Rev A00	
Date: Friday, April 22, 2011		Sheet 69	of 109

SSID = Hall.Sensor



<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Hall Effect Sensor

Size
A4

Document Number

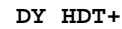
Enrico 14 AMD

Rev
A00

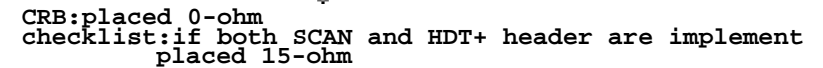
Date: Friday, April 22, 2011

Sheet 70 of 109

www.chinafix.com.cn




1D8V_S0



Sheet 71 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Size
A3

Document Number
Enrico 14 AMD


Rev
A00

Date: Friday, April 22, 2011

Sheet 72 of 109

(Blanking)

<Core Design>



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

Rev

A00

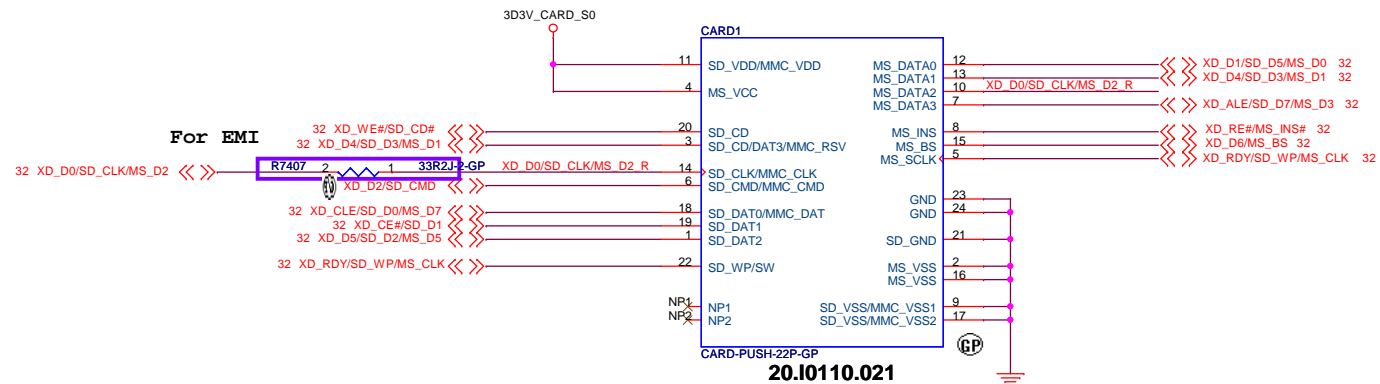
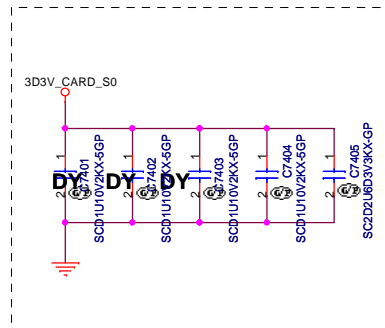
Date: Friday, April 22, 2011

Sheet 73 of 109

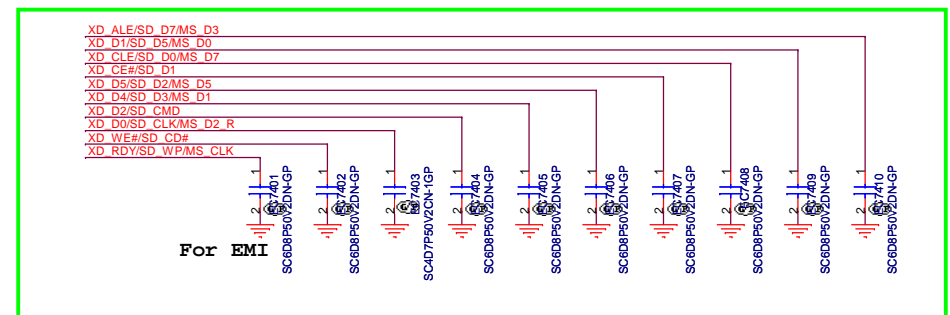
SSID = SDIO

SD/XD/MS Card Reader

www.chinafix.com.cn



0810 Vendor Recommend




<Core Design>

DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
CARD Reader Connector			
Size	Document Number	Rev	
A3	Enrico 14 AMD	A00	
Date: Friday, April 22, 2011		Sheet	74 of 109


(Blanking)

<Core Design>

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Express Card			
Size A3	Document Number Enrico 14 AMD		Rev A00
Date: Friday, April 22, 2011		Sheet 75 of	109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size	Document Number	Rev
A3	Enrico 14 AMD	A00

Date: Friday, April 22, 2011	Sheet 76 of 109
------------------------------	-----------------

(Blanking)

<Core Design>



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Size
A3

Document Number
Enrico 14 AMD

Rev
A00

Date: Friday, April 22, 2011

Sheet 77 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size
A4

Document Number

Enrico 14 AMD


Rev
A00

Date: Friday, April 22, 2011

Sheet 78 of 109

(Blanking)

<Core Design>



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 79 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Reserved

Size

A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 80 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

UNUSED PARTS/EMI Capacitors

Size
A3

Document Number
Enrico 14 AMD

Rev
A00

Date: Friday, April 22, 2011

Sheet 81 of 109

X02

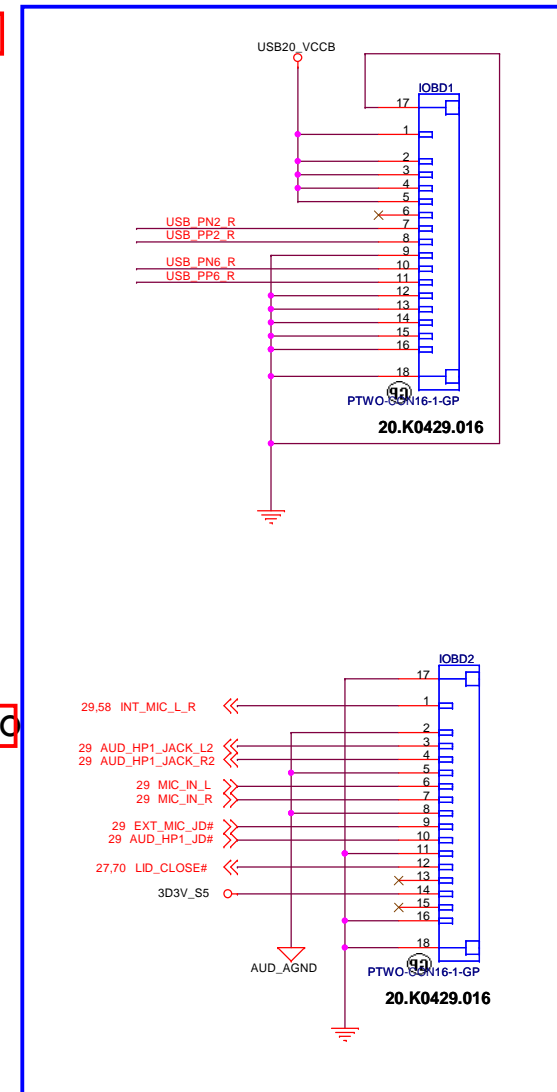
USB_PN2_R R8203 1 2 0R0603-PAD << >> USB_PN2 18
USB_PP2_R R8204 1 2 0R0603-PAD << >> USB_PP2 18

SSID = USB

X02

USB_PN6_R R8201 1 2 0R0603-PAD << >> USB_PN6 18
USB_PP6_R R8202 1 2 0R0603-PAD << >> USB_PP6 18

SSID = AUDIO



<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			
IO Board Connector			
Size A3	Document Number Enrico 14 AMD	Rev A00	
Date: Friday, April 22, 2011	Sheet 82	of 109	

SSID = VIDEO

www.chinafix.com.cn

CONFIGURATION STRAPS

ALLOW FOR PULLUP PADS FOR THESE STRAPS AND IF THESE GPIOs ARE USED, THEY MUST NOT CONFLICT DURING RESET

RECOMMENDED SETTINGS
0= DO NOT INSTALL RESISTOR
1= INSTALL 3K RESISTOR
X = DESIGN DEPENDANT
NA = NOT APPLICABLE

STRAPS	PIN	DESCRIPTION OF DEFAULT SETTINGS	RECOMMEND	PLATFORM SETTING
TX_PWRS_ENB	GPIO0	Transmitter Power Savings Enable 0: 50% Tx output swing 1: Full Tx output swing	X	1
TX_DEEMPH_EN	GPIO1	PCIE TRANSMITTER DE-EMPHASIS ENABLED 0:Tx de-emphasis disabled 1:Tx de-emphasis enabled	X	1
BIF_GEN2_EN_A	GPIO2	0:Advertises the PCIe device as 2.5GT/s capable at power on. 1:Advertises the PCIe device as 5.0GT/s capable at power on.	0	0
GPIO5_AC_BATT	GPIO5	optional input allow the system to request a fast power reduction by setting GPIO5 to low.	?	0
GPIO8_ROMSO	GPIO8	RESERVED	0	0
VGA_DIS	GPIO9	0:VGA Controller capacity enabled 1:The device won't be recognized as the system's VGA controller	0	0
ROMIDCFG[2:0]	GPIO[13:11]	BIOS_ROM_EN=1, Config[2:0] defines the ROM type BIOS_ROM_EN=0, Config[2:0] defines the primary memory aperture size	X X X	0 0 1 (256MB)
GPIO21_BB_EN	GPIO21	RESERVED	0	0
BIOS_ROM_EN	GPIO_22_ROMCSB	0:Disable external BIOS ROM device 1:Enable external BIOS ROM device	X	0
VIP_DEVICE_STRAP_EN	V2SYNC	VIP Device Strap Enable indicates to the software driver that it sense whether or not a VIP device is connected on the VIP Host interface.	X	0
RSVD	H2SYNC	RESERVED	0	0
RSVD	GENERICC	RESERVED	0	0
AUD[1]	HSYNC	AUD[1:0]:11-Audio for both DisplayPort and HDMI	X	1
AUD[0]	VSYSN		X	1

VGA1A

1 OF 7

PCI EXPRESS INTERFACE

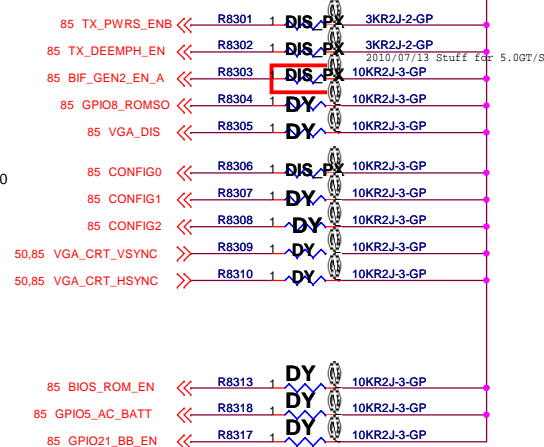
DIS_PX

71.ROBSO.M01

Colay with Seymour-XT-S3
(71.SEYMR.M01)

PIN STRAPS

2010/06/11
Need to check



JTAG SIGNAL OPTION

Signal	Normal mode	Debug mode	pilot run mode
TESTEN	"1" (PU)	"1" (PU)	"0" (PD)
JTAG_TRST#	"0" (PD)	"1" (PU)	NC
JTAG_TCK	CLK	"1" (PU)	NC
JTAG_TMS	"1" (PU)	"1" (PU)	NC

<Core Design>

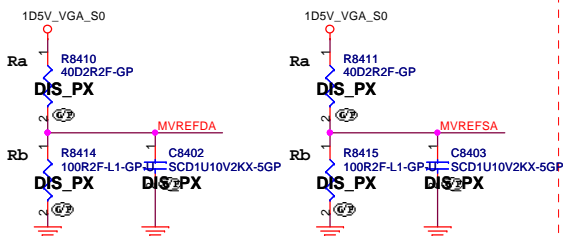
DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **GPU PEG/STRAPPING(1/5)**
Size: **A3** Document Number: **Enrico 14 AMD** Rev: **A00**
Date: Friday, April 22, 2011 Sheet: 83 of 109

SSID = VIDEO

www.chinafix.com.cn

PLACE MVREF DIVIDERS AND CAPS CLOSE TO ASIC



DDR3/GDDR3 Memory Stuff Option (ROBSON-S3/SEYMOUR-XT-S3)

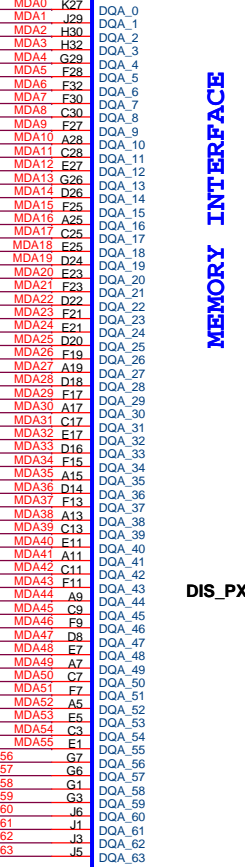
	DDR5	DDR3
MVDDQ	1.5V	1.5V/1.8V
Ra	40.2R	40.2R
Rb	100R	100R

DPC_CALR (Park/Robson-S3):
Analog calibration.
Connect DPxx_CALR to GND through a 150-Ω (1%) resistor.

**This basic topology should be used for DRAM_RST for DDR3/GDDR3/GDDR5. These Capacitors and Resistor values are an example only. The Series R and || Cap values will depend on the DRAM load and will have to be calculated for different Memory, DRAM Load and board to pass Reset Signal Spec.

Designator	For SEYMOUR	For Robson
R_MEM_1	10R	10R
R_MEM_2	50R	50R
R_MEM_3	5K	5K
C_MEM	120pF	120pF

Place all these components very close to GPU (Within 25mm) and keep all component close to each Other (within 5mm) except R_MEM_2



71.ROBSO.M01

Colay with Seymour-XT-S3
(71.SEYMR.M01)

2010/07/06
Schematics check list:
A pull-down resistor is required.

<Core Design>

DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: **GPU Memory(2/5)**

Size: **A3** Document Number: **Enrico 14 AMD** Rev: **A00**

Date: Friday, April 22, 2011 Sheet 84 of 109

For normal GPU operation, these signals can be left floating (do not populate the capacitors and resistors).

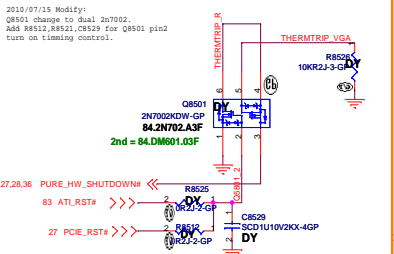
Memory ID Table

DVPPDATA[0:3]	Description
0000	DDR3 SAMSUNG-K4W1G1646G-BC11 (900MHz) 64M*16
0001	DDR3 Hynix-H5T1G63DFR-11C (900MHz) 64M*16
0010	DDR3 SAMSUNG K4W2G1646C-HC11 (900MHz) 128M*16
0011	DDR3 Hynix-H5T2G63BFR-11C (900MHz) 128M*16

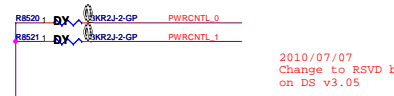
DVPPDATA[0:3] Default: Internal Pull down

For Seymour,
DPC_PVDD is DPC_VDD18
DPC_PVSS and all DPC_VSSR are DP_VSSR

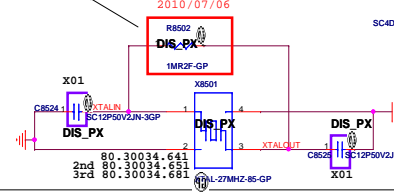
X02



gpio_6, gpio_15, PWRMNT_0, gpio_14, SSIN, gpio_20, PWRMNT_1
Voltage control signals for the core (VDDC and VDDCI).
At Reset, these signals will be inputs with weak internal pull-down outputs.
VBIOS can define all voltage control signals to be either 3.3V or open drain outputs (all signals must be the same type). The output state (high/low) of these signals is programmable for each PowerPlay state.



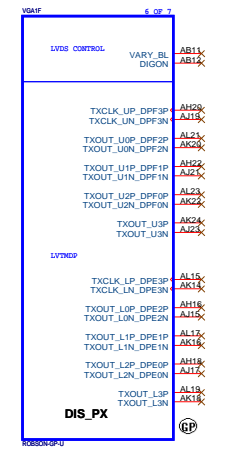
2010/07/06
Schematics check list:
A 1-M ohm resistor must be connected between XTALIN and XTALOUT when a crystal is used.



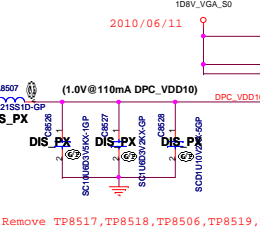
SSID = VIDEO

www.chinafix.com.cn

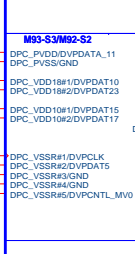
LVDS Interface



MEM_ID Control



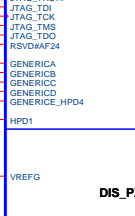
DVO



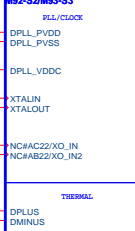
I2C



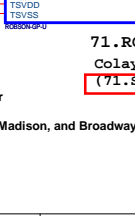
DIS_PX



DIS_PX

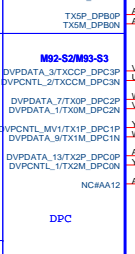


DIS_PX

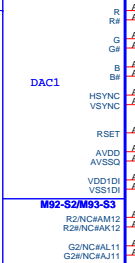


71.ROBSO.M01
Colay with Seymour-XT-53
(71.SEYMR.M01)

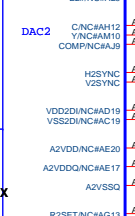
DVO



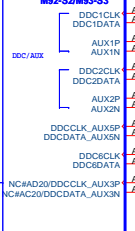
I2C



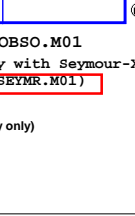
DIS_PX



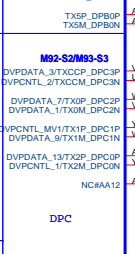
DIS_PX



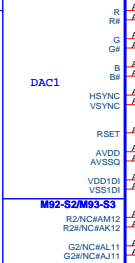
DIS_PX



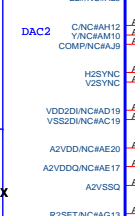
DVO



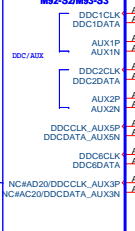
I2C



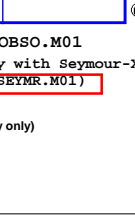
DIS_PX



DIS_PX



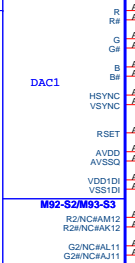
DIS_PX



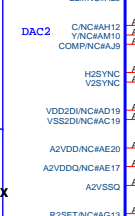
DVO



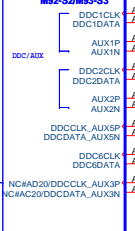
I2C



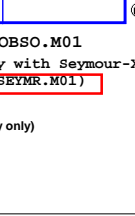
DIS_PX



DIS_PX



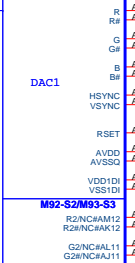
DIS_PX



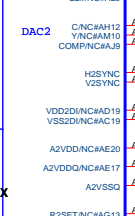
DVO



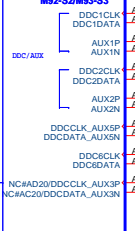
I2C



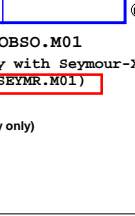
DIS_PX



DIS_PX



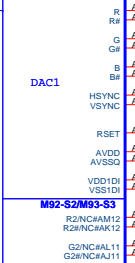
DIS_PX



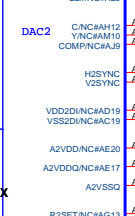
DVO



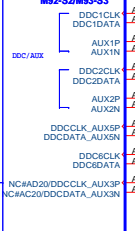
I2C



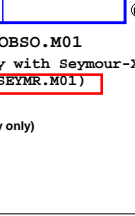
DIS_PX



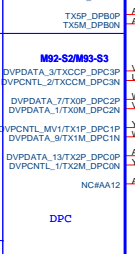
DIS_PX



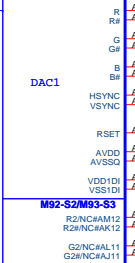
DIS_PX



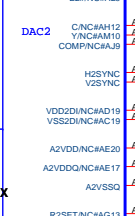
DVO



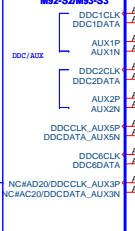
I2C



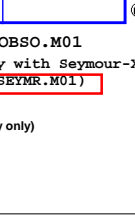
DIS_PX



DIS_PX



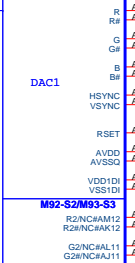
DIS_PX



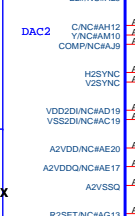
DVO



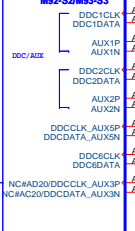
I2C



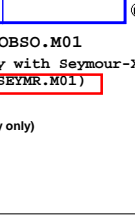
DIS_PX



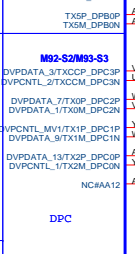
DIS_PX



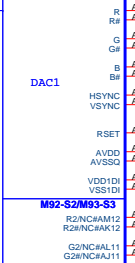
DIS_PX



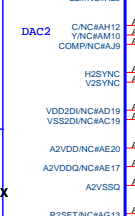
DVO



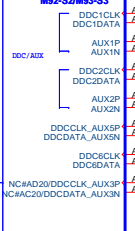
I2C



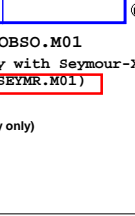
DIS_PX



DIS_PX



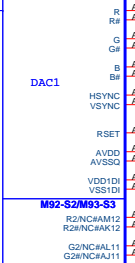
DIS_PX



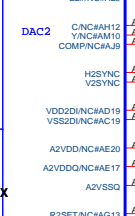
DVO



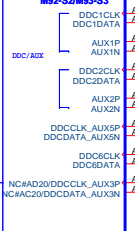
I2C



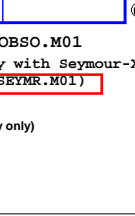
DIS_PX



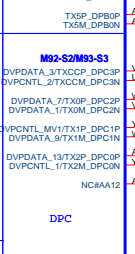
DIS_PX



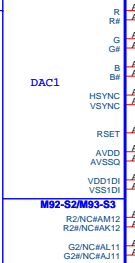
DIS_PX



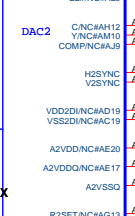
DVO



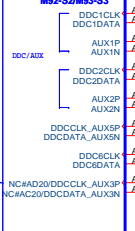
I2C



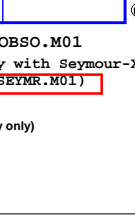
DIS_PX



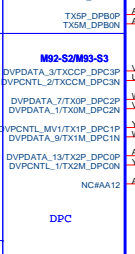
DIS_PX



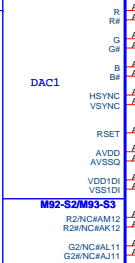
DIS_PX



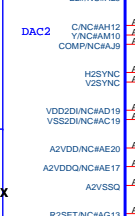
DVO



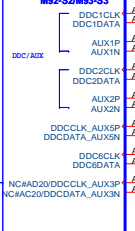
I2C



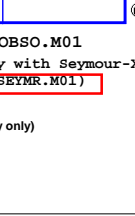
DIS_PX



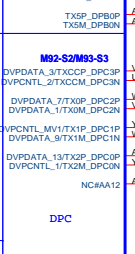
DIS_PX



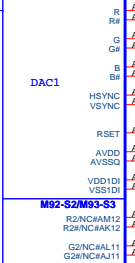
DIS_PX



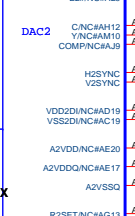
DVO



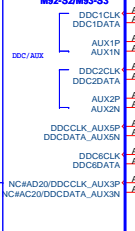
I2C



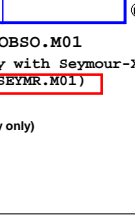
DIS_PX



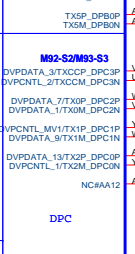
DIS_PX



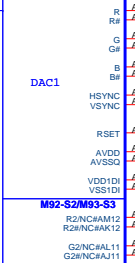
DIS_PX



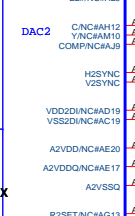
DVO



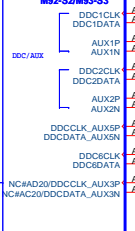
I2C



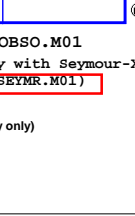
DIS_PX



DIS_PX



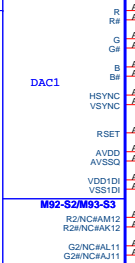
DIS_PX



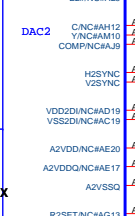
DVO



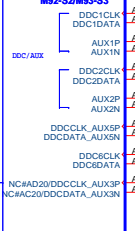
I2C



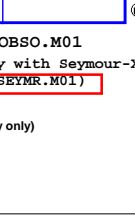
DIS_PX



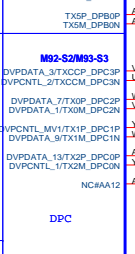
DIS_PX



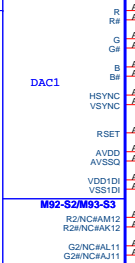
DIS_PX



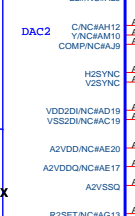
DVO



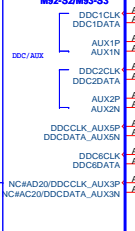
I2C



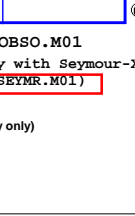
DIS_PX



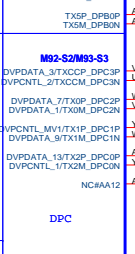
DIS_PX



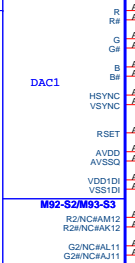
DIS_PX



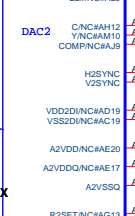
DVO



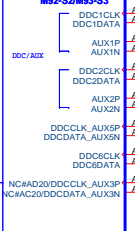
I2C



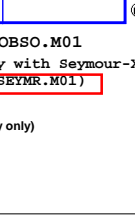
DIS_PX



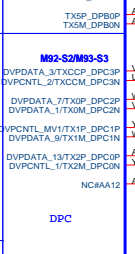
DIS_PX



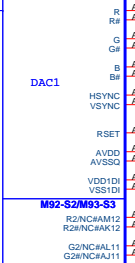
DIS_PX



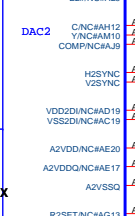
DVO



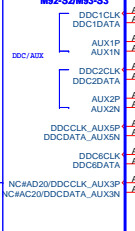
I2C



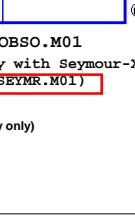
DIS_PX



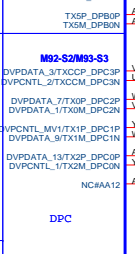
DIS_PX



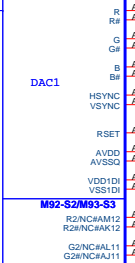
DIS_PX



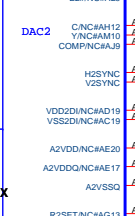
DVO



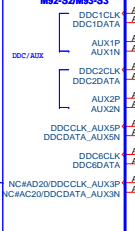
I2C



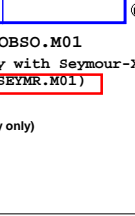
DIS_PX



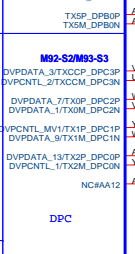
DIS_PX



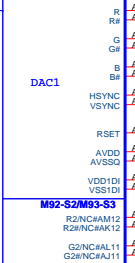
DIS_PX



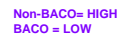
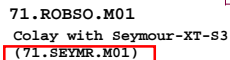
DVO



I2C



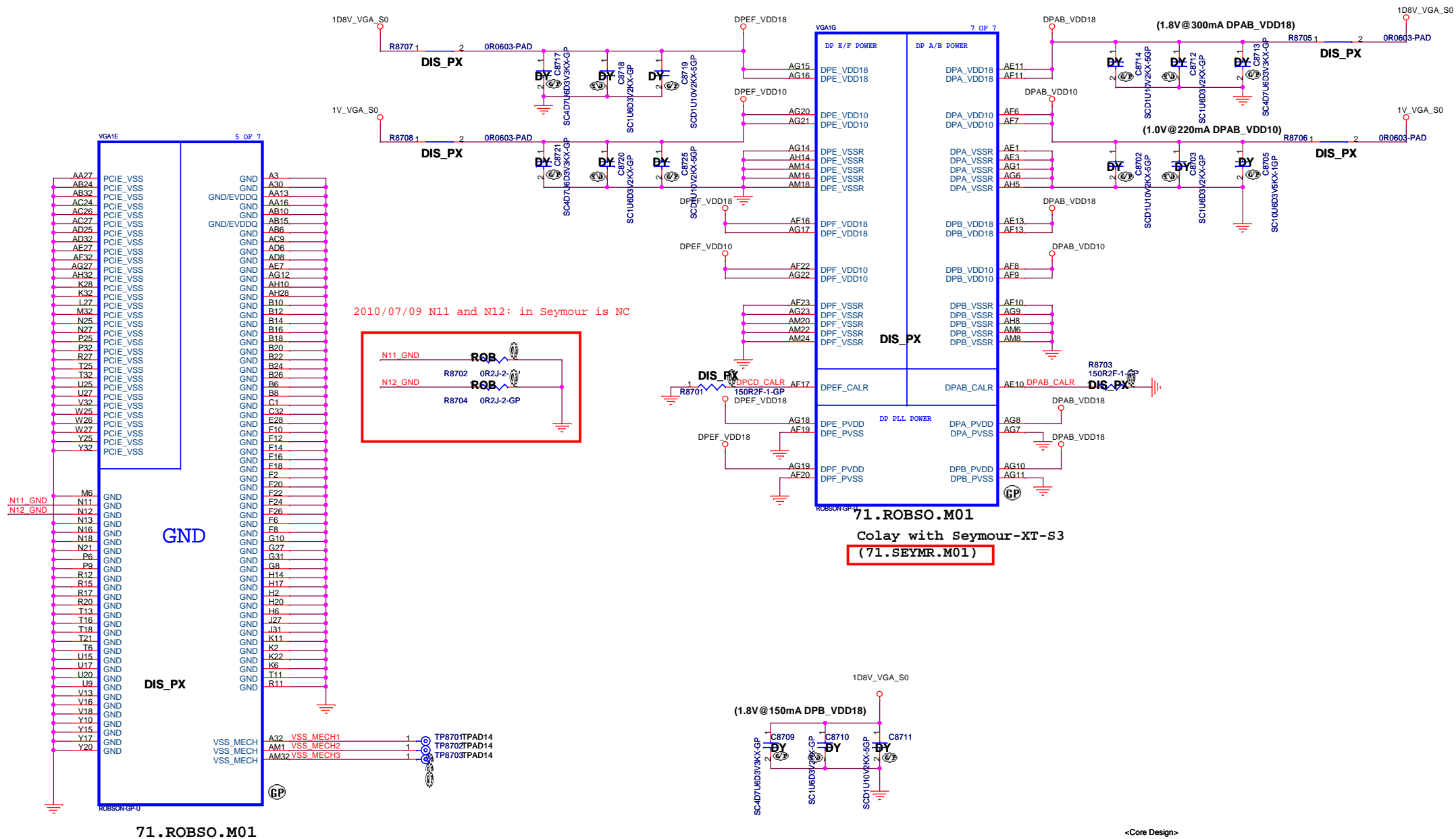
DIS_PX



PX_EN# = High, BIF_VDDC = 1V_VGA_S0
PX_EN## = High, BIF_VDDC = VGA_CORE

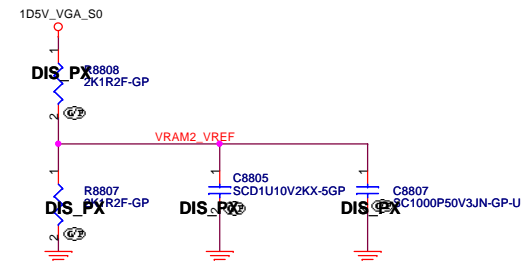
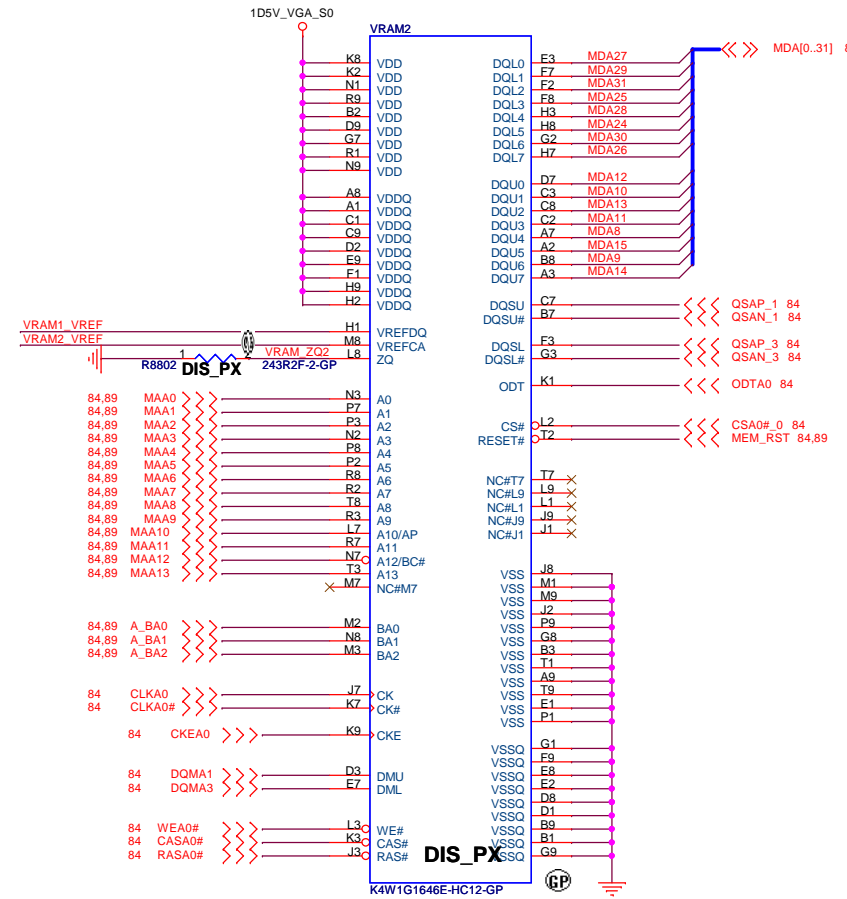
SSID = VIDEO

www.chinafix.com.cn



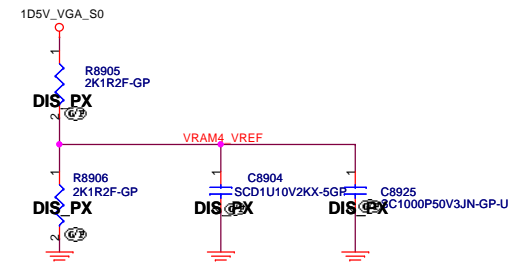
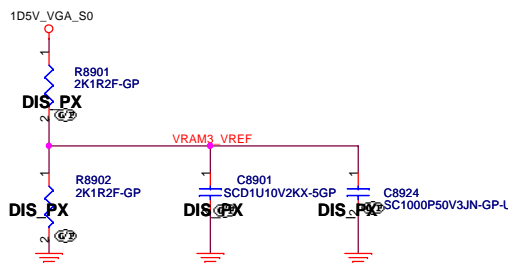
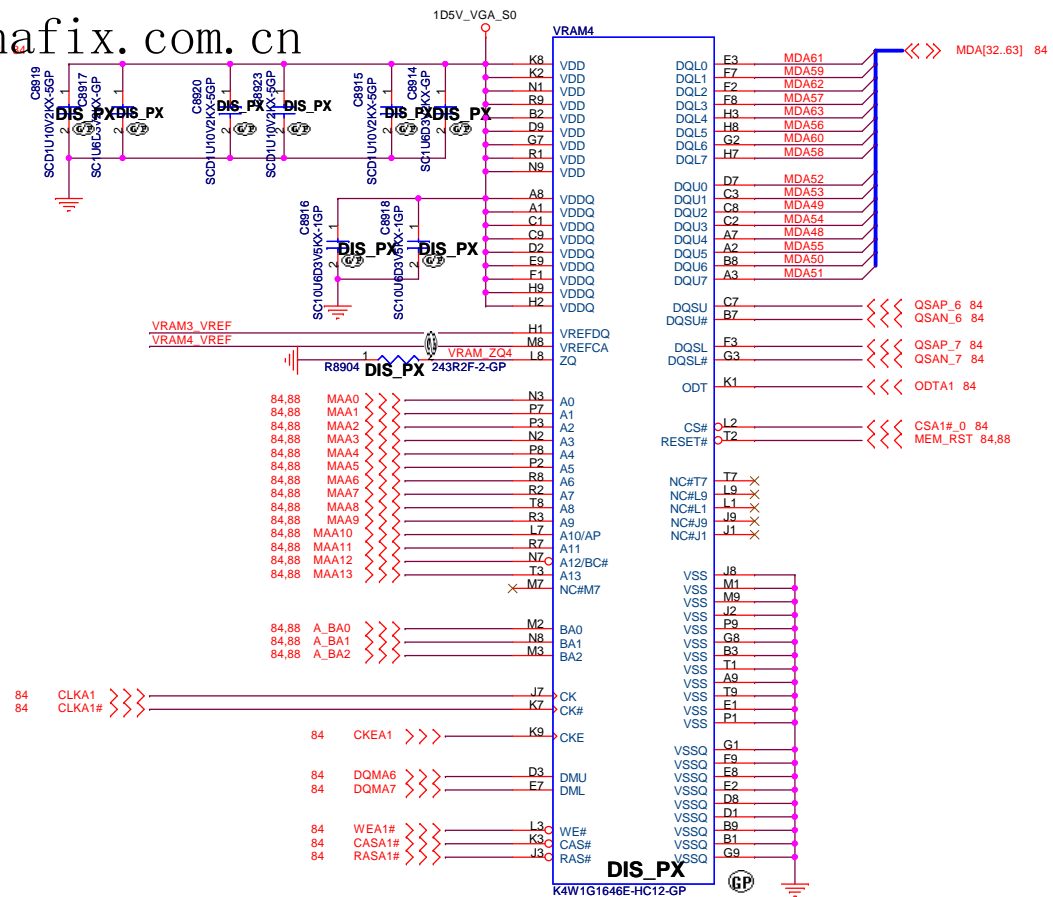
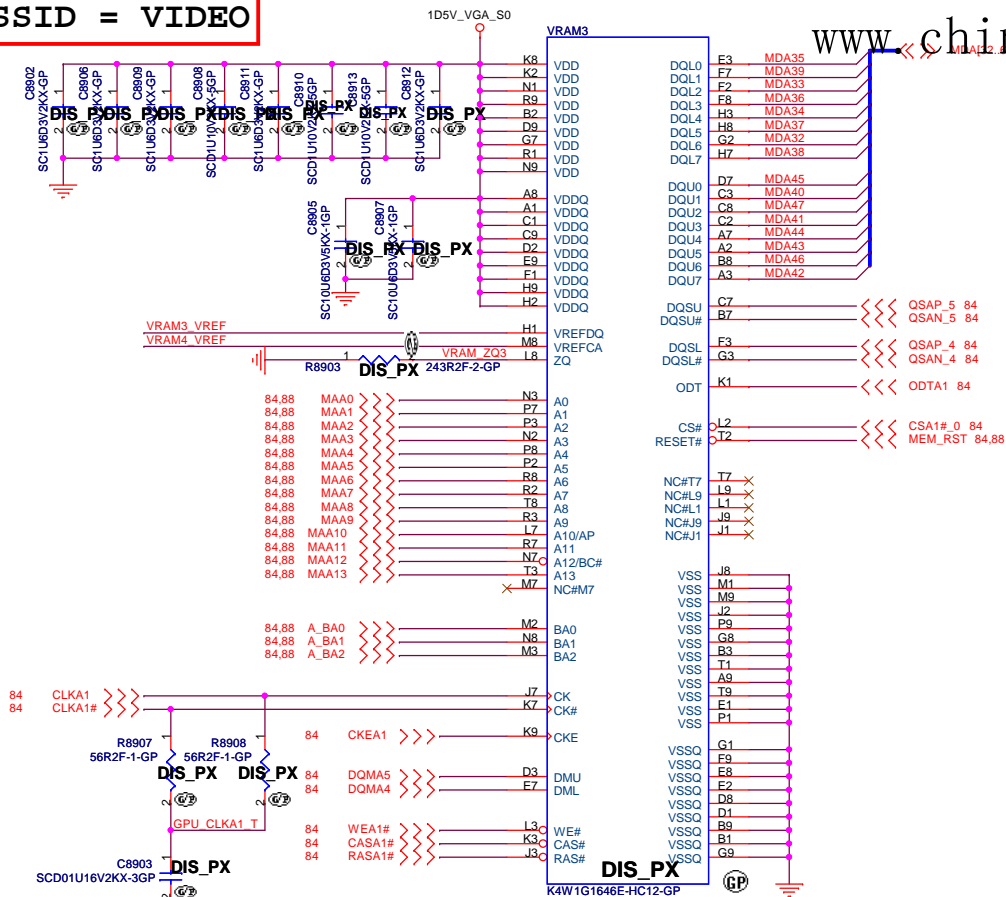
<Core Design>

www.chinafix.com.cn



SSID = VIDEO

www.chinafix.com.cn




<Core Design>

DELL Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title: GPU-VRAM3,4 (2/4)
Size: A3 Document Number: Enrico 14 AMD Rev: A00
Date: Friday, April 22, 2011 Sheet: 89 of 109

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title


GPU-VRAM5,6 (3/4)

Size	Document Number	Rev
A3	Enrico 14 AMD	A00

Date: Friday, April 22, 2011	Sheet 90 of 109
------------------------------	-----------------

(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

GPU-VRAM7,8 (4/4)

Size

A3

Document Number

Enrico 14 AMD

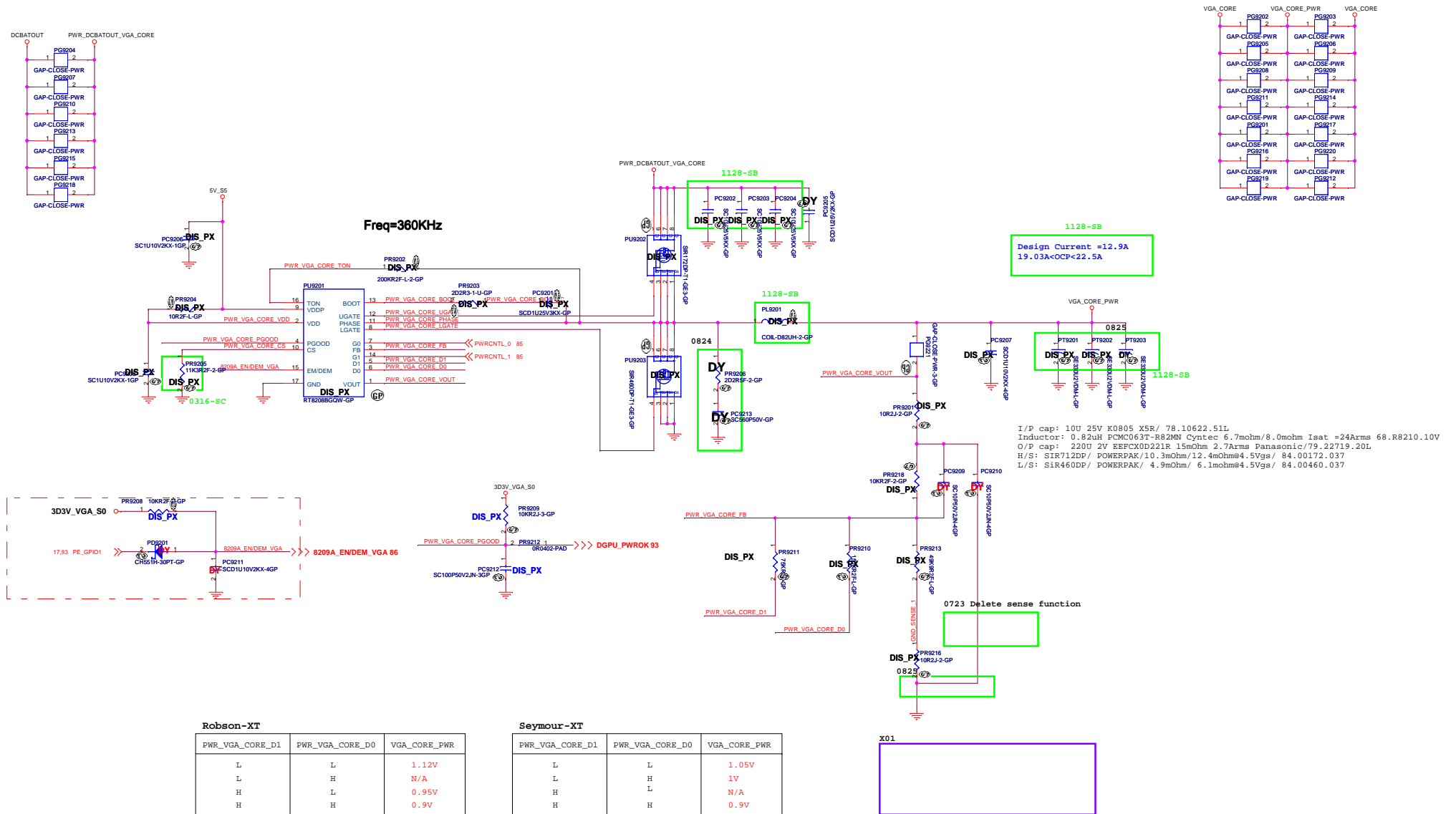
Rev

A00

Date: Friday, April 22, 2011

Sheet 91 of 109

```
SSID = PWR.Plane.Regulator_VGACORE
```



Robson-XI		
PWR_VGA_CORE_D1	PWR_VGA_CORE_D0	VGA_CORE_PWR
L	L	1.12V
L	H	N/A
H	L	0.95V
H	H	0.9V

$$V_{out} = 0.75V * (R1 + R2) / R2$$

For ROBSON

PR9210=44.2K(64.44225.6DL)

PR9211=150K(64.15035.6DL)

Seymour-XT		
PWR_VGA_CORE_D1	PWR_VGA_CORE_D0	VGA_CORE_PWR
L	L	1.05V
L	H	1V
H	L	N/A
H	H	0.9V

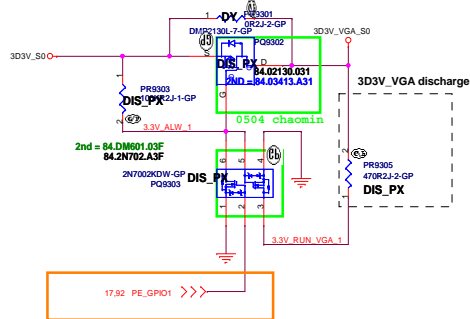
$$V_{out} = 0.75V * (R1 + R2) / R2$$

For Seymour

PR9210=150K(64.15035.6DL)

PR9211=75K(64.75025.6DL)

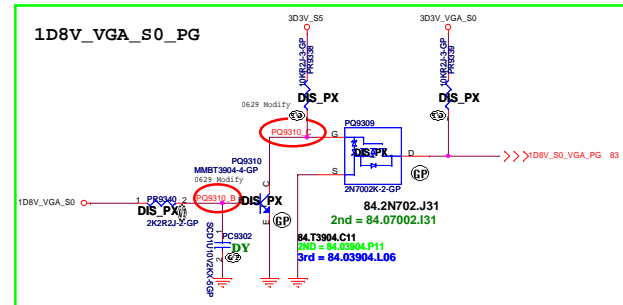
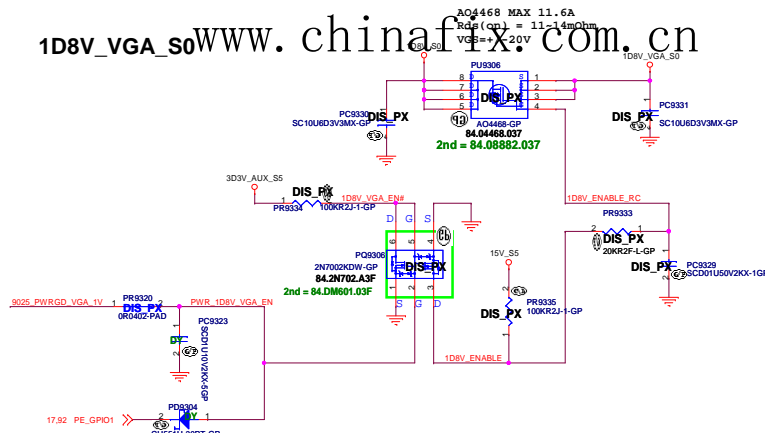
+3VS to 3.3V_DELAY Transfer



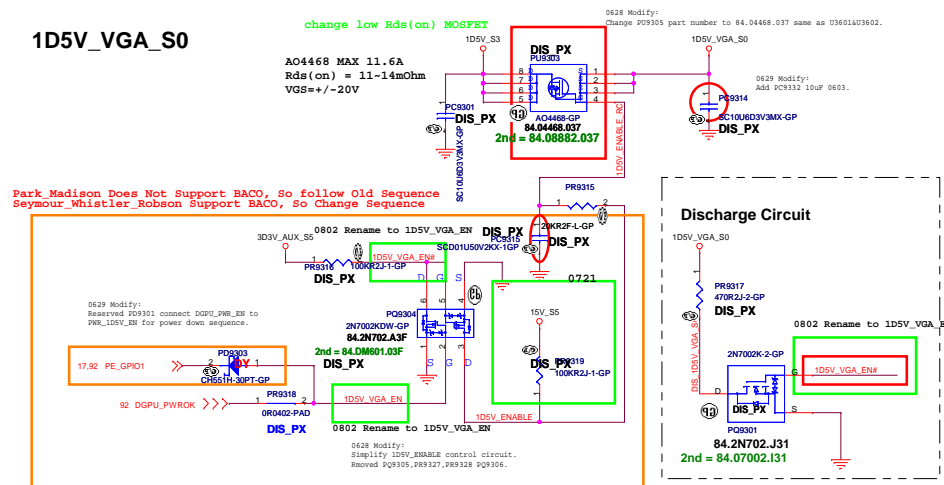
Different To Intel, AMD Is High Active

	PE_GPIO0	PE_GPIO1
dGPU mode	H	H
IGPU	L	L
IGPU with BACO	H	H

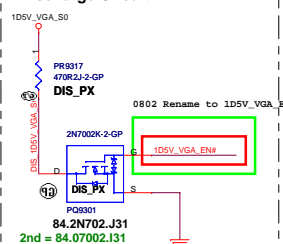
1D8V_VGA_S0



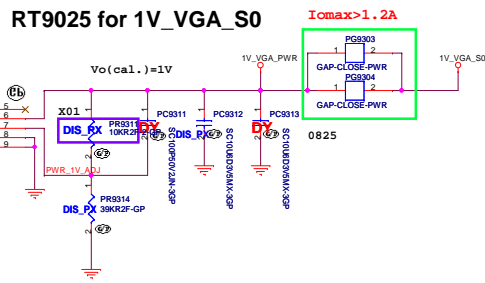
1D5V_VGA_S0



Discharge Circuit



RT9025 for 1V_VGA_S0




<Core Design>

SSID = VIDEO

www.chinafix.com.cn

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

LVDS Switch

Size

Document Number

Rev

Enrico 14 AMD

A00

Date: Friday, April 22, 2011


Sheet 94 of 109

(Blanking)



(Blanking)

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

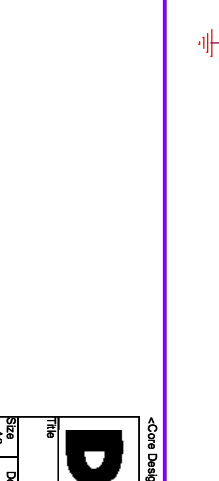
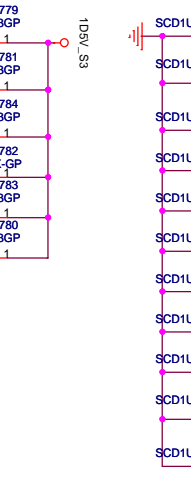
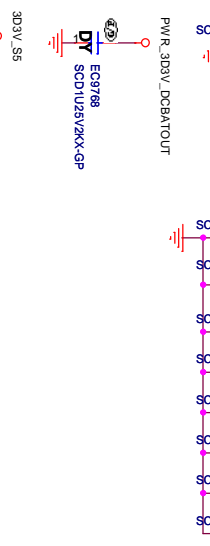
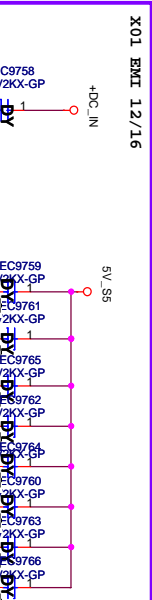
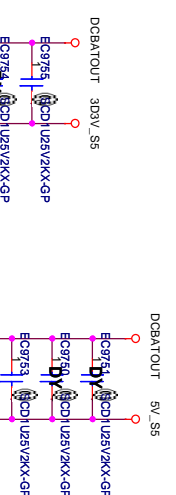
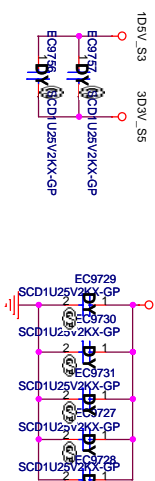
Size
A3

Document Number
Enrico 14 AMD

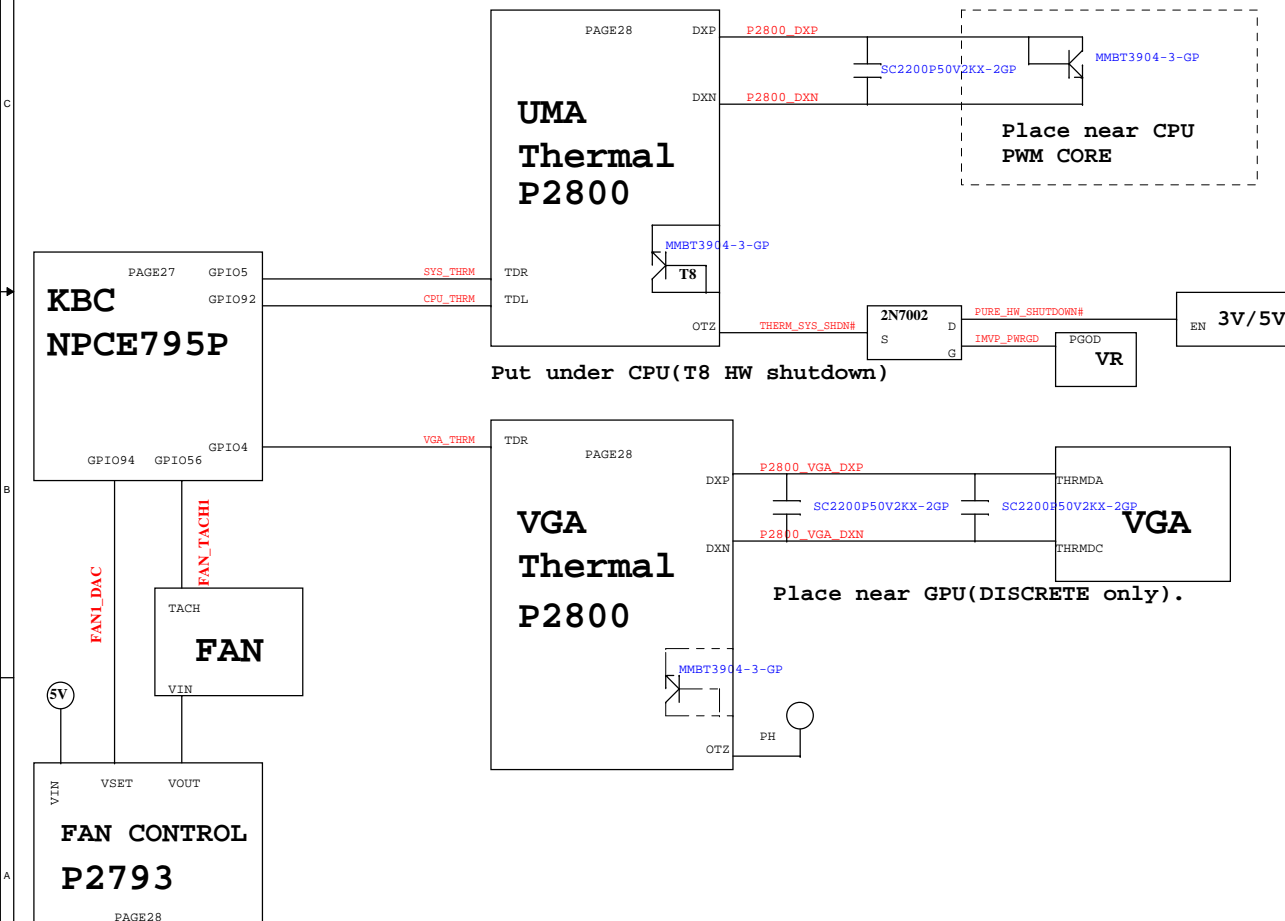
Rev
A00

Date: Friday, April 22, 2011

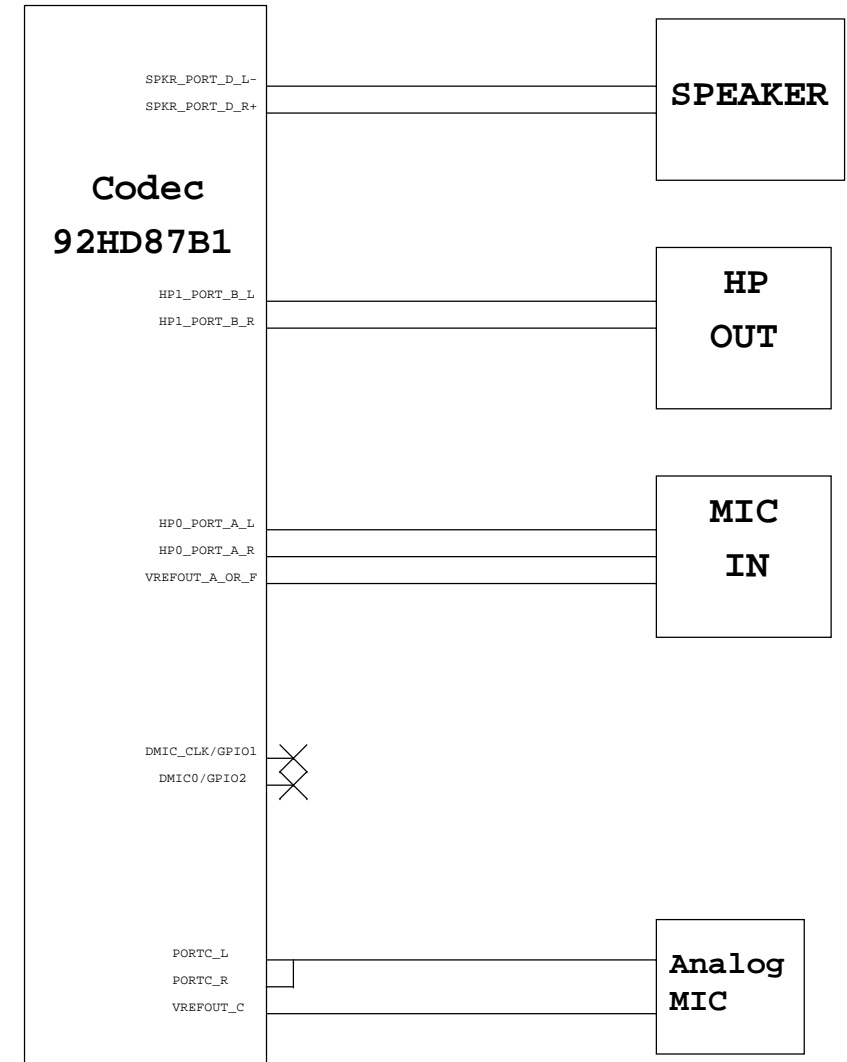
Sheet 96 of 109



Thermal Block Diagram



Audio Block Diagram



<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

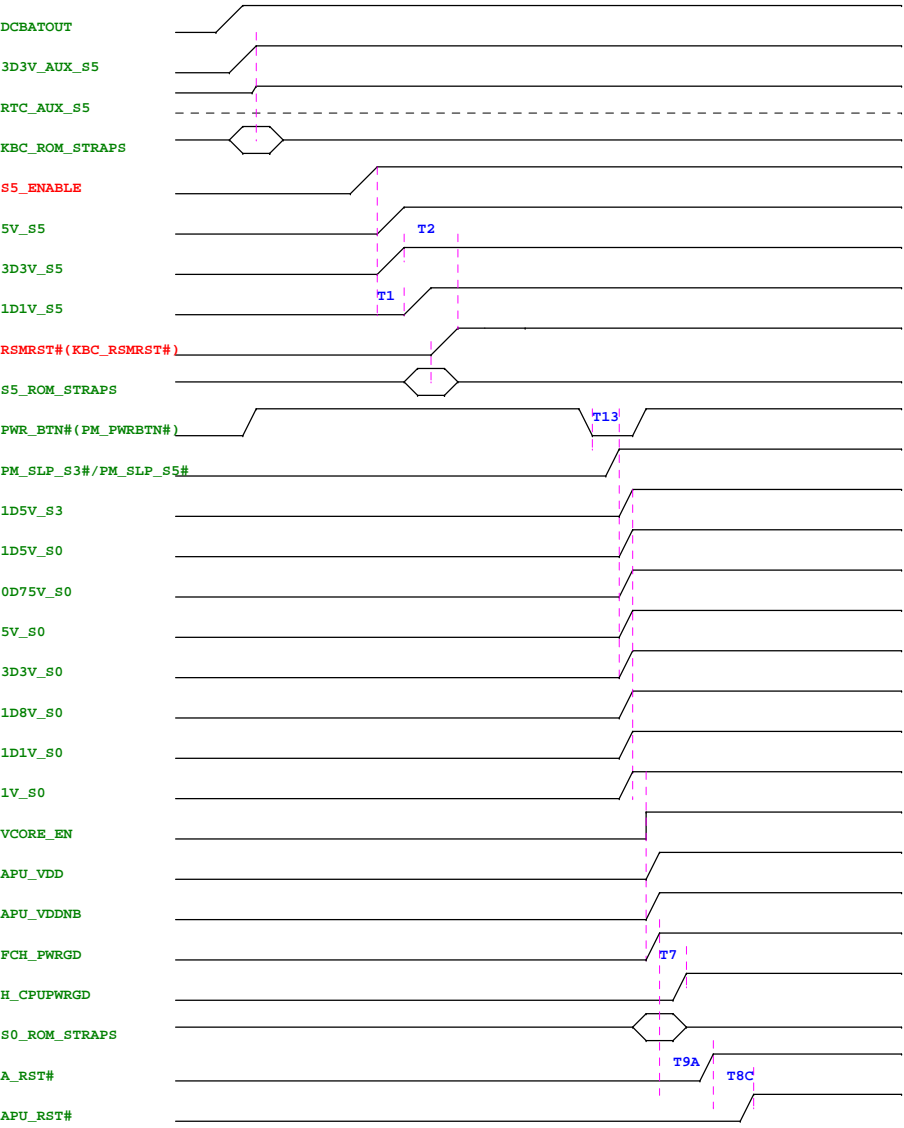
Title **THERMAL/AUDIO BLOCK DIAGRAM**

Size A3 Document Number **Enrico 14 AMD** Rev **A00**

Date: Friday, April 22, 2011 Sheet 98 of 109

POWER SEQUENCE

www.chinafix.com.cn



	Min	Max	Description
T1	-	-	+3.3V_S5 to +1.1V_S5
T2	10 ms	-	+3.3V_S5 to resume reset (RSMRST#).
T7	98 ms	150 ms	FCH PWRGOOD assertion to LDT_PG assertion delay.
T8C	1.0 ms	2.3 ms	PCIRST# to LDT_RST#.
T9A	101 ms	113 ms	FCH PWR_GOOD to A_RST#.
T13	8 ns	-	PwrButton to SLP_S3# / SLP_S5# de-assertion

<Core Design>

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

POWER SEQUENCE

Size
A3

Document Number
Enrico 14 AMD

Rev
A00

Date: Friday, April 22, 2011

Sheet 99 of 109

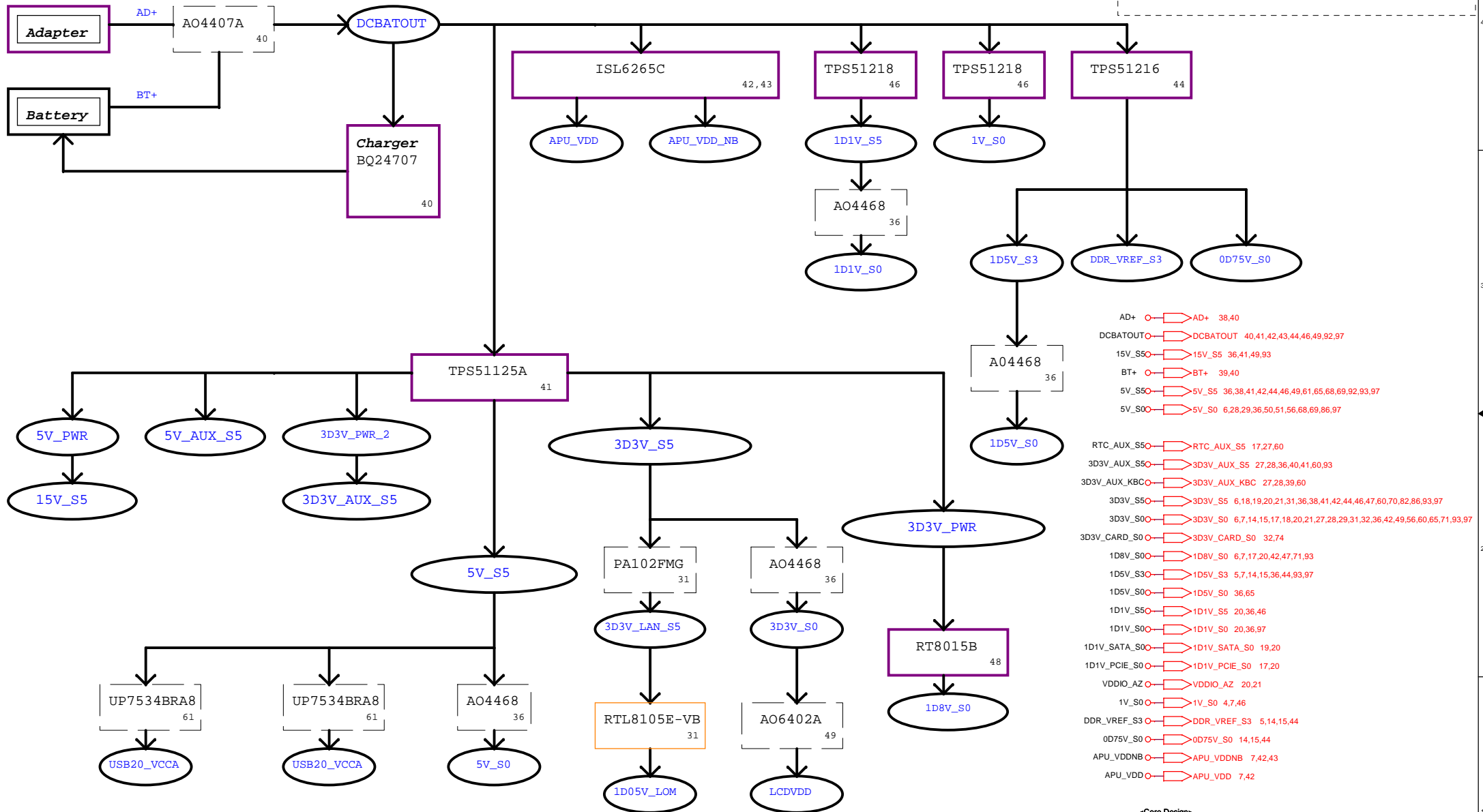
Power Delivery Block Diagram

Power Shape

Regulator

LDO

Switch



<Core Design>

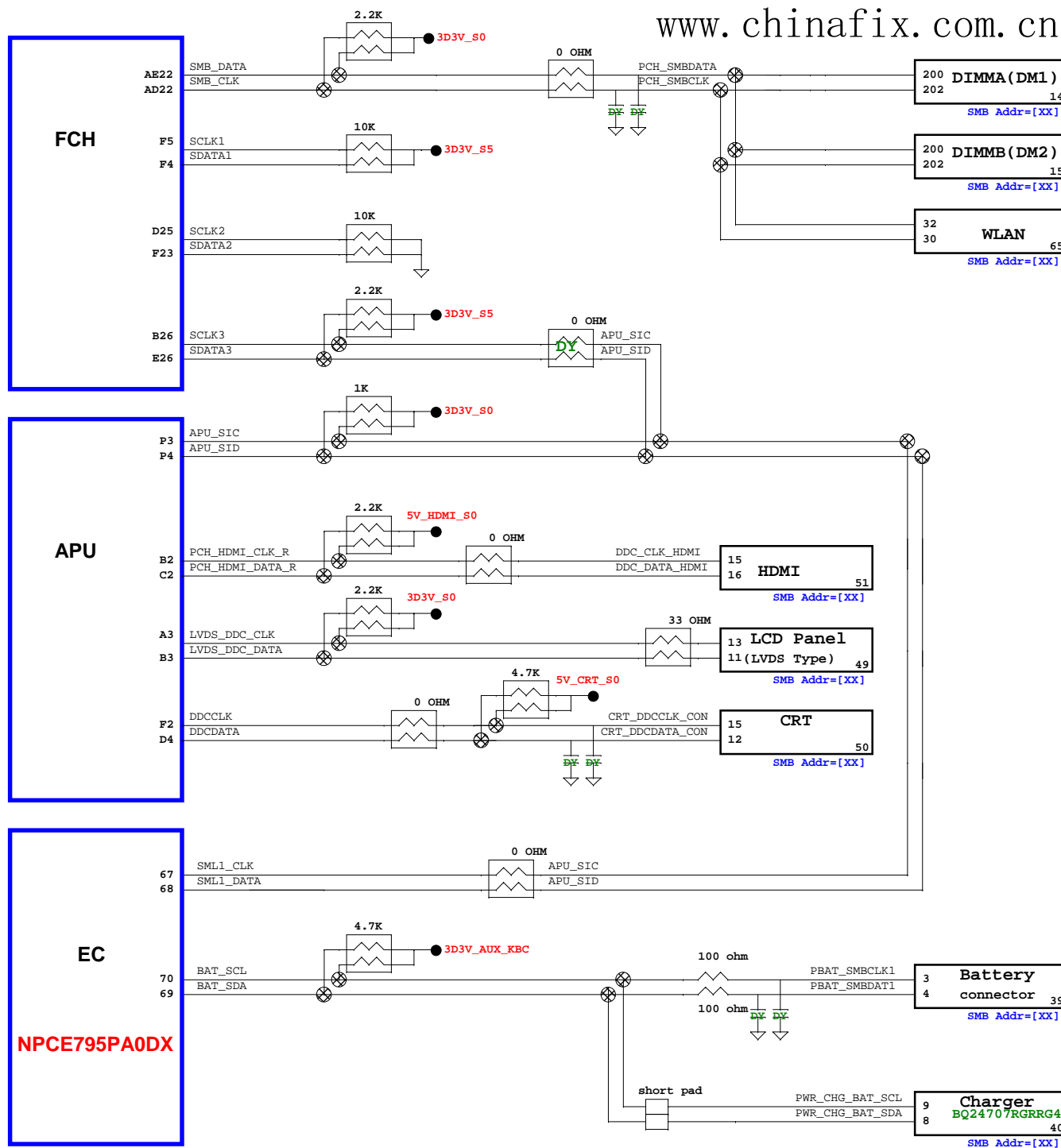


Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **Power Block Diagram**

Size A3 Document Number **Enrico 14 AMD** Rev **A00**

Date: Friday, April 22, 2011 Sheet 100 of 109



<Core Design>



Title			Rev
SMBUS BLOCK DIAGRAM			
Size	Document Number	Rev	
A2		A00	
Date:	Friday, April 22, 2011	Sheet	101 of 108

Change notes -

www.chinafix.com.cn

DATE	VERSION	DATE	Page	Modify List	OWNER
	X01	9/23	50	Delete F5001, Share Fuse with HDMI	EE
			71	DUMMY Debug Port DB1,RN7102, R7107	EE
			27	Change R2724 value to 20K, X01 Version	EE
			39,56	Change BATT1,ODD1,HDD1 Connector	ME
			27	Add C2722 0.1uF between Q2703 G&S pin for fixed leakage voltage to 3D3V_AUX_KBC under DC mode.	EE
			27	Add Q2706 2N7002 to avoid leakage loop from 3D3V_S5 to 3D3V_AUX_KBC issue when 10mW latched fail timing. Un-stuff C2713 to follow the standard schematics.	EE
			28	Change U2801, U2803 to 74.02800.A71	EE
	X01	9/29	61	Change U6102 to 74.07534.079	EE
			50	Change L5001,L5002,L5003 bead to 0402 size:68.00217.991	EE
			38,59,69,82	Change DCIN1,RJ45,TPAD1,IOBD1 Connector	ME
			82	Change IOBD1 Pin define	EE
	X01	10/13	6	Dummy APU_SIC, APU_SID level shifter, pop R644,R645	EE
			6	Add level shifter for H_Thermtrip#	EE
			36	DUMMY Q3601,R3622 for reserved	EE
			28	Change R2816,R2822 to 107KR,R2817 ,R2821to 226KR for new version P2800 chip	EE
			39	Delete R3901 for double pull high	EE
			49	Delete R4902 for double resister	EE
			27	Change PURE_HW_SHUTDOWN#(R2705) power rail to 3D3V_AUX_KBC	EE
	X01	10/20	92	Change PR9213 to 75K, PR9211 to 150K for VGA_CORE (Robson-LP)Output	Power
			27,36	Add GPIO97 for IMVP_PWRGD control ,Change D3605.2 to 1V_S0_PWRGD,Delete D3606, Change D3603.1 to VRM_VDD_PWRGD for sequence	EE
			86	Modify 1D5V_VGA_PWRGD to 1D5V_VGA_PWOK	EE
			31	Dummy R3101,R3102,Q3101,R3108 for leakage	EE
			36,47	Change R3607 to 10K,C3605 to 15n,PR4711 to 0ohm, PC4710 DY, C3610 DY, R3633 to 33K, C3615 to 33n,R3604 to33K for sequence	EE

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Change notes

Size
A3

Document Number

Enrico 14 AMD

Rev


A00

Date: Friday, April 22, 2011

Sheet 102 of 109

DATE	VERSION	DATE	Page	Modify List	OWNER
	X01	10/20	20	Change R2004 to 0603 size for current tolerance	EE
			93	Change PR9311 to 10K for 1V_VGA Voltage	Power
			61,65	Add C6105,C6106,C6509,C6510 to 6.8p for solve SIV USB fail	EE
			27	Change RN2705 8P4R to 4P2R and R2715, RN2705 DY	EE
			40	Add PR4061 PR4062 100KR, empty other parts for fine tune sequence for leakage	EE
		10/27	85,17	Modify C8524,C8525=12p, C1715,C1717=18p for crystal frequence match	EE
			68	Add LED for WLAN	EE
			14	Change RN1401 to 22 ohm and pop C1423,C1424 for solved SMBus SIV Fail	EE
		11/10	38	Change DCIN CONN pin define	EE
			31	Solved leakage issue follow DV15	EE
			68	Modify Wireless LED schematic	EE
			85	Change L8502,L8503,L8507,L8505,L8513 to short pad for power	EE
			17,31	Modify C1720=15p, C3102=15p for crystal frequence match	EE
			28	Add G709 for thermal solution	EE
			68	Delete RN6802,RN6801	EE
			83~89	Change GPU from Robson LP to Seymour XT	EE
		11/17	46	DY 1V to merge 1D1V	EE
			27	Add two model ID for config	EE
			58	Delete MIC2 and move mic1 to IO Board	EE
			92	Update Seymour and Robson power plan setting(PR9219,PR9210,PR9214,PR9211)	EE
			87	Pop R8421 for check list request	EE
			68	Modify power LED schematic and charger LEDs	EE
				Merge with power schematic	Power
			27	Add LID_CLOSE# pull high	EE

<Core Design>

			Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title Change notes					
Size A3	Document Number Enrico 14 AMD				Rev A00
Date: Friday, April 22, 2011		Sheet 103		of 109	

Change notes -

www.chinafix.com.cn

DATE	VERSION	DATE	Page	Modify List	OWNER
			50,51	Modift CRT,HDMI share fuse schematic	EE
	X01	11/24	31	Change L3101 to slime type and add R3101 GIGA mark for 10/100 internal PU	EE
			27	Change R2726, R2710 to F tolerance for accurate level to KBC	EE
			27,65,68	Change WLAN LED design to meet on/off behavior SPEC	EE
			27	Change RTC_POWER from RTC_AUX_S5 to 3D3V_AUX_S5 for saving RCT power and no influence on PSL	EE
			6	Pull up LTDP0_HPD to 5V from AMD SCL 1.04	EE
			6	Change RN634 to 2K2R follow AMD SCL 1.03	EE
			6	Add level shifter for LVDS SMBus follow AMD SCL 1.04	EE
			59	Rename part reference for Lan ESD	EMI
			31	Set R3101 BOM option for 8105E DY	EE
			31	Add RTC sense schematic	EE
		12/2	27	Reserved R2778 for EC power switch logic circuit.	EE
			27	Set R2769 empty, Duplicated function in page 40.	EE
			28	Reserve R2861 for hysteresis	EE
			36	Reserve C3633 for power up sequence tunning	EE
			49	Modify TP4906,TP4907 to AFTP	EE
			17,31	Change 25MHZ, 32.768K to small size by source recommand	Sourcer
			2	Modify Block Diagram	EE
			36	Change U3606 P/N	EE
			59	Modify Transformer schenatic from GIGA to 10/100 for latest config	EE
			6	Remove level shifter for LVDS SMBus(AMD confirm)	EE
			40	Reserve snuber 2.2ohm+560p for EMI solution	EMI
			50	Change L5001,L5002 and L5003 from 220hm to 30ohm for EMI Solution	EMI
			50	Change 2N7002E to 2N7002K for EOL	Sourcer

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title Change notes		
Size A3	Document Number Enrico 14 AMD	Rev A00
Date: Friday, April 22, 2011		
Sheet 104	of	109

Change notes -

www.chinafix.com.cn

DATE	VERSION	DATE	Page	Modify List	OWNER
			27	Modify R2776 to 64.9K	EE
			59	Modify R5903,R5904 to 0603 size	EE
			27	Change R2739 to 1% tolerance	EE
			6	Change RN634 form 2.2KR to 1KR by AMD suggestion	EE
			65,68	Change WLAN LED indicator for reserve EC and module circuit	EE
			60	Change Q6001.G from +RTC_VCC to RTC_PWR	EE
			15	Reserve R1531 and R1532 69.8R for memory glitch issue	EE
			36,46	Stuff 0R and change to open-gap for merge power rail	EE
			47	Change PQ4701 to ESD 2KV for Vendor EOL	EE
			38,39	PD3801 change to P6SMBJ58A,PD3902 change to SMF18AT1G	Power
			40	Add PQ4007 PR4012 and PR4037 to improve AC_IN# delay issue	Power
			All	Change reference from PTCxx to PTxx for meet SMT Process	Power
			41,42,44,46,92	Change PC4111,PC4116,PC4117,PC4204,PC4223,PC4203,PC4301,PC4302,PC4304,PC4403,PC4404,PC4405,PC4602,PC4603,PC4604,PC4613,PC4614,PC4618,PC9202,PC9203,PC9204 to 10u 0805 size	Power
			92	PR9205 change to 13 Kohm for OCP setting	Power
			6	Remove SIC,SID level shifter	EE
	12/7		36	Reserve 1V_S0_PWRGD link for 1V_S0 power rail	EE
			38	Change PD3801: 83.P6SMB.DAG(YS) change to 83.P6SBM.DAG(CHENMKO).	Power
			86	Change U8601.U8603,U8604,U8606 pin G to 5v_S0	EE
			28	Remove R2822,R2821,C2819 and NC U2803 OTZ pin	EE
			36	Dummy C3609	EE
			49	Change R4903,R4904 to 0603 size	EE
			17	Add RTC detect pin on REQ1#_GPIO40	EE
			61,65	Move C6105,C6106,C6509,C6510 to Connector side	EE
			61	Pop TC6102 and DY on IO Board side	EE

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Change notes			
Title			
Size	Document Number		Rev
A3	Enrico 14 AMD		A00
Date:	Friday, April 22, 2011	Sheet	105 of 109

Change notes -

www.chinafix.com.cn

DATE	VERSION	DATE	Page	Modify List	OWNER
			71	Pop DB1,RN7102,R7107 for debug	EE
			74	DY EC7401,EC7403 for reserve	EE
			36,46	Add PC4621 and PT4603 1V_PWR and change 1V_S0 to 1V_PWR	EE
			14,59	Rename C59011 to C5901 and Change TC4101 to 79.22719.20L	EE
			46	Dummy 1V power generator foe back up solution	EE
			40	Add PR4063,PC4025 for EMI Snaber solution	EMC
		12/7_1	17	Reserve damping resistor R1766 for crystal drive level adjustment	EE
			65	Reserve BT_ACT for future module extension	EE
			69	Change KB connector	EE
		12/8	69	Add Caps led schematic and change AD_IA_HW2 to GPIO50, PCIE_RST# to GPIO36, CAP_LED change to GPIO30	EE
		12/10	27	Add R2780 and DY R2732,Q2702 for EC "PROCHOT_EC" pin from PP to OD type	EE
		12/13	68,82	Change IOBD2 and PWBTN1 pin define	EE
			38,40,41	PC3806 PC4006 PC4008 PC4110 and PC4114 change to 10uF 25V 0805 size (78.10622.51L)	Power
			28	Change U2801,U2803 to B version(74.02800.B71)	EE
			97	Add EMI Solution	EMI
		12/14	40	Change PC4004 and PC4024 from 1uF to 0.1uF (78.10424.2BL)	Power
			28	DY R2816,R2817,C2831 for set ADJ floating	EE
			61	DY TC6102 for reserve on IO board	EE
		12/15	82	Change IOBD2 pin define and connector	EE, ME
			20	Chnage R2004 to 0402 size	EE
			17	Change R1766 location and change to 1KR for Put Rd at chip output side and suppress amplitude.	EE
		12/17	6,65	Swap RN605,TR6501 for Layout	EE
			97	Add EMI Solution	EMI
			36	Change C3615 tolerance from 16V to 25V for component derating high voltage tolerance	EE

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Change notes			
Title			
Size	Document Number	Rev	
A3	Enrico 14 AMD	A00	
Date:	Friday, April 22, 2011	Sheet	106 of 109

Change notes -

www.chinafix.com.cn

DATE	VERSION	DATE	Page	Modify List	OWNER
			36	Delete R2779 for LID_Close# double pull high	EE
		12/21	59	Change C5904 to 0.01u from vendor recommend	EE
			50	Modify CRT Hsync & Vsync level shift follow DV15	EE
			46	Modify 1V_S0 Schematic	EE
		12/21_1	42	DY PR4214,PR4402 for pull up on R3624	EE
		12/22	61	DY C6104,C6108	EE
		12/22_1	56	Change HDD1 CONN to 62.10065.H71	ME
			61	DY TC6101, Stuff TC6103	EE
		12/23	20	Change to 10u 0805 size	EE
		12/23_1		Implement OPI Solution	EE
		12/27		Crooeet VGA setting, PR9210:150K, PR9211:75K	EE
X02		03/03	41	Change PR4104 to 0 ohm,PR4106 to 200K	EE
			83	DY R8309,R8310 to solve device error	EE
			31	Move C3125 to Q3101.S ,R3134 to 100k to solve unnecessary pulse	EE
				Change C3102,C3103 to 18P from vendor recommend	EE
			17	Change RN1701 to 22 ohm for solve SIV solution	EE
			50	Change RN5001 to 150 ohm for solve SIV solution	EE
				Stuff C5002,C5003,C5004	EE
			97	Add SPR3,SPR4	ME
			59	Add RN5901 for nonuse Giga lan	EE
			50,59,97	Change CRT ,TPAD1,RJ45 CONN, H10 Hole and add SPR3,SPR4	ME
		03/07	83~87	Change VGA P/N to 71.ROBSO.M01	EE
			85	DY R8525,R8526 and Q8501 for nonuse	EE
			28	DY R2813,R2805,R2832,C2808,U2805,R2812,R2811, Stuff R2823 for P2800	EE

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

File

Change notes

Size
A3Document Number
Enrico 14 AMDRev
A00

Date: Friday, April 22, 2011

Sheet 107 of 109


	VERSION	DATE	Page	Modify List	OWNER
			28,85	DY U2803,R2815,R2812,R2814,C2813,C2814. stuff RN8501,Q8503 for GPU temperature by SMBus	EE
		03/09	27	DY D2701,D2704 and D2705, Add R2781,R2782 and R2783 for connect directly	EE
			97	Change SPR3 to 34.39S07.003	EE
			38,39	Rename AFPP3811,3812,3813,3814,3901,3902,3903,3904 to AFTP	EE
		03/10	38,60	Delete AFTP6001,AFTP6002,AFTP3811	EE
			17	Change C1719,C1720 to 18p for vendor recommend	EE
			40	Delete PR4063 and PC4025 for EMI Solution	EE
		03/10_1	71	Add R7102 to reserved	EE
			27	Change R2724 to 33k for SC PCB version	EE
			31	Add RN3101,Q3104 and R3108 to solve Lan leakage issue	EE
		03/11	41,42,47	Change power gap P/N	EE
				Change 0 ohm to short pad	EE
			61,65,82	Delete TR6101,TR6501,TR8202,TR8201 CMC	EE
		03/16	41	Change PR4103 from 150Kohm to 143Kohm for 5V OCP setting	Power
			44	Change PR4408 from 75Kohm to 66.5Kohm for 1.5V OCP setting	Power
			92	Change PR9205 from 13Kohm to 11 Kohm for VGA OCP setting	Power
			47	Change PC4709 from 1.5KpF to 100pF for comp	Power
			46	Dummy PC4602 and POP PC4604.	Power
		03/17	28	DY C2818,D2802,C2816 and Stuff C2815	EE
		03/22	40	DY PQ4007,PR4037,PR4012 for new version IC	EE
	A00	04/07	49	Add 0 ohm at Q4901.4 for reserved to avoid module leakage	EE
			71	Change DB1 foorprint to PAD-10P-177042 for factory request	EE
			18	Change R1818 to 0 ohm for reserved non-zero power ODD	EE
		04/11	18	Change R2724 to 47K for X-build version	EE

<Core Design>



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title			Change notes
Size	Document Number	Rev	
A3	Enrico 14 AMD	A00	
Date:	Friday, April 22, 2011	Sheet	108 of 109

Core Design>			
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title			
Change notes			
Size	Document Number	Rev	
A3	Enrico 14 AMD	A00	
Date:	Friday, April 22, 2011	Sheet	109 of 109